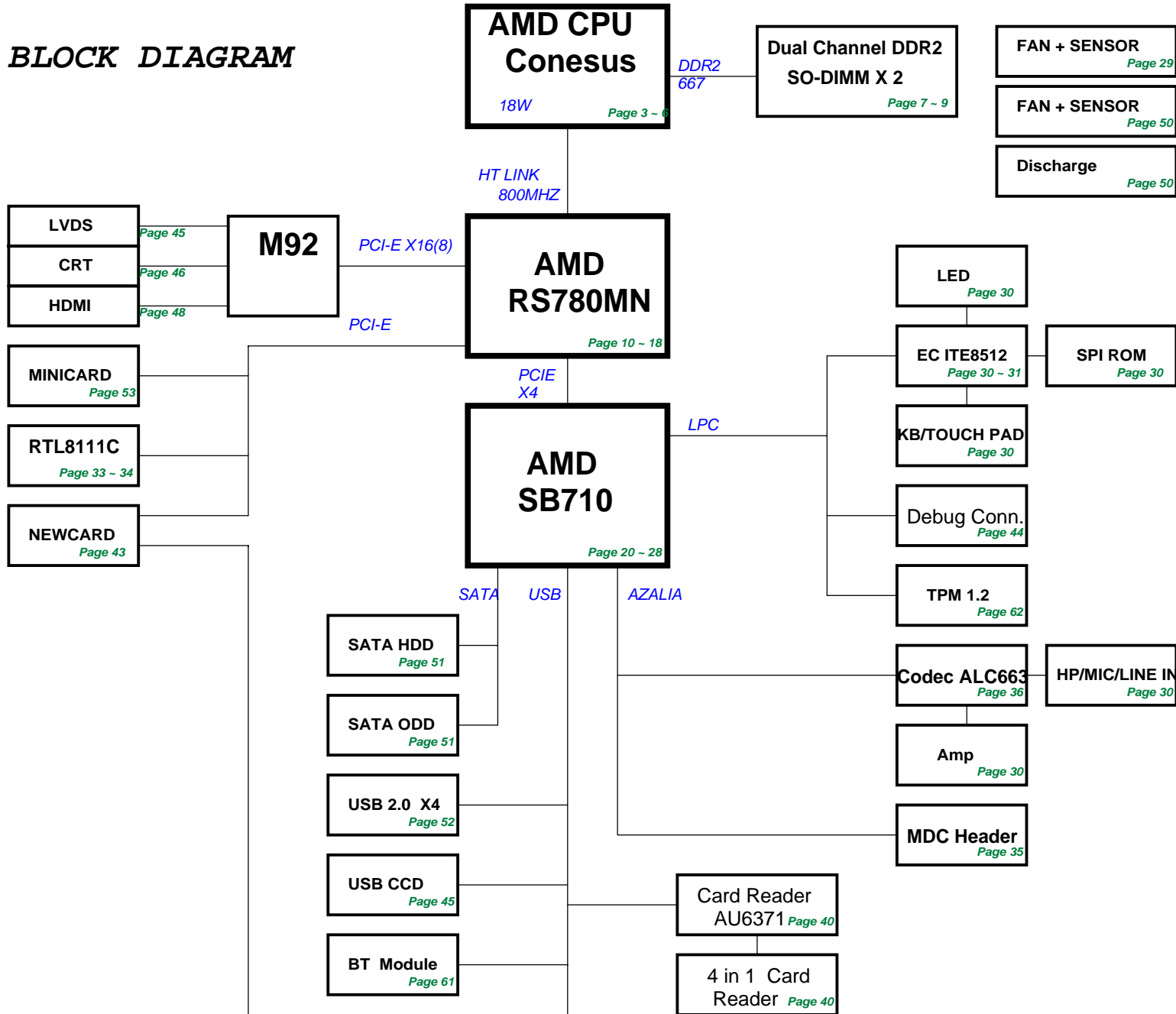
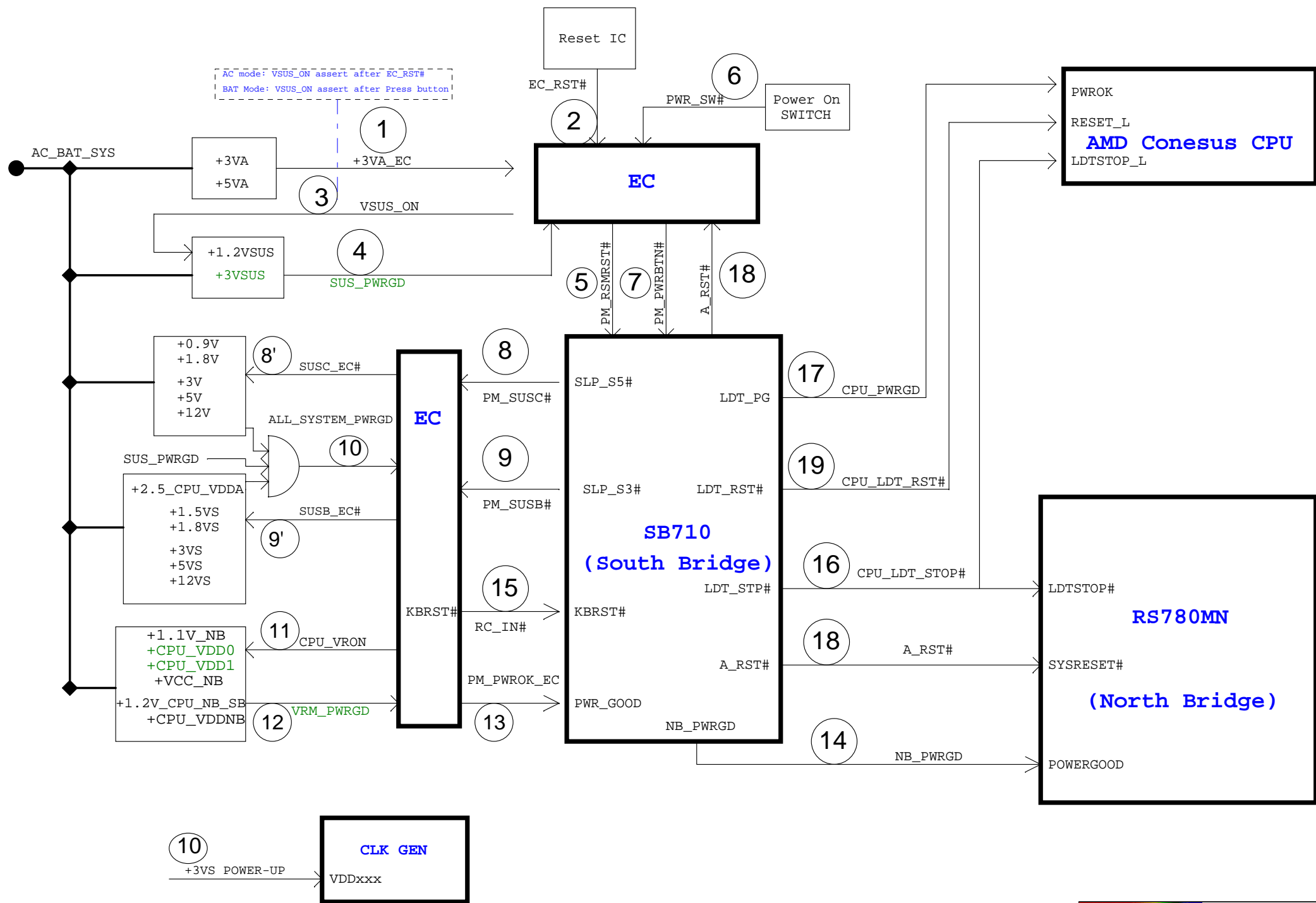
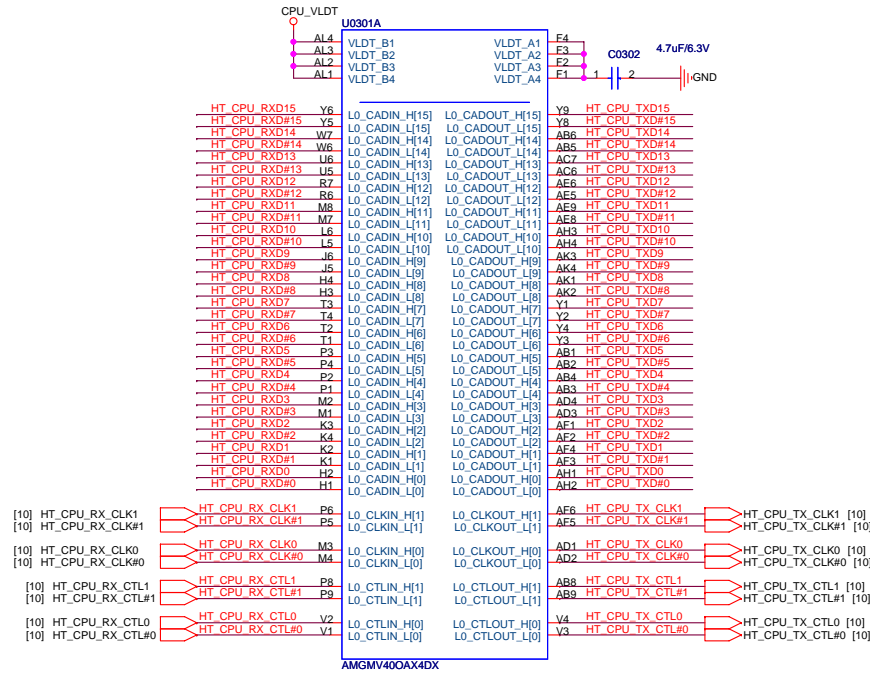


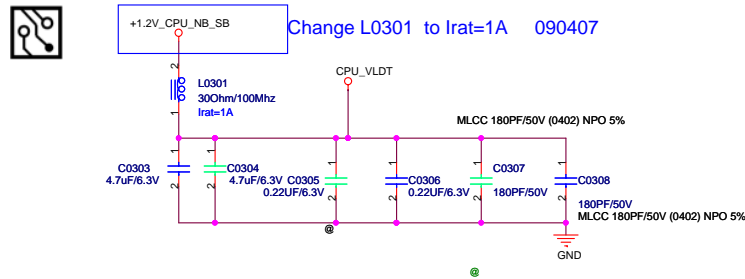
# BLOCK DIAGRAM

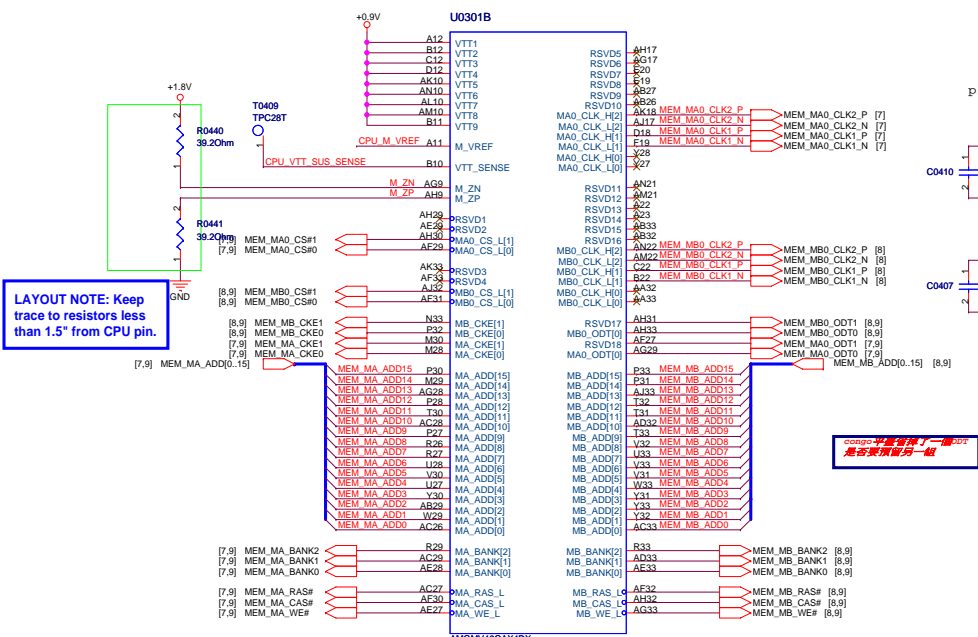






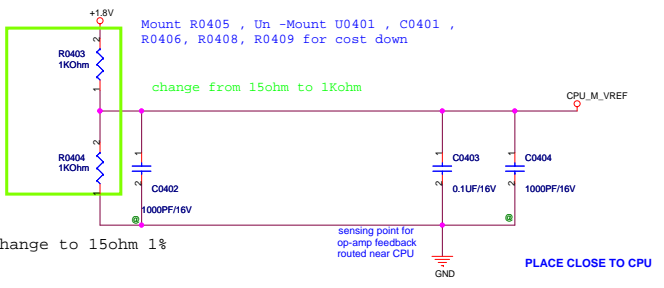
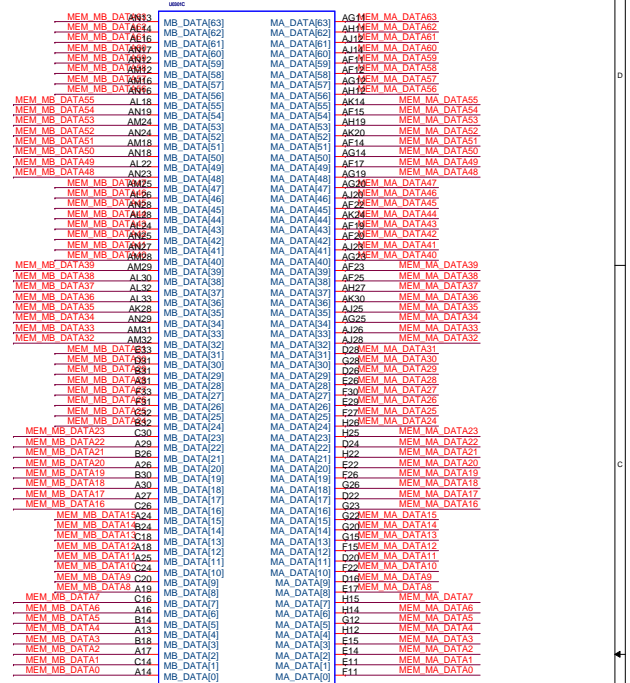
**DESIGN NOTE:**  
 VLDT must be routed as a pour or a trace at least 200 mils wide.  
 VLDT may be routed from the source to either ALx balls or Fx balls.  
 Choose whichever makes routing simpler.  
 These six capacitors must be placed very near the selected balls.  
 The "other" set of balls must be decoupled with a 4.7uF cap.





LAYOUT NOTE: Keep trace to resistors less than 1.5" from CPU pin.

change 150ohm to 1kohm  
请改电阻值为1k



R0403 & R0404 change to 150hm 1%

sensing point for op-amp feedback routed near CPU



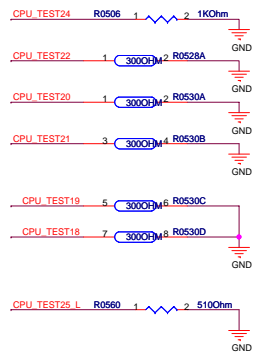
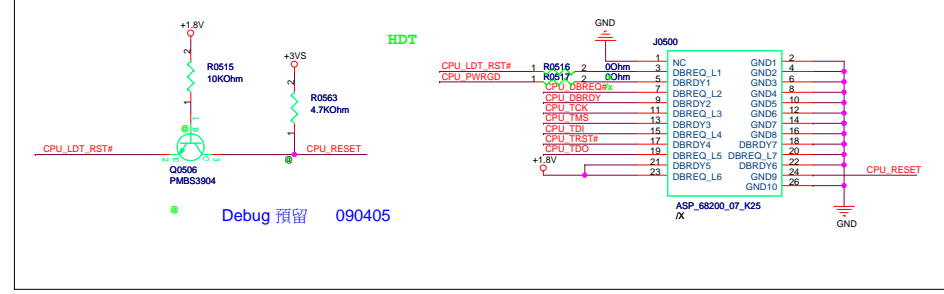
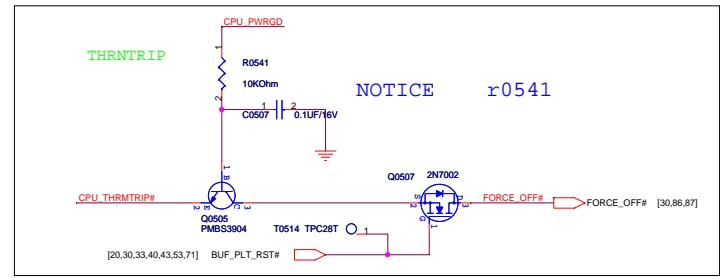
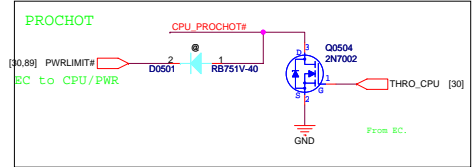
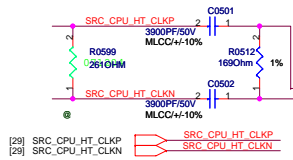
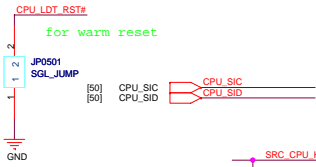
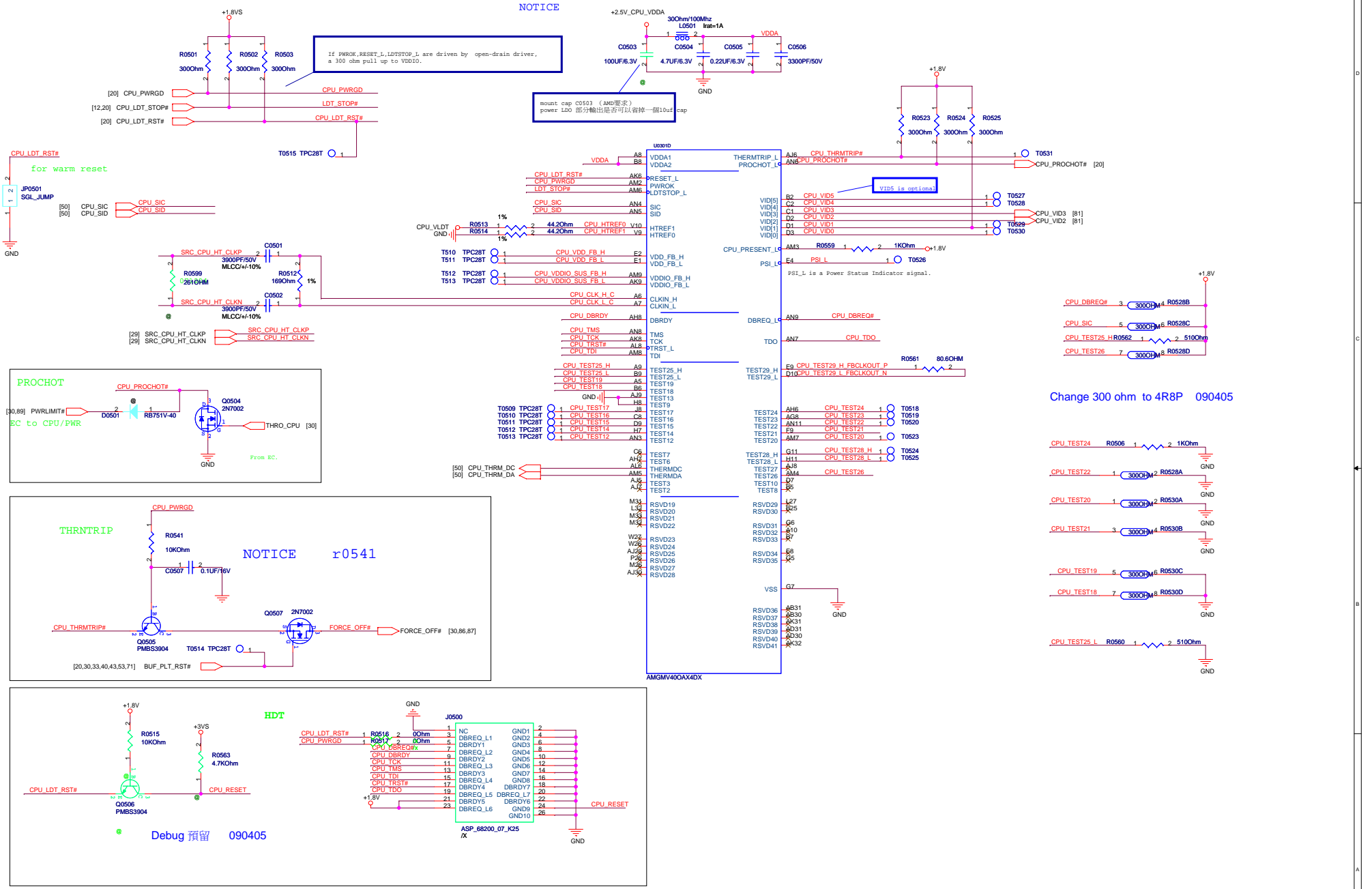
**NOTICE**

If PWROK, RESET\_L, LDTSTOP\_L are driven by open-drain driver, a 300 ohm pull up to VDDIO.

mount cap C0503 (AMD要求) power LDO 部分輸出是否可以省略一個10uF cap

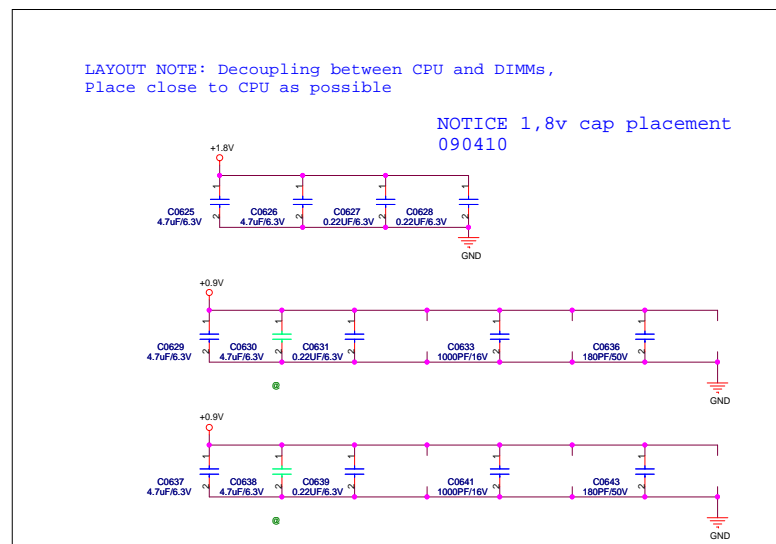
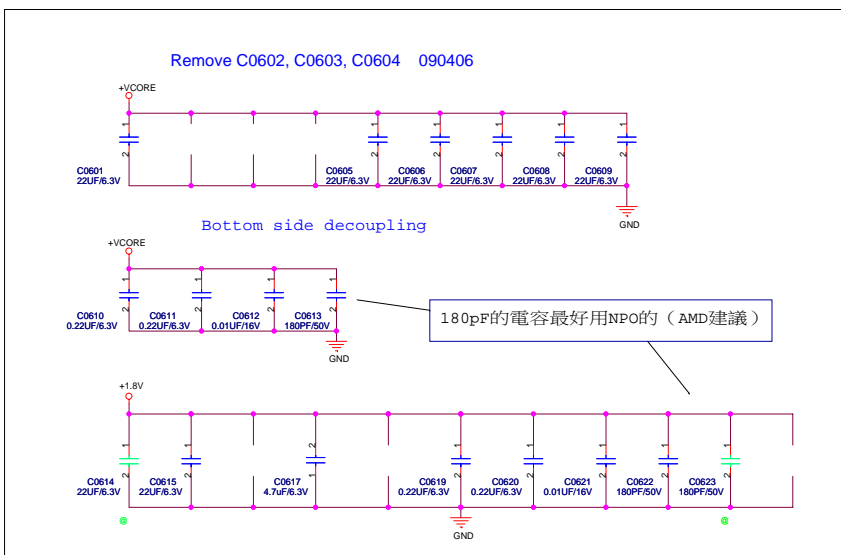
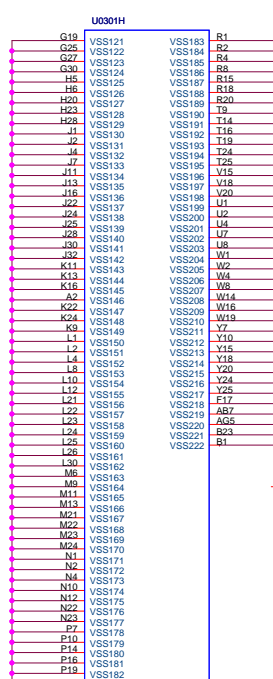
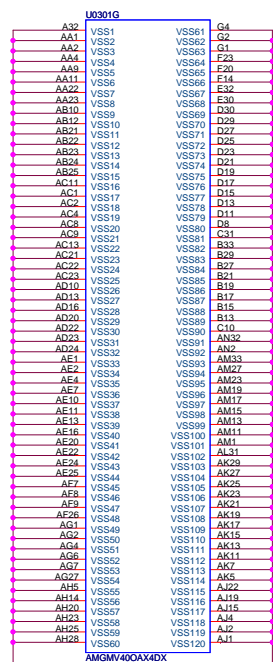
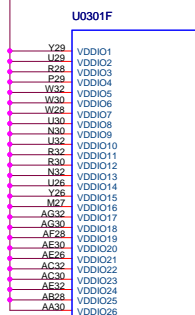
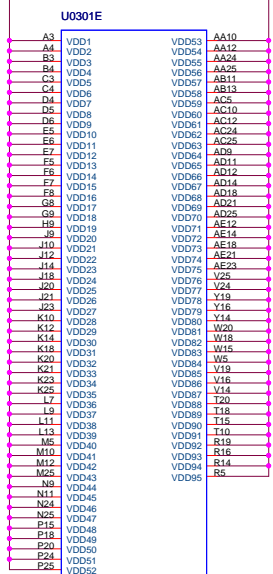
VID5 is optional

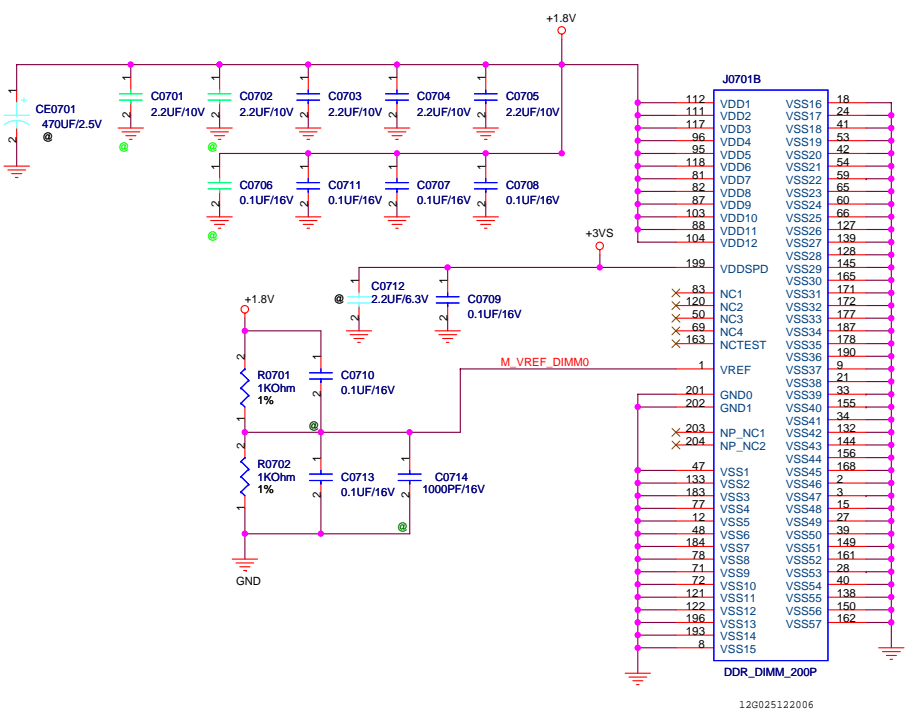
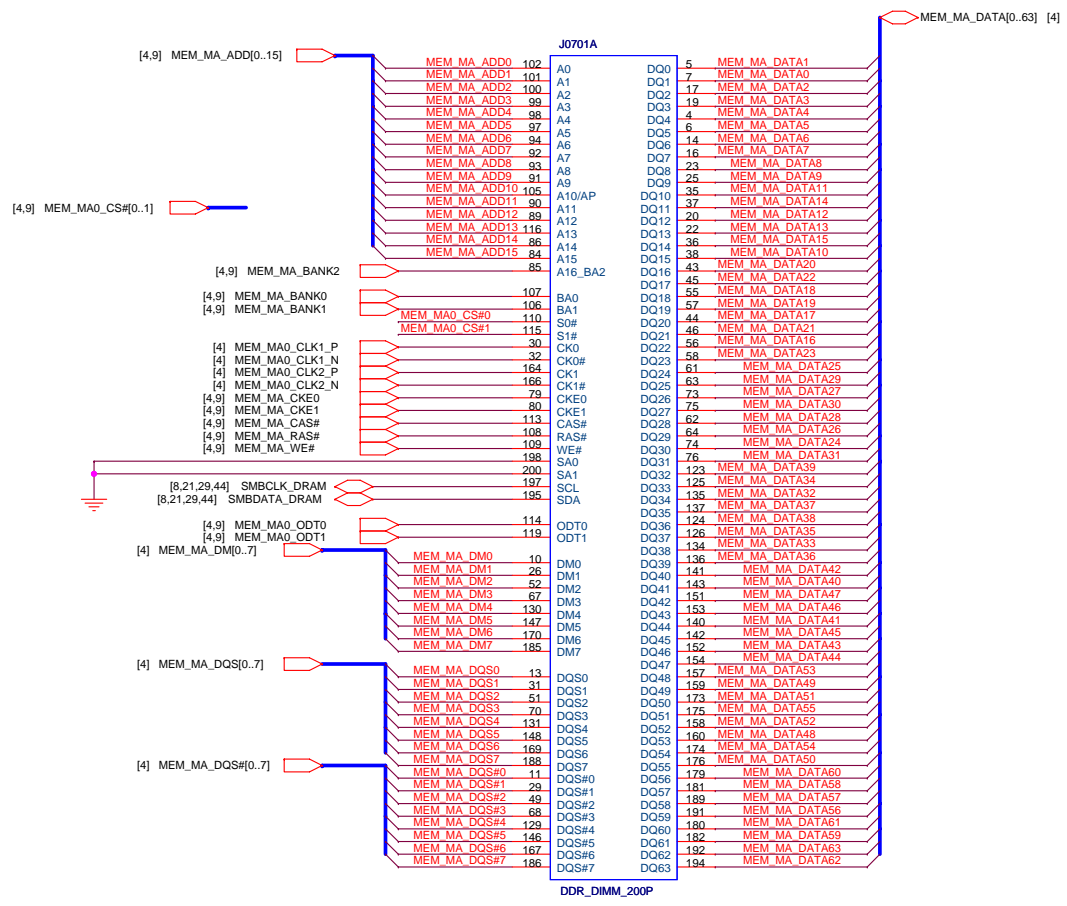
Change 300 ohm to 4R8P 090405



+V CORE +V CORE

+1.8V





P/N:12G025122006

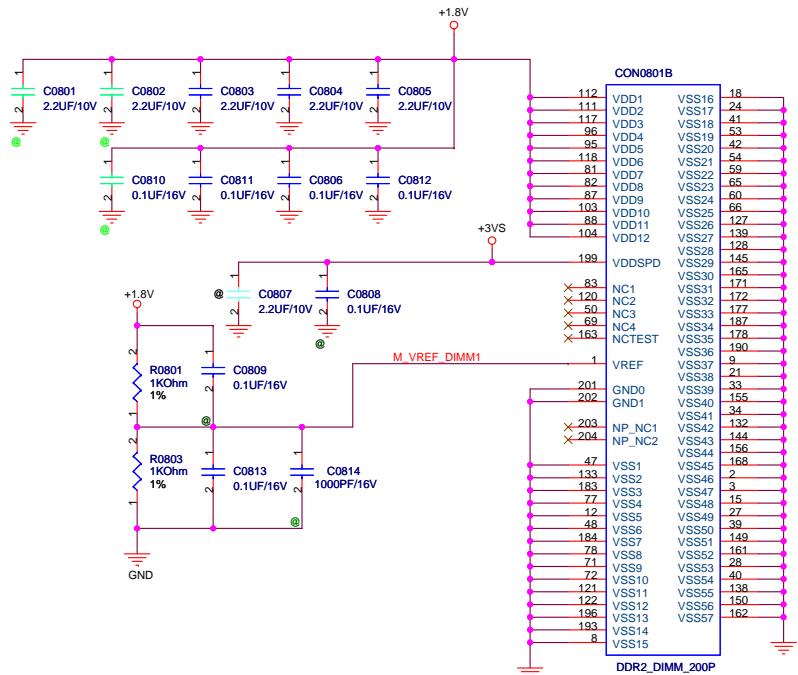
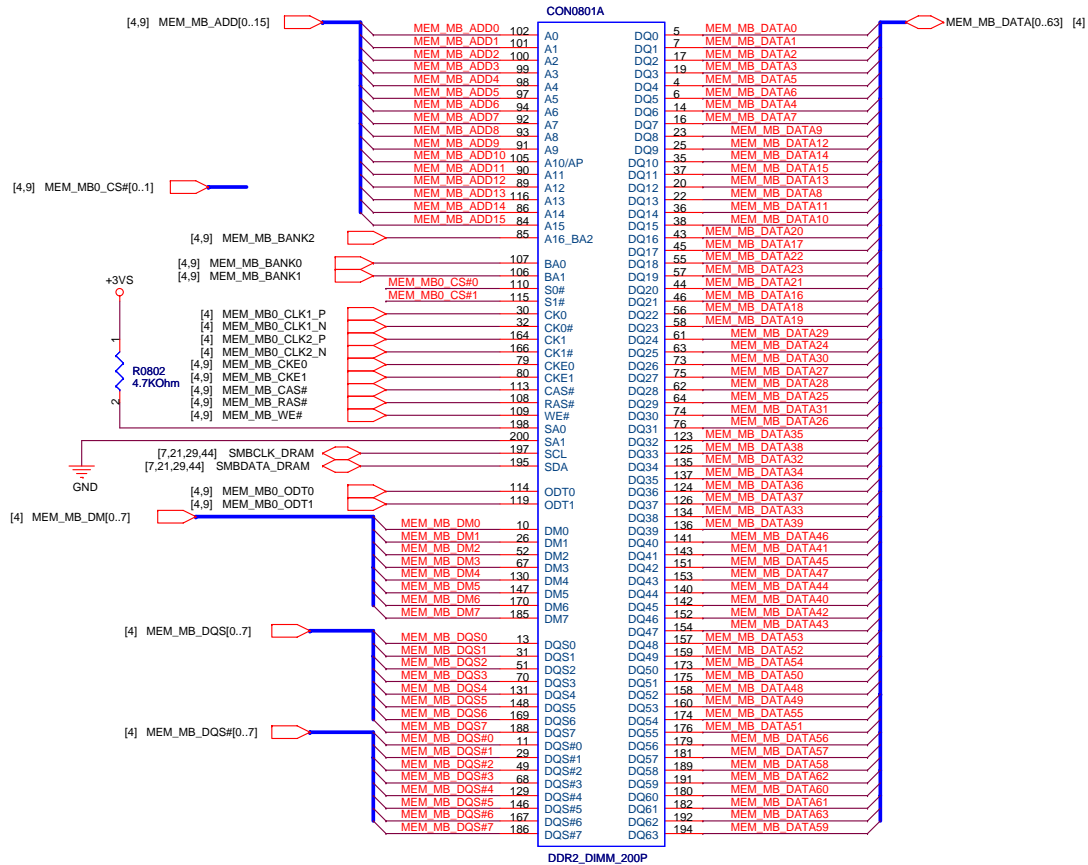
<Variant Name>

**ASUS** Title : **DDR2 SO-DIMM**

ASUSTeK COMPUTER INC Engineer:

Size	Project Name	Rev
Custom	<b>F5Z</b>	2.05

Date: Tuesday, May 26, 2009 Sheet 7 of 91



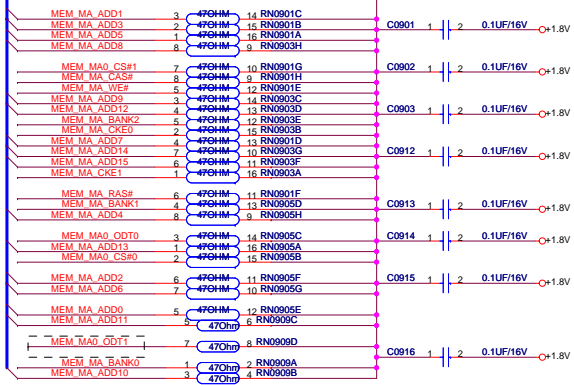
PN:12G025C22003  
REV.



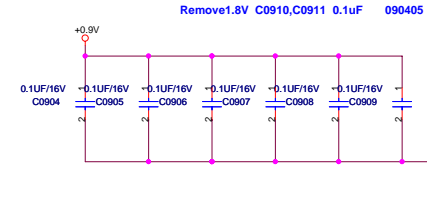
change to 8R16P 090405

[4.7] MEM\_MA\_ADD[0..15]

071219  
Del Bank2 to Bus

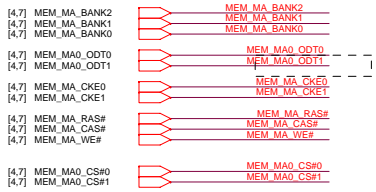


是否用排容?  
090330



Remove1.8V C0910,C0911 0.1uF 090405

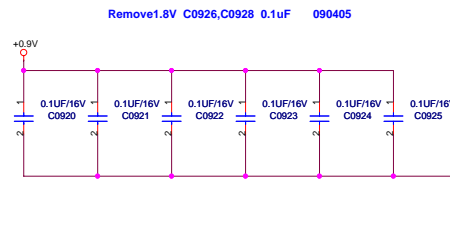
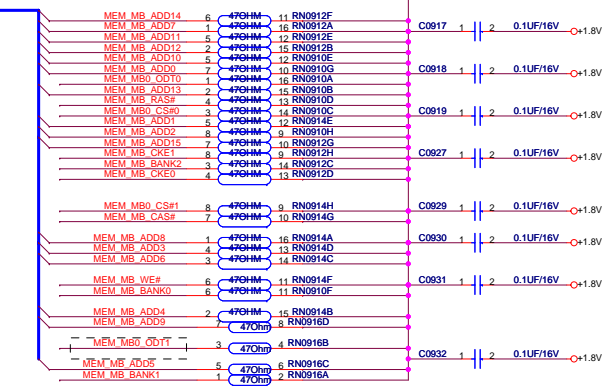
071207



add MA0\_ODT1@MB0\_ODT1 090417

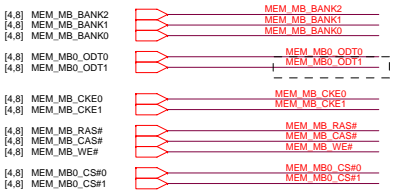
change to 8R16P 090405

[4.8] MEM\_MB\_ADD[0..15]

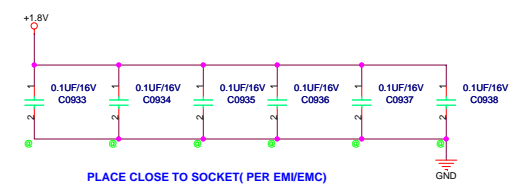


Remove1.8V C0926,C0928 0.1uF 090405

071211



add MA0\_ODT1@MB0\_ODT1 090417



PLACE CLOSE TO SOCKET (PER EM/EMC)

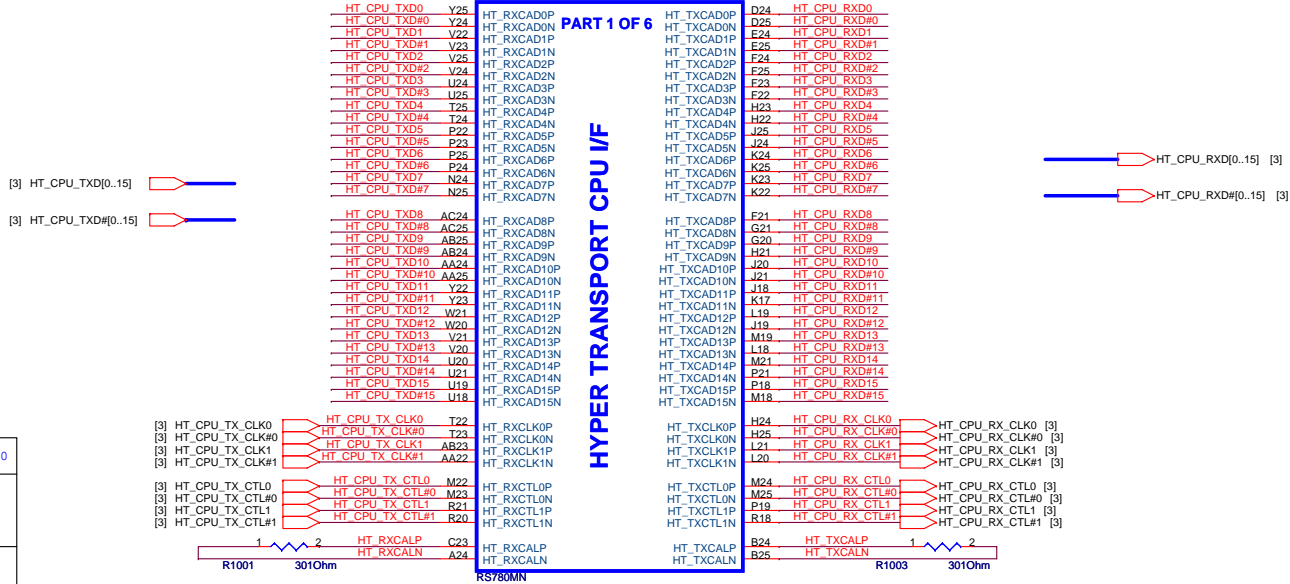
R1.11 080319

Change the NB Part number to RS780 (A13)

U1001A

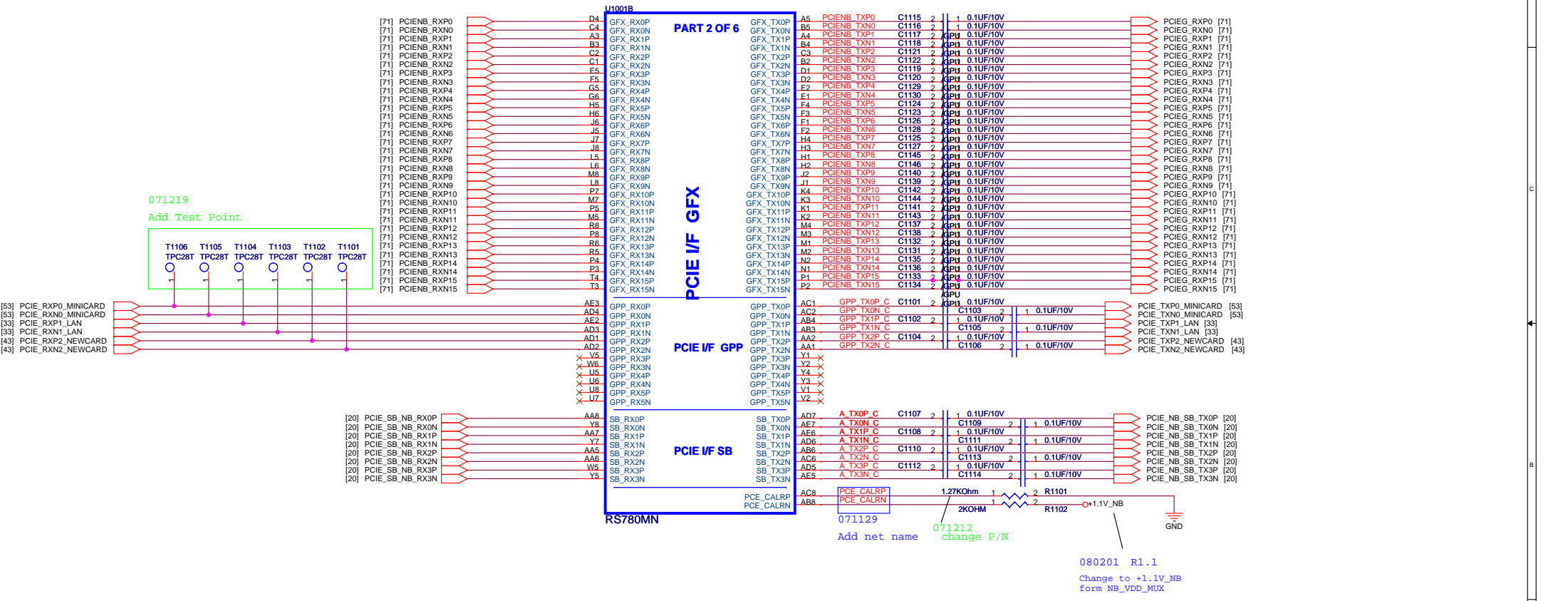
PART 1 OF 6

HYPER TRANSPORT CPU I/F

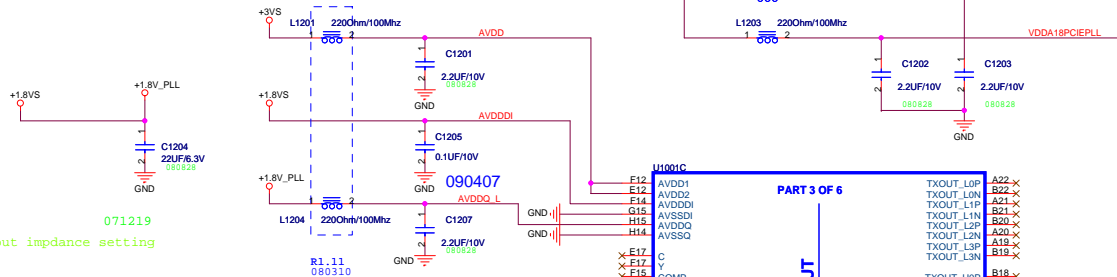


Signal	RS740	RX780	RS780
HT_RXCALP	49.9R (GND)	1.21K	301R
HT_RXCALN	49.9R (VDDHT)		
HT_TXCALP	100R	1.21K	301R
HT_TXCALN			

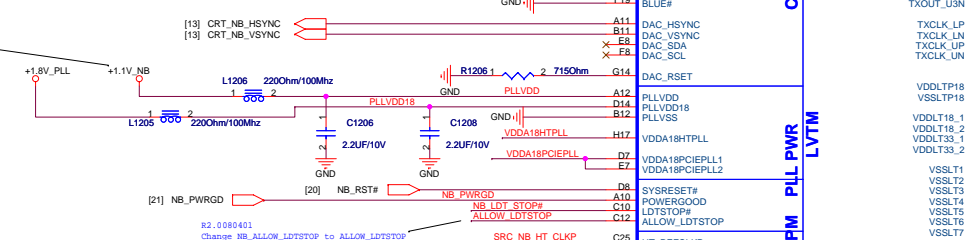
R1.11 080319  
 Change the NB Part number to RS780 (A13)



notice L1201 L1204 change SL?  
090411

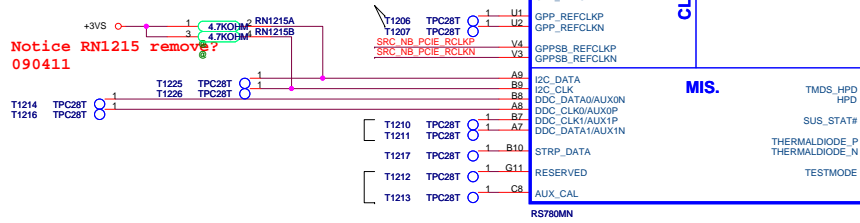


080201 R1.1  
Change to +1.1V\_NB  
form NB\_VDD\_MUX

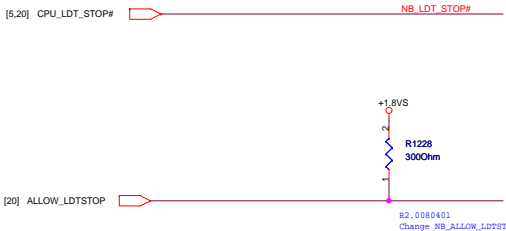


STRP_DATA	0	1
VCC_NB	1.0V	1.1V

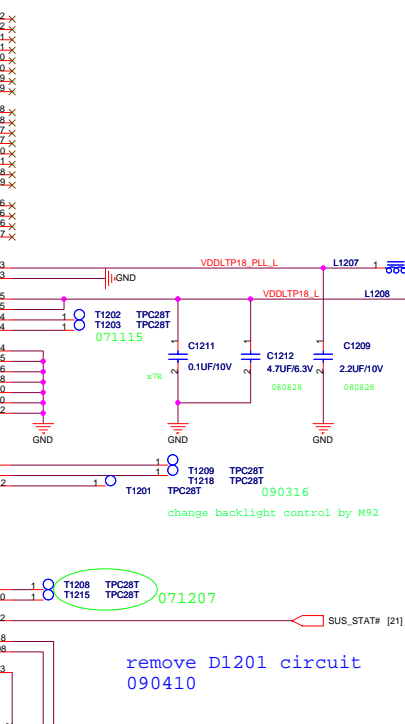
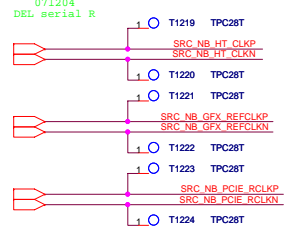
Notice RN1215 remove?  
090411



080325  
R2.0 Remove Q1201A and R1219



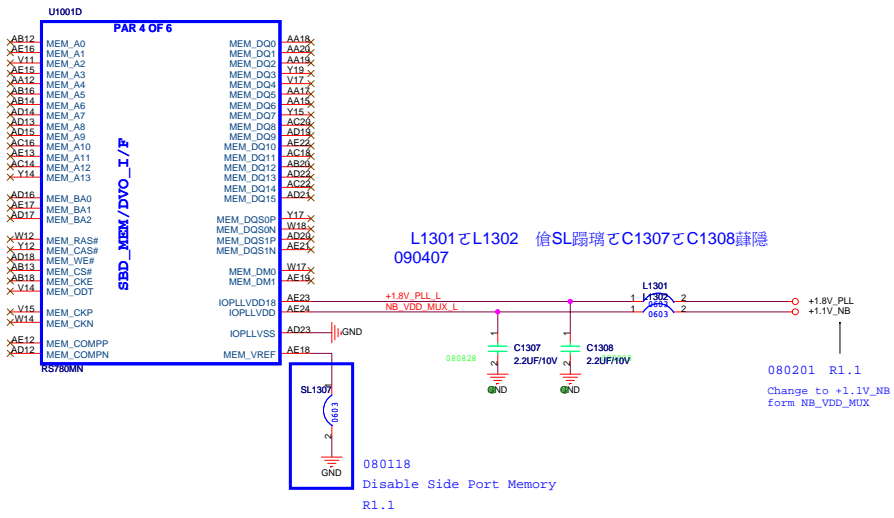
071218  
for measurement near U1001



remove D1201 circuit  
090410

071116

R1.11 080319  
 Change the NB Part number to RS780 (A13)



**DFT\_GPIO1: LOAD\_EEPROM\_STRAPS**

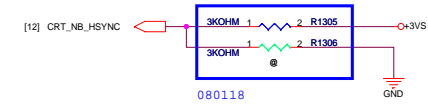
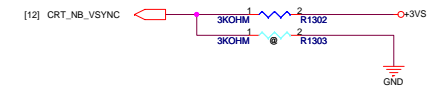
Selects Loading of STRAPS from EPROM  
 1 : Bypass the loading of EEPROM straps and use Hardware Default Values  
 0 : I2C Master can load strap values from EEPROM if connected, or use default values if not connected  
 RS780:SUS\_STAT

**STRAP\_DEBUG\_BUS\_PCIE\_ENABLE**

Enables the Test Debug Bus using PCIE bus:  
 1 : Disable ( Can still be enabled using nbcfg register access )  
 0 : Enable  
 RS780: configurable thru register setting only

**RS740/RS780: Enables Side port memory**

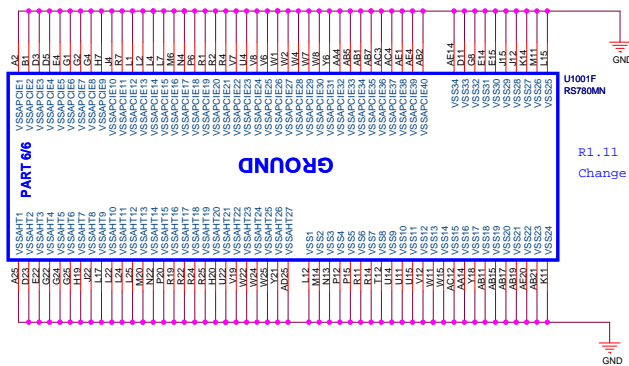
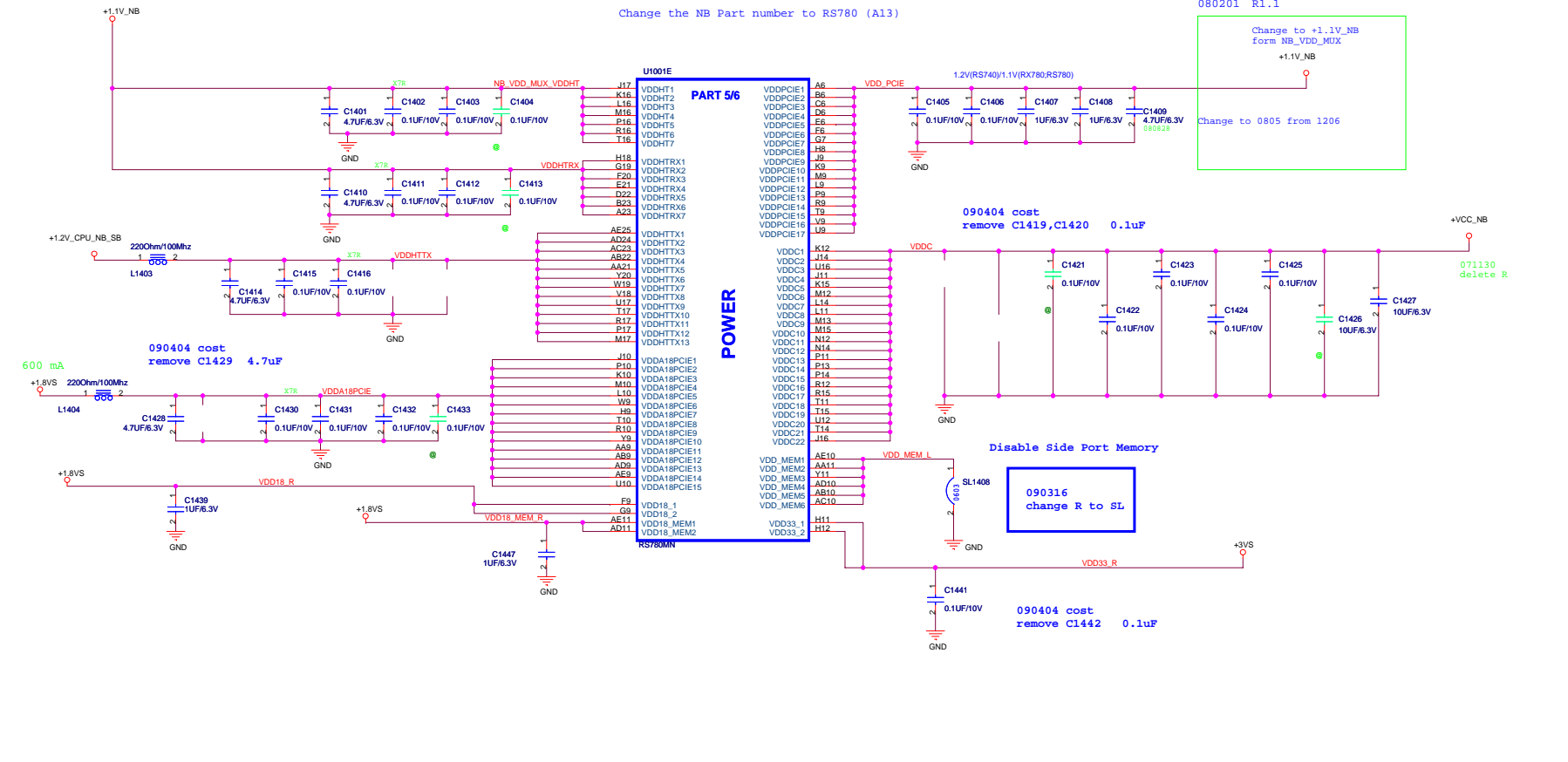
RS780:HSYNCS#  
 Selects if Memory SIDE PORT is available or not  
 1 = Memory Side port Not available  
 0 = Memory Side port available  
 Register Readback of strap: NB\_CLKCFG:CLK\_TOP\_SPARE\_D[1]



080118  
 Disable Side Port Memory  
 R1.1

R1.11 080319  
Change the NB Part number to RS780 (A13)

080201 R1.1  
Change to +1.1V\_NB  
form NB\_VDD\_MUX  
+1.1V\_NB  
Change to 0805 from 1206



R1.11 080319  
Change the NB Part number to RS780 (A13)

5

4

3

2

1

D

D

C

C

B

B

A

A



Title :

ASUSTeK COMPUTER INC. NB1

Engineer: <OrgAddr1>

Size	Project Name	Rev
A	F5Z	2.05

Date: Tuesday, May 26, 2009

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5

4

3

2

1

	5	4	3	2	1
D					
C					
B					
A					



**Title :**

ASUSTeK COMPUTER INC. NB1

**Engineer:** <OrgAddr1>

Size	Project Name	Rev
A	<b>F5Z</b>	2.05

Date: **Tuesday, May 26, 2009** Sheet **16** of **91**

	5	4	3	2	1
D					
C					
B					
A					



	5	4	3	2	1
D					
C					
B					
A					



**Title :**

ASUSTeK COMPUTER INC. NB1

**Engineer:** <OrgAddr1>

Size	Project Name	Rev
A	<b>F5Z</b>	2.05

Date: **Tuesday, May 26, 2009** Sheet **17** of **91**

	5	4	3	2	1
D					
C					
B					
A					

	5	4	3	2	1
D					
C					
B					
A					



**Title :**

ASUSTeK COMPUTER INC. NB1

**Engineer:** <OrgAddr1>

Size	Project Name	Rev
A	<b>F5Z</b>	2.05

Date: **Tuesday, May 26, 2009** Sheet **18** of **91**

	5	4	3	2	1
D					
C					
B					
A					

5

4

3

2

1

D

D

C

C

B

B

A

A



Title :

ASUSTeK COMPUTER INC. NB1

Engineer: <OrgAddr1>

Size  
A

Project Name  
F5Z

Rev  
2.05

Date: Tuesday, May 26, 2009

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5

4

3

2

1





R2.0 080331  
Change the R2208, R2209 to C2218 and C2219.

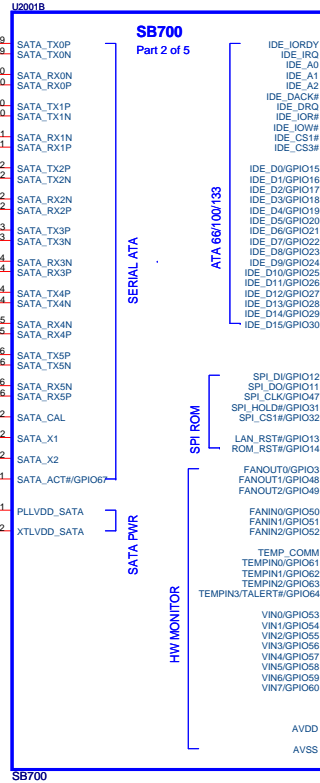
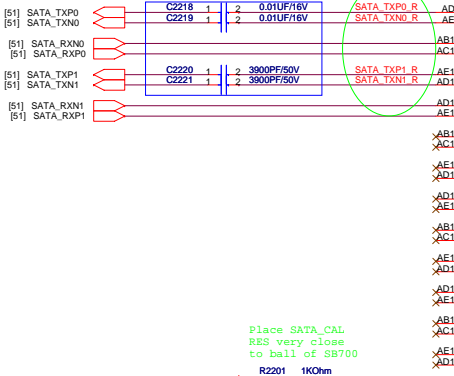
R1.11 080319  
Change the SB Part number to SB700 (A12)

Change the R2210, R2211 to C2220 and C2221.

071121 change  
add net name

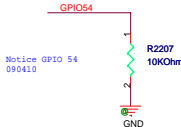
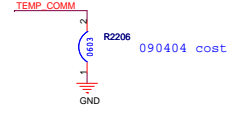
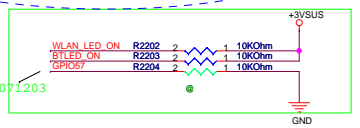
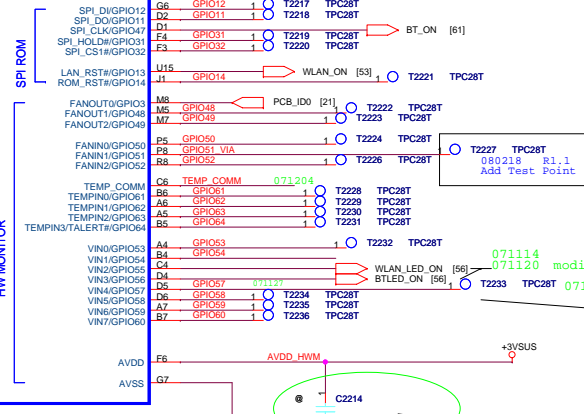
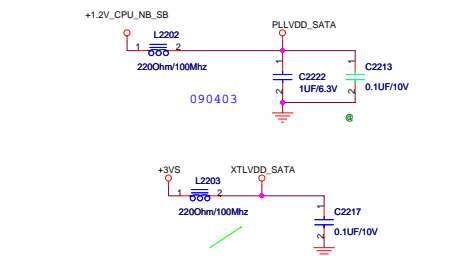
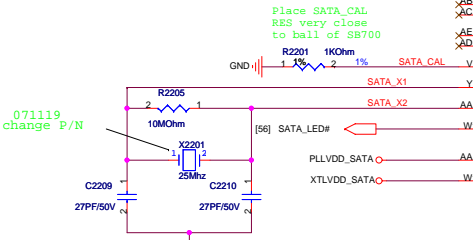
for SATA HDD

for SATA ODD

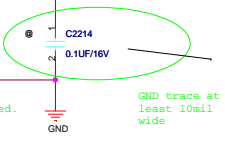


071119  
add TP

GPIO54, GPIO57 可設成output low  
R2204 & R2207 可以Costdown 090405



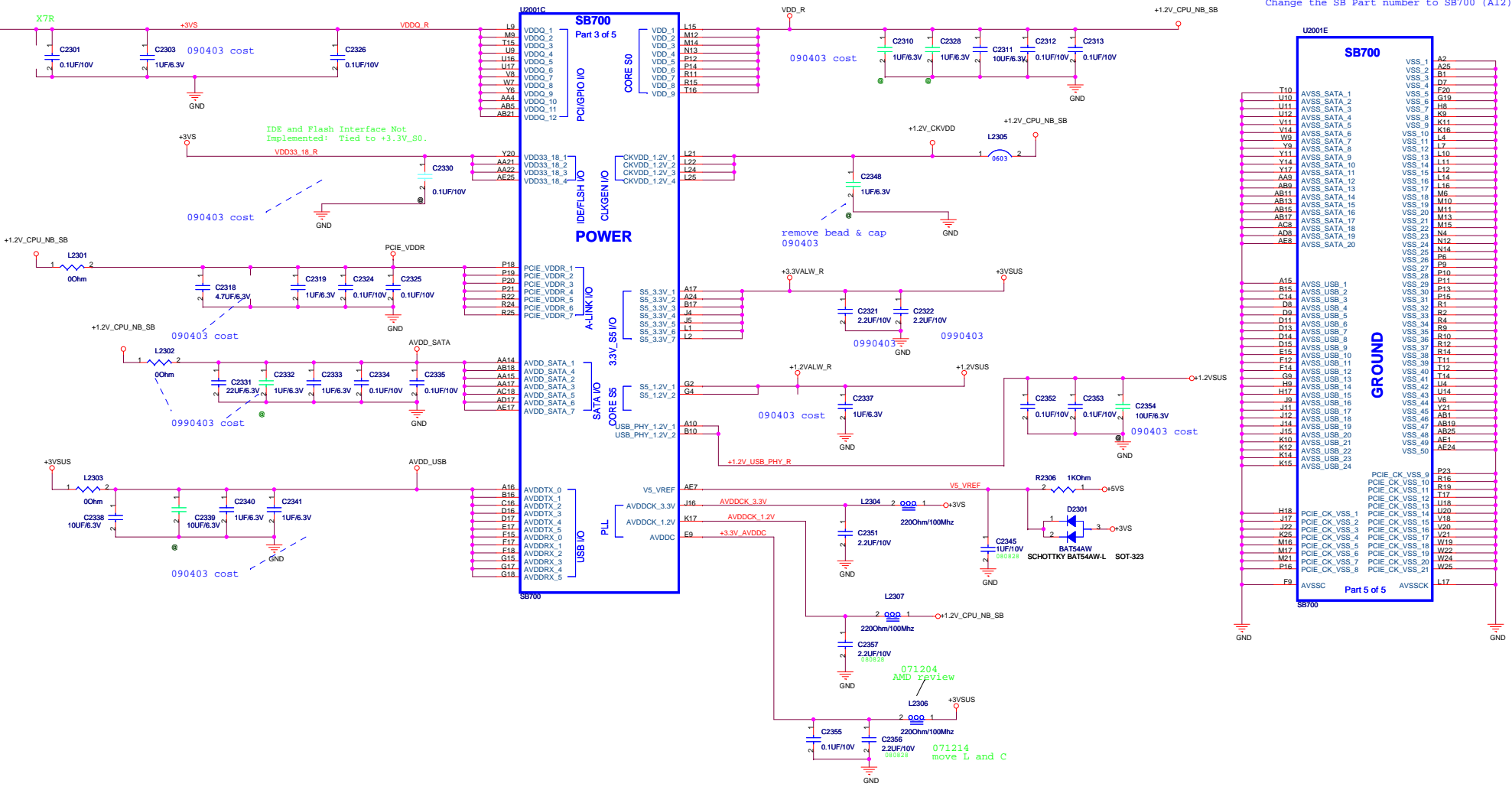
HWM not Implemented:  
Decoupling caps not used.  
071119



R1.11 080319  
Change the SB Part number to SB700 (A12)

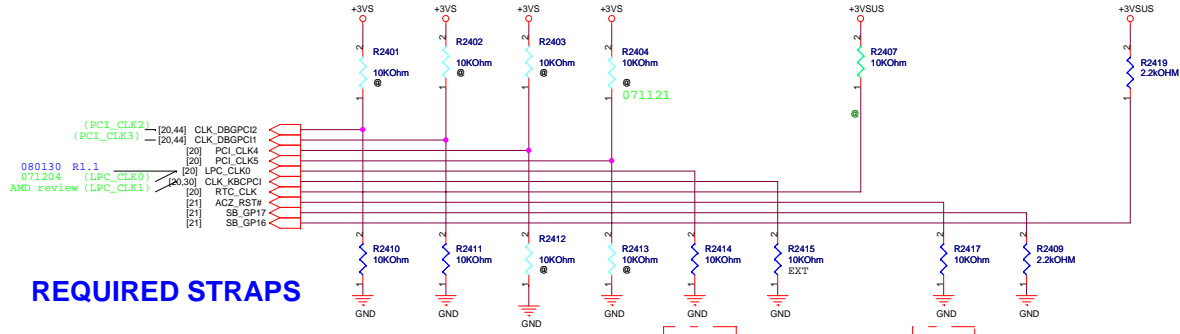
change C2311 to 10uF  
090403

R1.11 080319  
Change the SB Part number to SB700 (A12)



Remove R2405, R2406, R2416  
R2408, R2418, R2420, R2418 090405

NOTE: SB700 HAS INTERNAL 15K PULL UP RESISTOR FOR RTC\_CLK



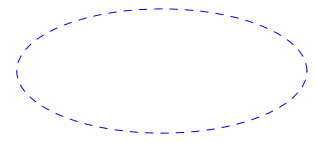
**REQUIRED STRAPS**

Remove EEPROM 090405

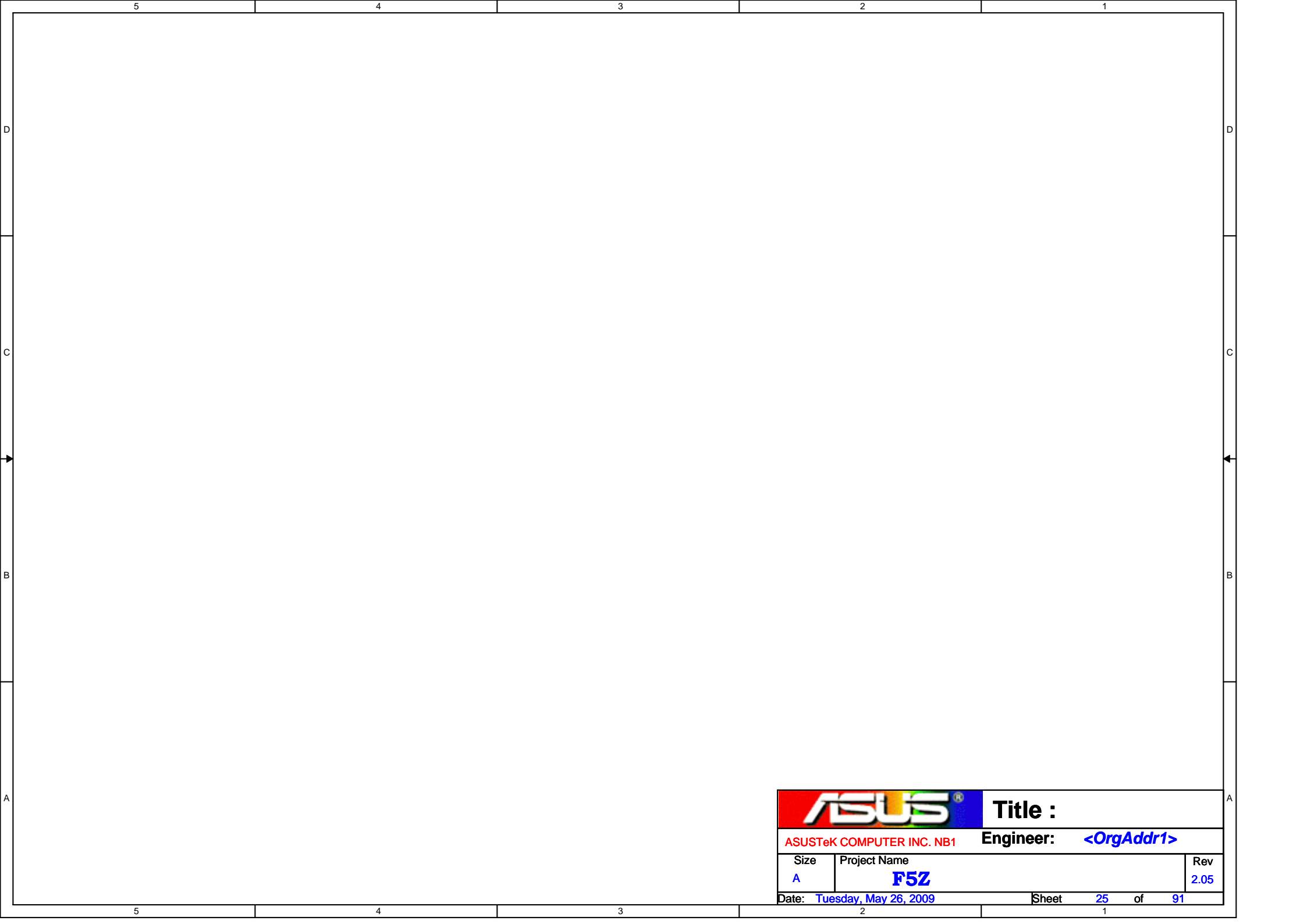
	PCI_CLK2	PCI_CLK3	PCI_CLK4	PCI_CLK5	LPC_CLK0	LPC_CLK1	RTC_CLK	ACZ_RST#	GP17	GP16
<b>PULL HIGH</b>	BOOTFAIL TIMER ENABLED	USE DEBUG STRAPS	RESERVED	RESERVED	EC ENABLED	CLKGEN ENABLED	INTERNAL RTC DEFAULT	ENABLE PCI MEM BOOT	H,H = Reserved H,L = SPI ROM	
<b>PULL LOW</b>	BOOTFAIL TIMER DISABLED DEFAULT	IGNORE DEBUG STRAPS DEFAULT			EC DISABLED DEFAULT	CLKGEN DISABLED DEFAULT	EXT. RTC [PD on X1, apply 32KHz to RTC_CLK]	DISABLE PCI MEM BOOT DEFAULT	L,H = LPC ROM (Default) L,L = FW ROM	

For SB700 A12 and later version

080204 R1.1  
Change the Text Comment







Title :

ASUSTeK COMPUTER INC. NB1

Engineer: <OrgAddr1>

Size	Project Name	Rev
A	F5Z	2.05

	5	4	3	2	1
D					
C					
B					
A					



**Title :**

ASUSTeK COMPUTER INC. NB1

**Engineer:** <OrgAddr1>

Size	Project Name	Rev
A	<b>F5Z</b>	2.05

5

4

3

2

1

D

D

C

C

B

B

A

A



Title :

ASUSTeK COMPUTER INC. NB1

Engineer: <OrgAddr1>

Size  
A

Project Name  
F5Z

Rev  
2.05

Date: Tuesday, May 26, 2009

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4

3

2

1

5

4

3

2

1

D

D

C

C

B

B

A

A



Title :

ASUSTeK COMPUTER INC. NB1

Engineer: <OrgAddr1>

Size	Project Name	Rev
A	F5Z	2.05

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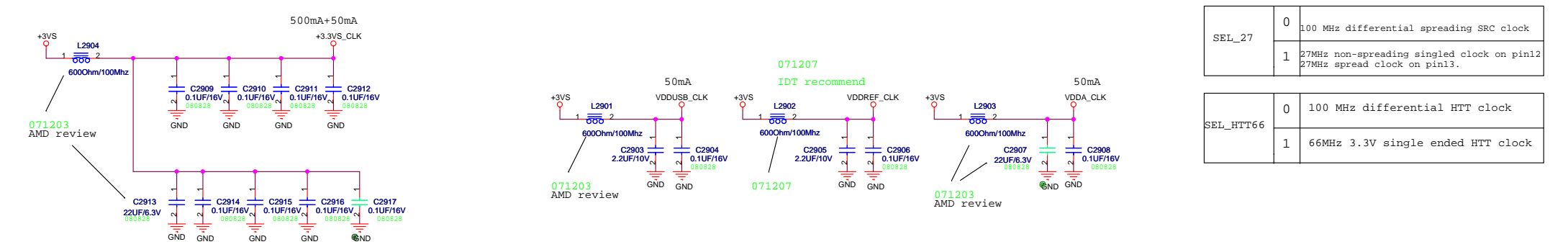
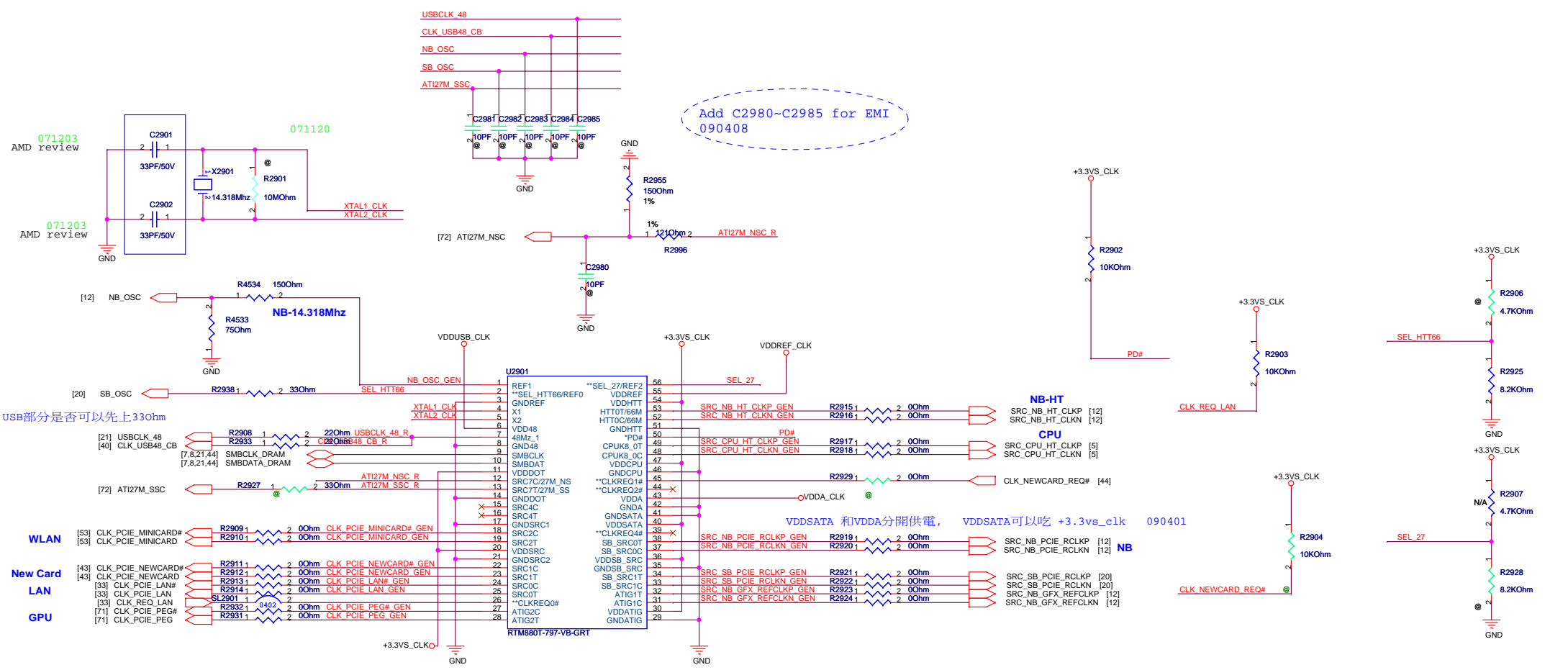
5

4

3

2

1



SEL_27	0	100 MHz differential spreading SRC clock
	1	27MHz non-spreading singled clock on pin12 27MHz spread clock on pin13.
SEL_HTT66	0	100 MHz differential HTT clock
	1	66MHz 3.3V single ended HTT clock



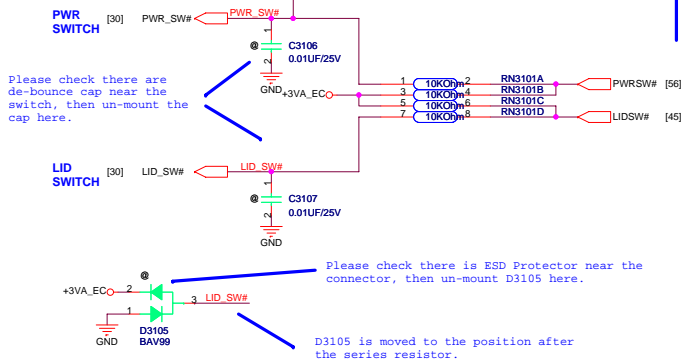
**For Battery**

Note: If there is the same circuit on pp.60 (DC & BAT IN), please delete the circuit here



Remove D3101 part circuit  
090409

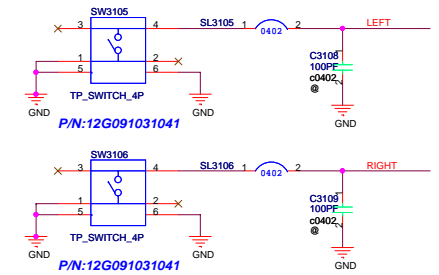
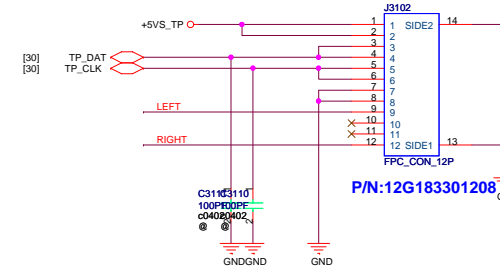
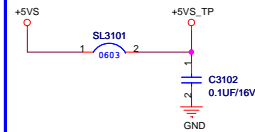
**For Switch**



**For Thermal Control Method**

Note: Please follow the Thermal-Trip circuit on pp.3-6 (CPU\_)

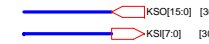
**Touchpad Connector**



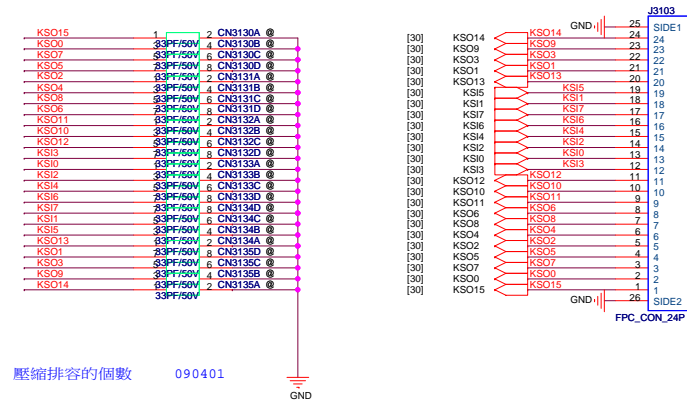
Notice switch P/N  
090410

**Keyboard Connector**

Schematic below is only the example in the previous project. It will be different between the different connector used in the Project.




Please follow the ASUS Keyboard Matrix Spec  
Please Design based on your project.

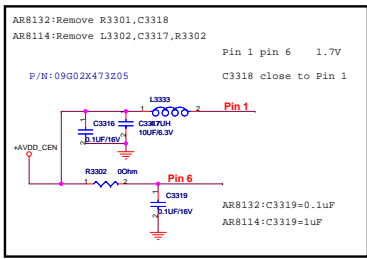


Remove all RST SCH and Change SW to other page

<Variant Name>

		Title : *	
ASUSTeK COMPUTER INC		Engineer: <i>Richard Lu</i>	
Size	Project Name	Rev	
Custom	<b>F5Z</b>	2.05	
Date: <i>Tuesday, May 26, 2009</i>		Sheet	32 of 91

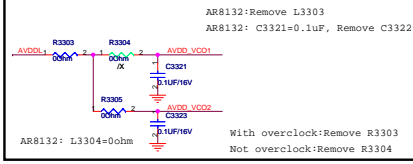




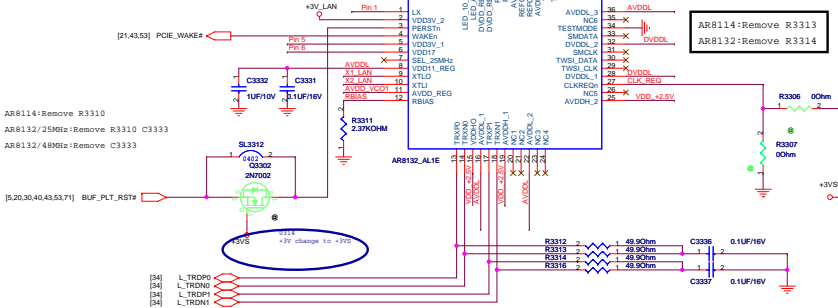
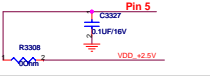
AR8132 with overclock: Remove R3315  
 AR8114: Remove R3315

Ground pad要打散熱孔

PCIE Tx, Rx方向是以兩橋為觀點  
 LAN pin Tx, Rx是以LAN為觀點



For AR8132: Remove R3305, R3306, C3324, C3325, C3326, Q3301  
 For AR8114: Remove C3327, R3308  
 Q3301 close to Pin8



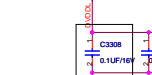
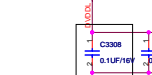
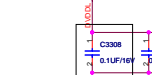
AR8114: Remove R3313  
 AR8132: Remove R3314

R3306 0ohm  
 R3307 0ohm  
 CLK\_REQ\_LAN [29]

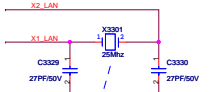


+3VSUS L3301  
 80ohm/100mhz  
 C3301 10uF/6.2V  
 C3303 1uF/10V  
 C3304 0.1uF/16V

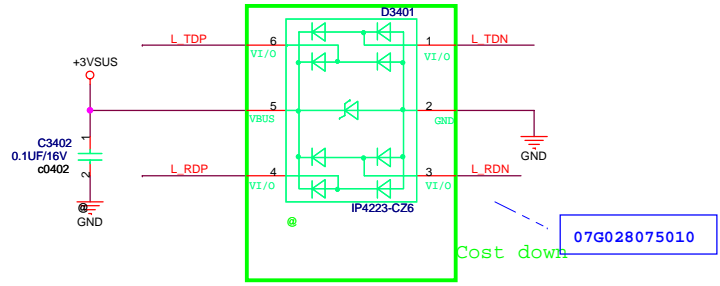
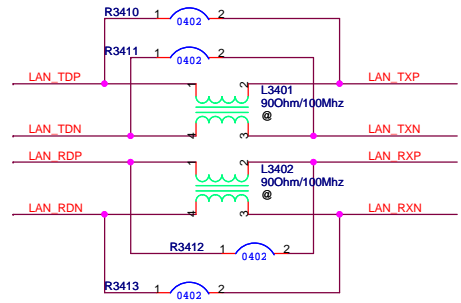
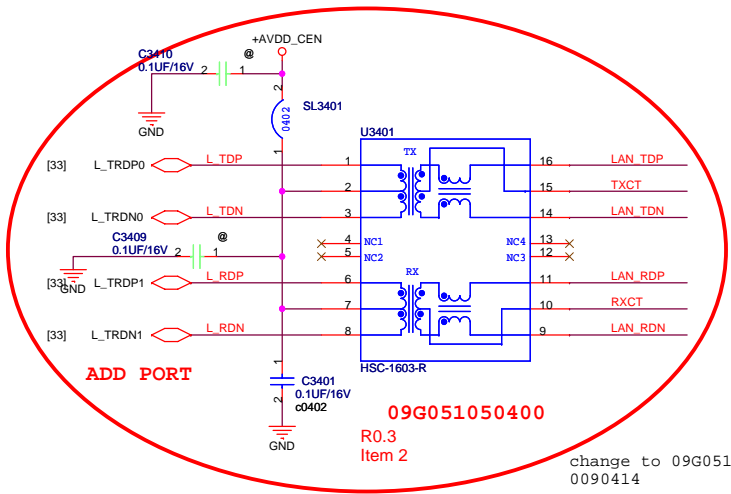
C3301 C3303 C3304 close to pin2



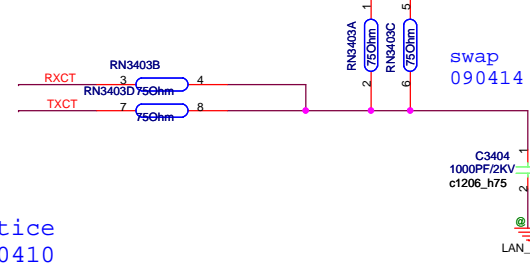
For AR8132 : Remove R3309



AR8114: Remove C3328  
 AR8132/25MHz: Remove C3328  
 AR8132/48MHz: Remove C3329 C3330 X3301

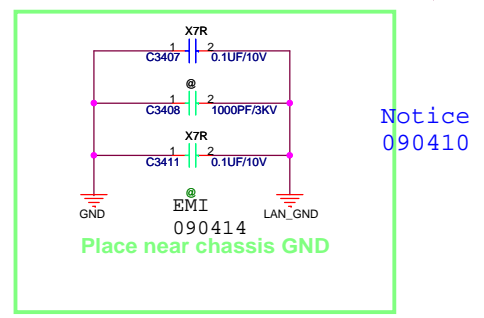
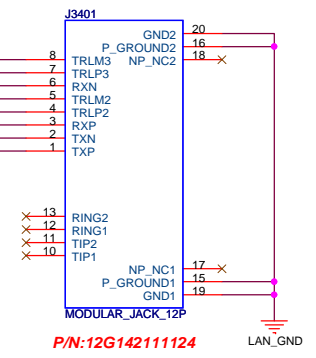


For RJ-45/RJ-11



Remove RJ11  
090331

Notice  
090410



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D

C

C


B

B

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A

<Variant Name>

		<b>Title :</b> LAN-MDC
ASUSTeK COMPUTER INC		<b>Engineer:</b> <i>Richard Lu</i>
Size Custom	Project Name <b>F5Z</b>	Rev 2.05
Date: <b>Tuesday, May 26, 2009</b>	Sheet <b>35</b> of <b>91</b>	

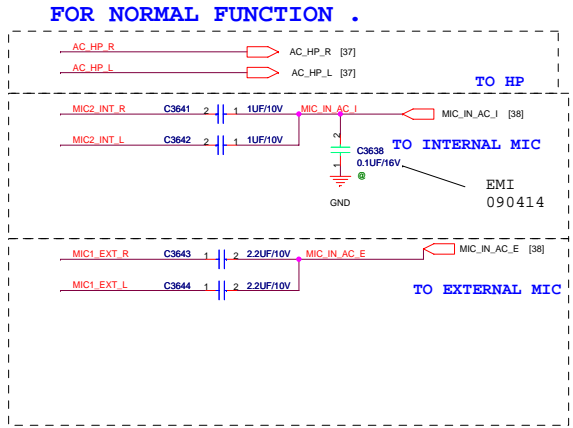
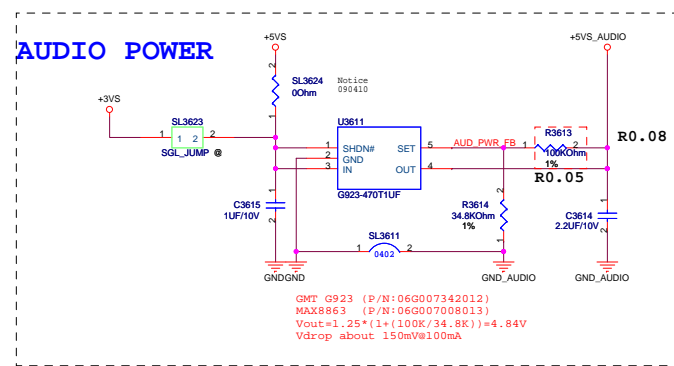
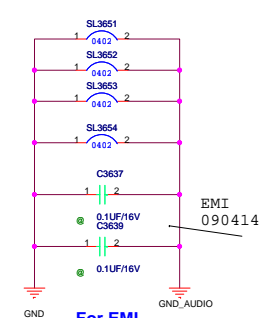
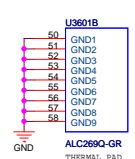
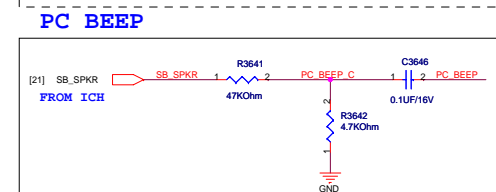
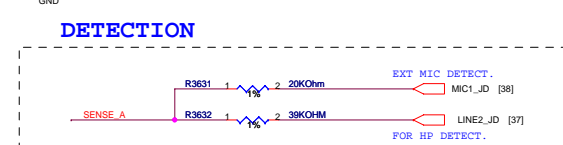
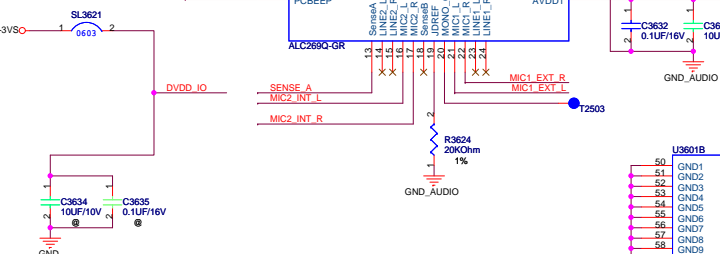
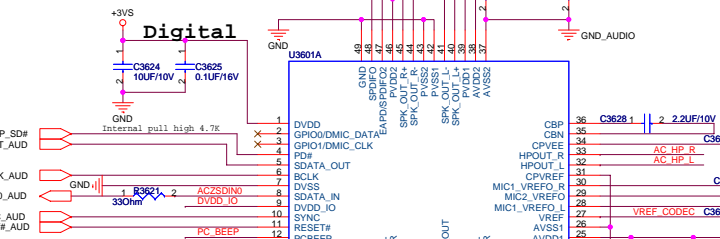
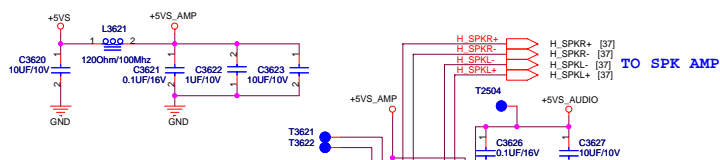
5

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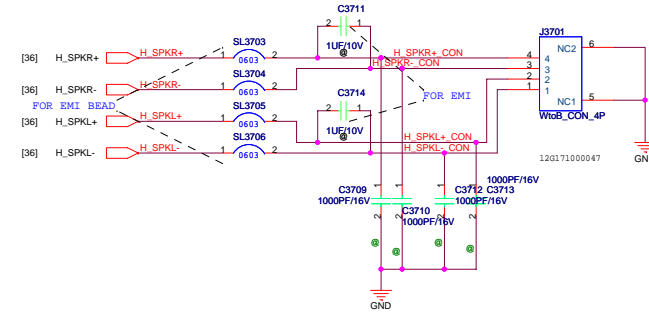
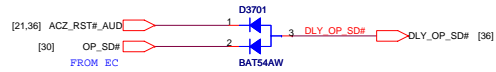
3

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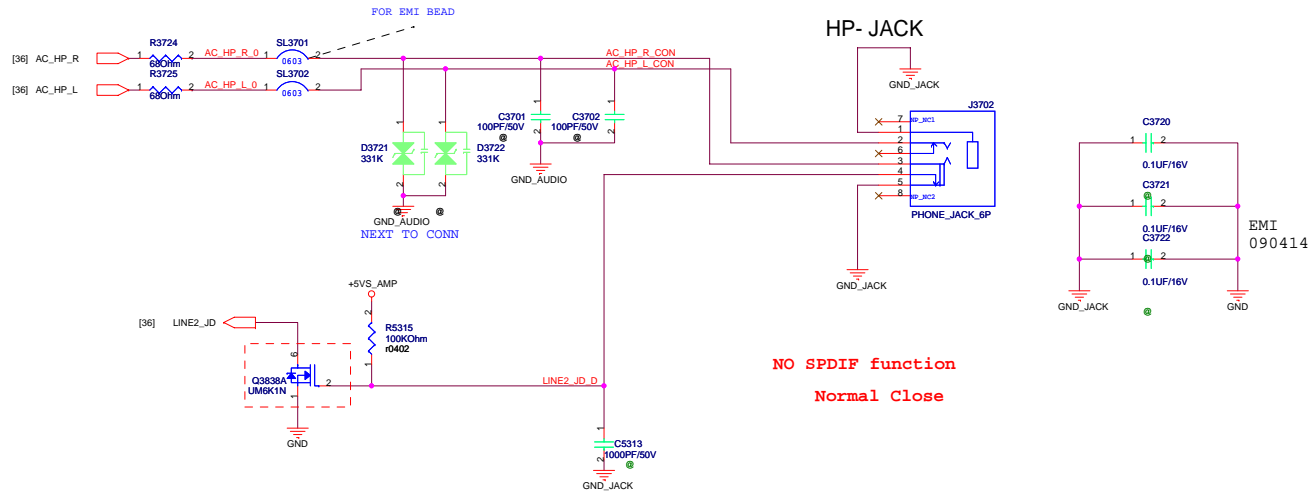
1



### MUTE CONTROL



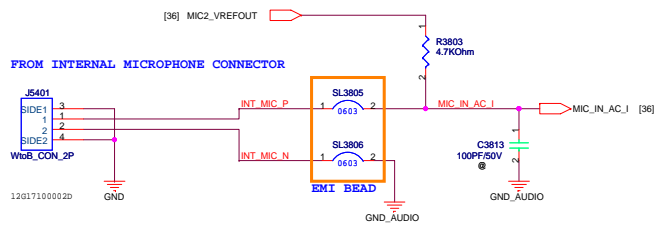
JACK\_IN# or LINE2\_JD depend on JACK's structure.  
Suppose the first pin should be contacted to GND while HP is plugged in.



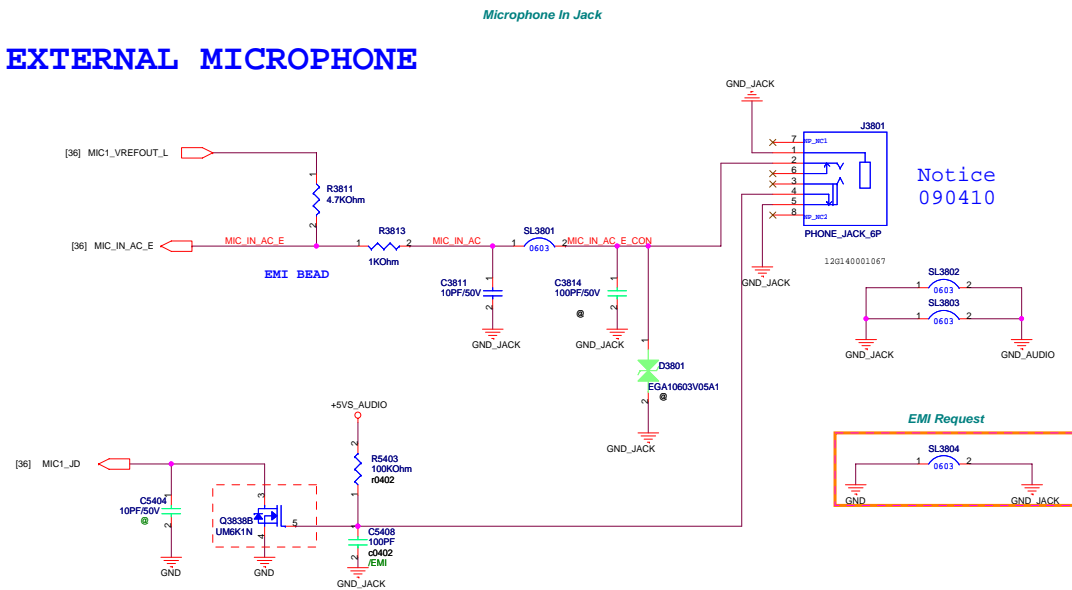
<Variant Name>

<b>ASUS</b>		<b>Title : AMP-GMT1431</b>	
ASUSTek COMPUTER INC		Engineer: <b>Richard Lu</b>	
Size	Project Name	Rev	
Custom	<b>F5Z</b>	2.05	
Date: Tuesday, May 26, 2009	Sheet	37	of 91

## INTERNAL MICROPHONE

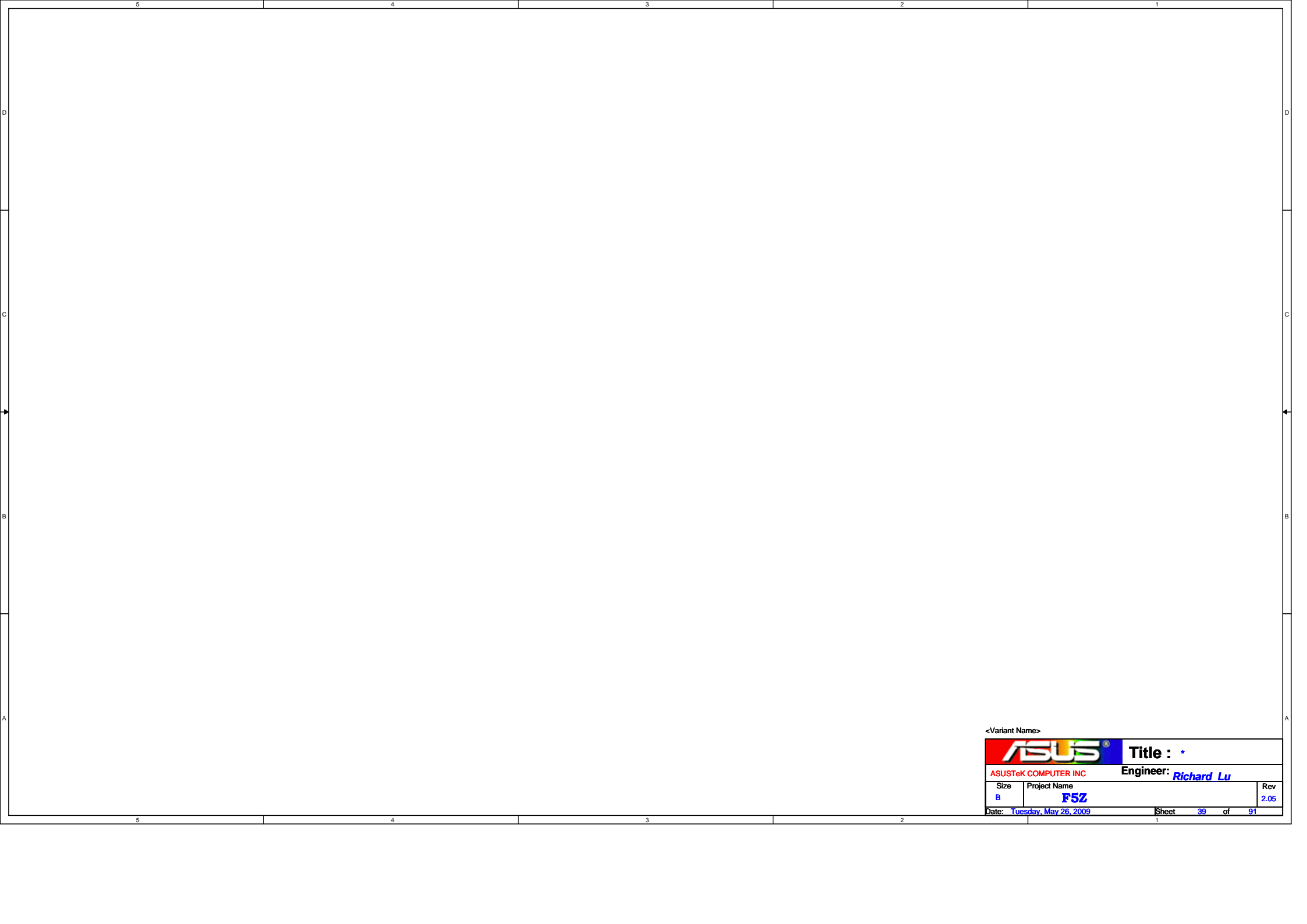



## EXTERNAL MICROPHONE

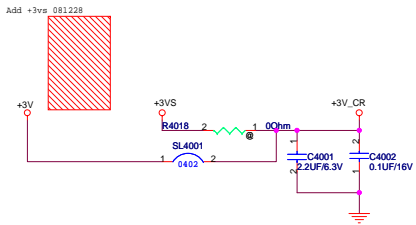


<Variant Name>

<b>ASUS</b>		<b>Title : MIC-IN Jack</b>	
ASUSTeK COMPUTER INC		Engineer: <b>Richard Lu</b>	
Size	Project Name	Rev	
C	FSZ	2.05	
Date: Tuesday, May 26, 2009	Sheet	38	of 91

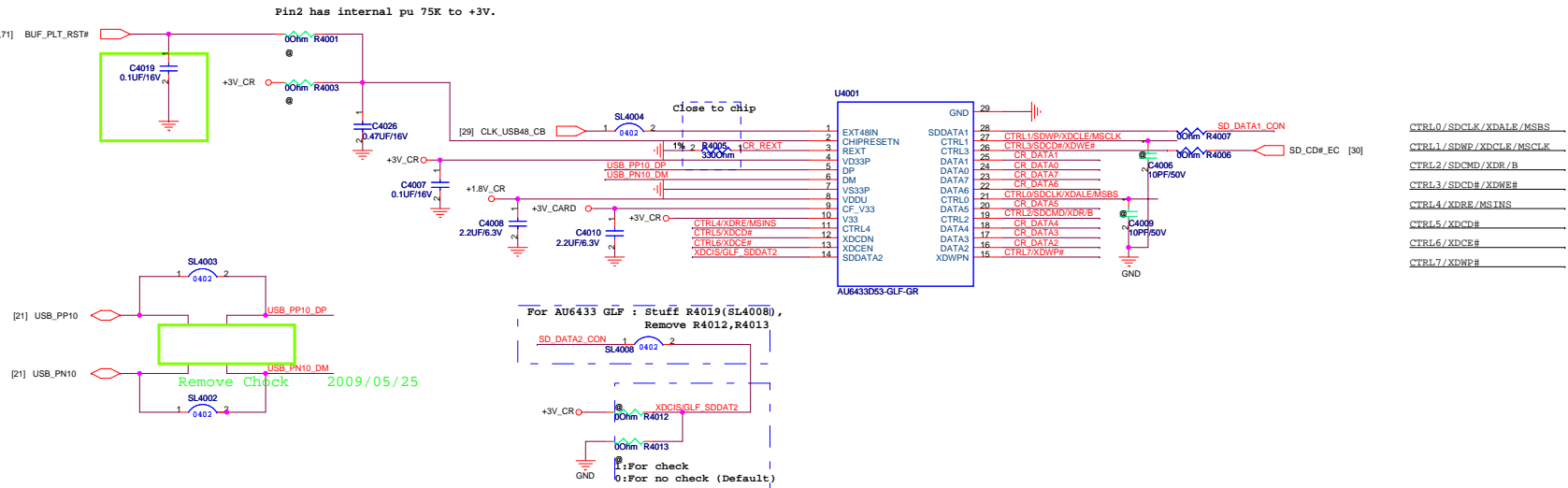


<Variant Name>		
		<b>Title :</b> *
ASUSTeK COMPUTER INC		<b>Engineer:</b> <i>Richard Lu</i>
Size B	Project Name <b>F5Z</b>	Rev 2.05
Date: <i>Tuesday, May 26, 2009</i>		Sheet <i>39</i> of <i>91</i>

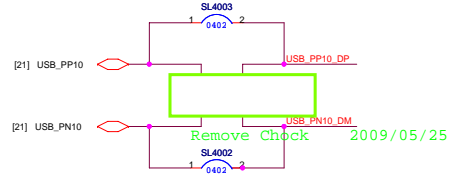


**AU6433-GLF: 02G630001530**  
**AU6433-GEF: 02G630001521.**  
 現在要求使用AU6433-GLF: 02G630001530，  
 做bom以及線路要注意

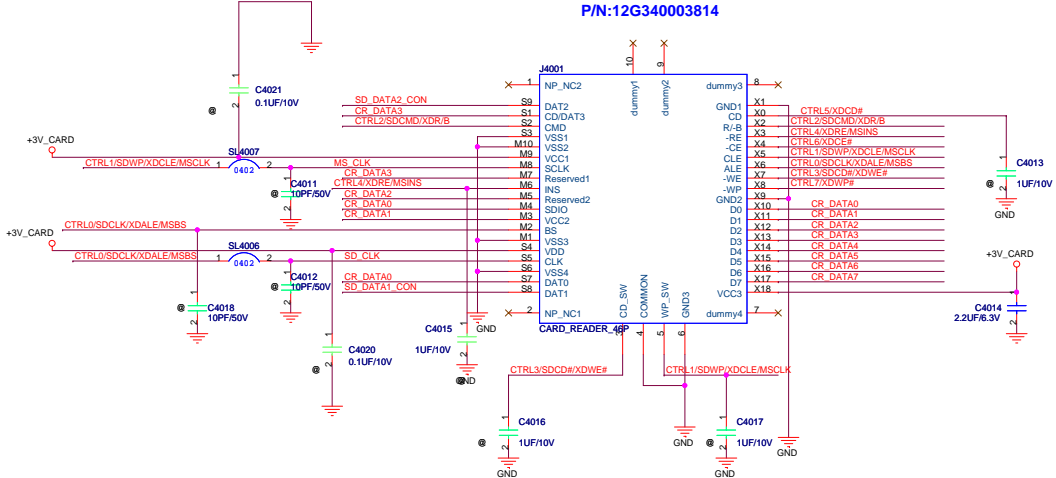
Pin2 has internal pu 75K to +3V.  
 [5,20,30,33,43,53,71] BUF\_PLT\_RST#



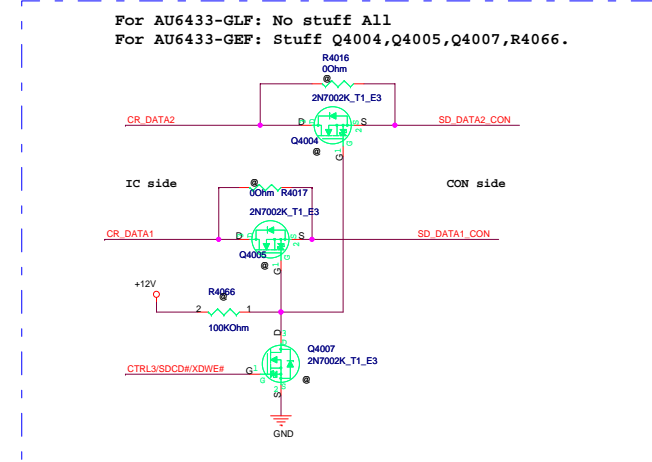
For AU6433 GLF : Stuff R4019(SL4008),  
 Remove R4012,R4013  
 For AU6433 GEF : Stuff R4019(SL4008),  
 Remove R4012,R4013



P/N:12G340003814



Fix MS Duo Adaptor short issue.  
 (SD\_DATA1,SD\_DATA2,XD\_GND short,XD\_CD# may be possible short)





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<Variant Name>

		Title : *	
ASUSTeK COMPUTER INC		Engineer: <i>Richard Lu</i>	

Size	Project Name	Rev
Custom	<b>F5Z</b>	2.05
Date: <i>Tuesday, May 26, 2009</i>		Sheet 41 of 91

5

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C

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B

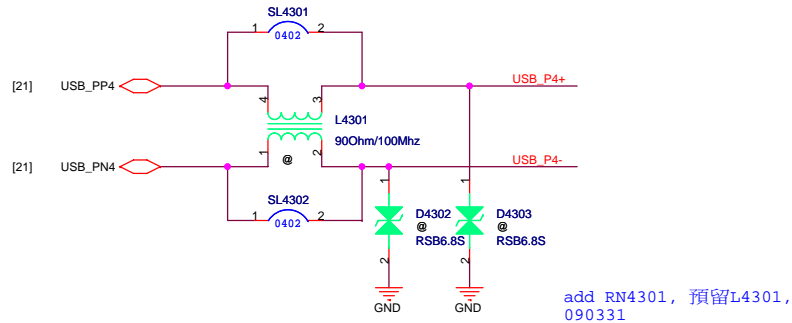
A

A

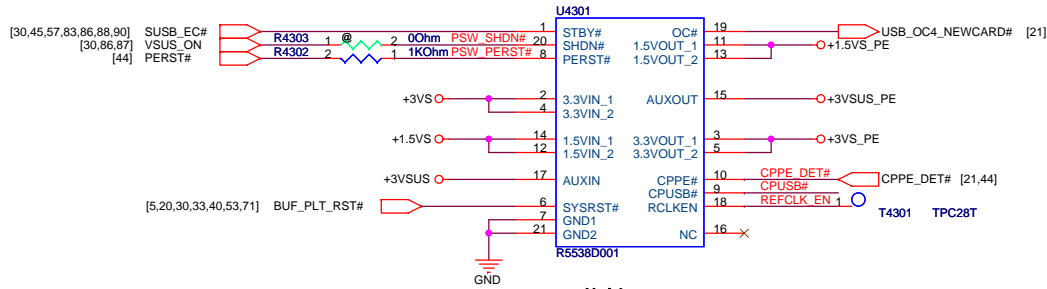
<Variant Name>

		<b>Title :</b> *
ASUSTeK COMPUTER INC		<b>Engineer:</b> <i>Richard Lu</i>

Size	Project Name	Rev
Custom	<b>F5Z</b>	2.05
Date: <i>Tuesday, May 26, 2009</i>		Sheet <b>42</b> of <b>91</b>



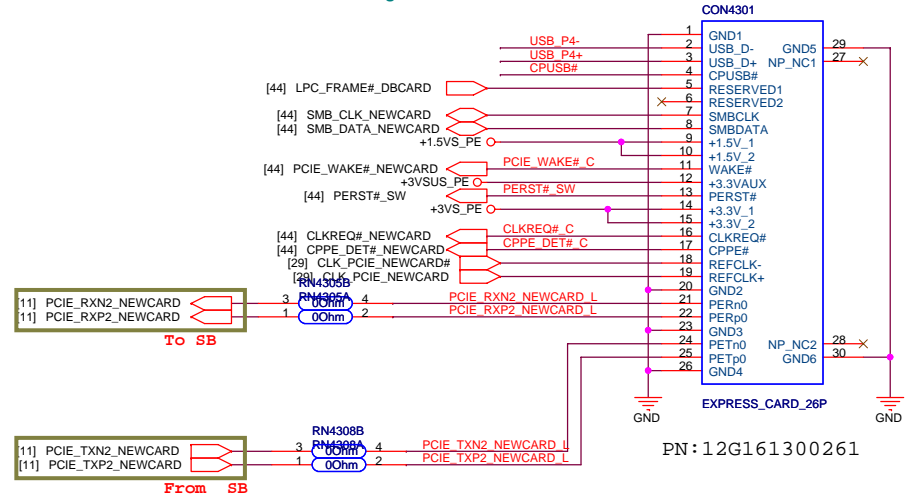
add RN4301, 預留L4301, 090331



換料

!! ExpressCard Standard 1.0:  
Change Pin7 from RESERVED to SMBCLK  
Change Pin8 from SMBCLK to SMBDATA  
Change Pin9 from SMBDATA to +1.5V

NewCard Header



To SB

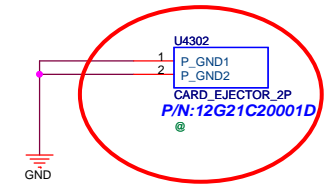
From SB

PN: 12G161300261

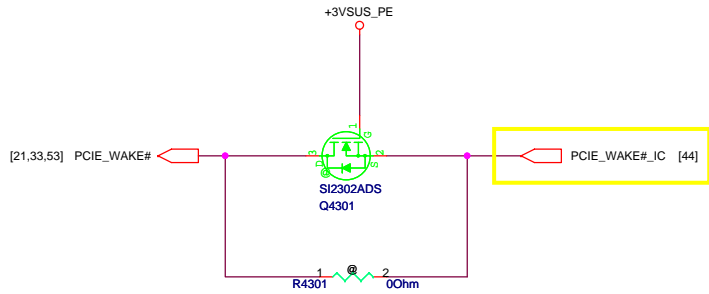
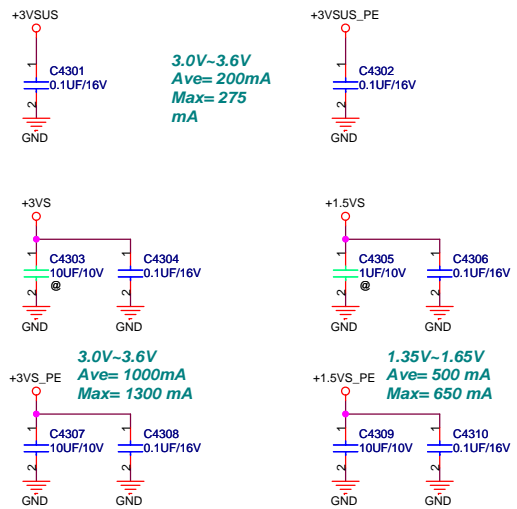
R2.0 080402

Un-mount U4302 (Since it is not SMT component)

080216 R1.1  
Add Resistor



Remove U4302.  
090406

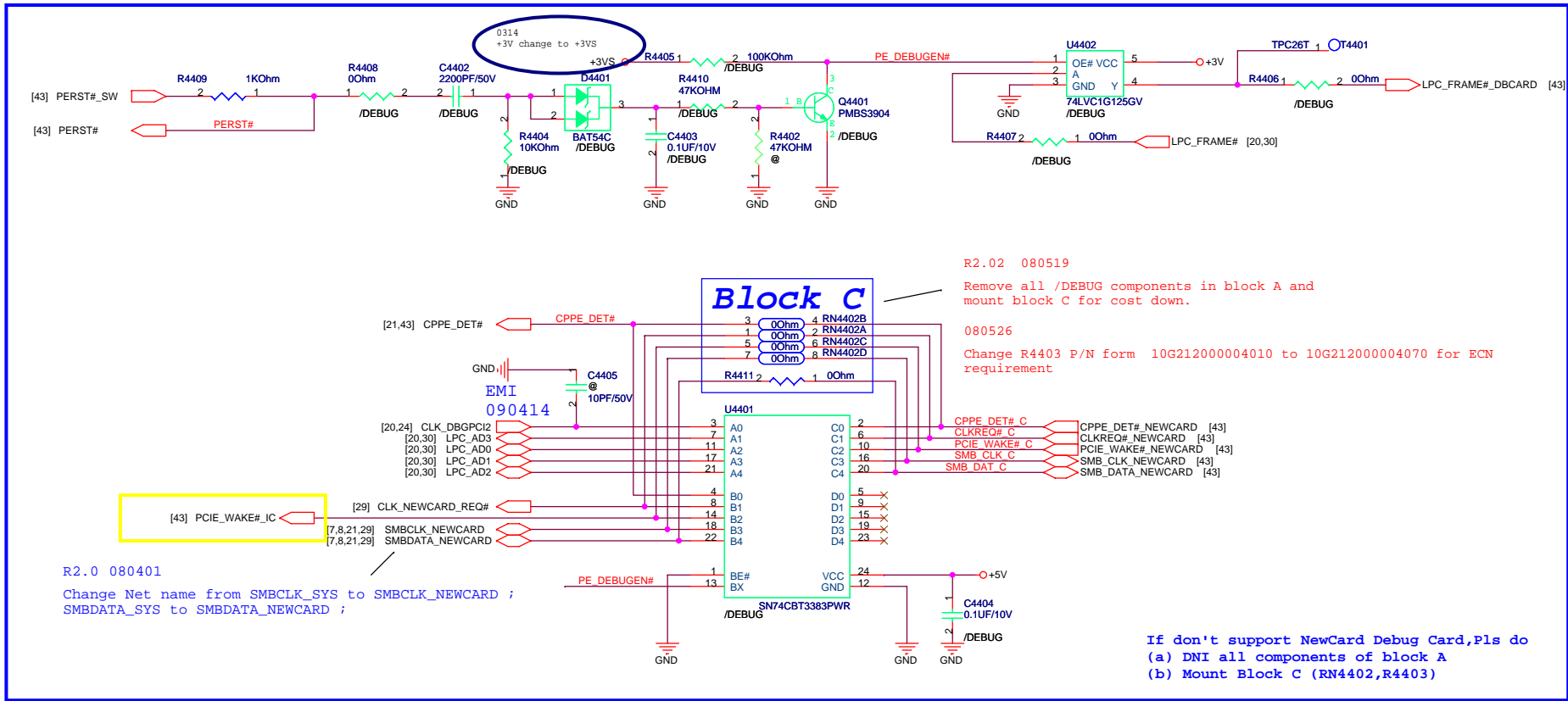


RemoveNew Card REFCLK\_EN control part  
090331

<Variant Name>

		<b>Title : NEWCARD</b>	
ASUSTek COMPUTER INC		Engineer: <b>Richard Lu</b>	
Size	Project Name	Rev	
Custom	<b>F5Z</b>	2.05	
Date: Tuesday, May 26, 2009	Sheet 43 of 91		

# Block A

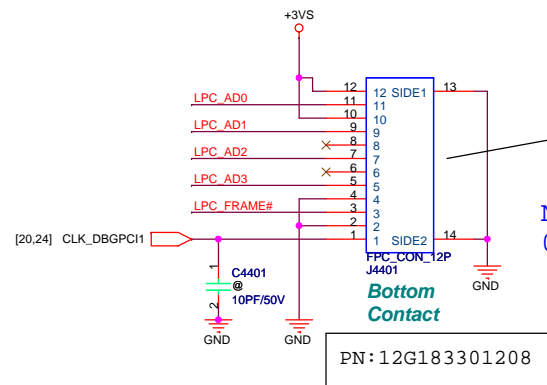


R2.0 080401

Change Net name from SMBCLK\_SYS to SMBCLK\_NEWCARD ;  
SMBDATA\_SYS to SMBDATA\_NEWCARD ;

## For PCMCIA Debug Card

If support NewCard Debug Card,  
Pls don't mount all components.



R2.04

Un-mount J4401 for cost down

Notice  
090410

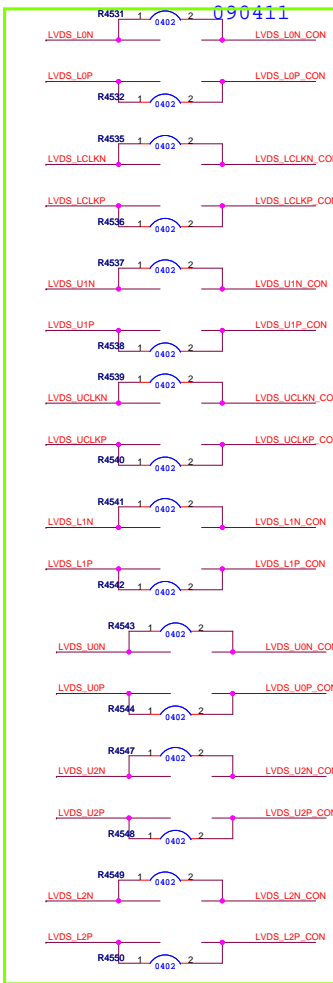
R2.05

Change RN4401 from 100ohm to 100pF capacitance.  
The capacitance with modification of RNX3001 is used to fix the LAD and SERIRQ signals coupling issue. However, the LPC debug board EEROM over-write function is not support now.

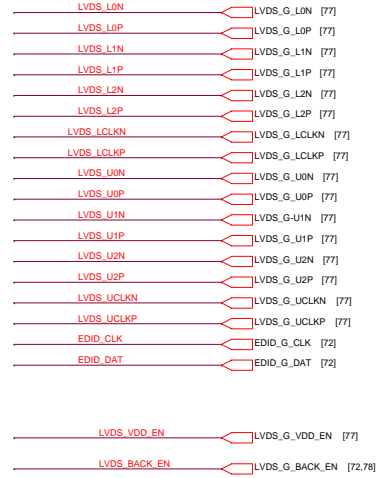
<Variant Name>

layoutguide notic those SL colay with chock

090411

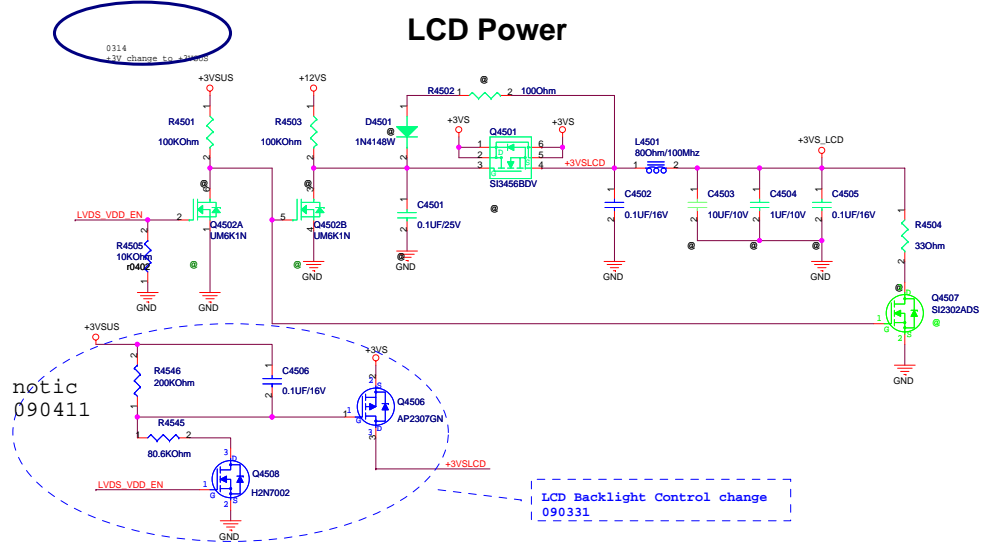


M92-M2



Remove Bead 2005/05/25

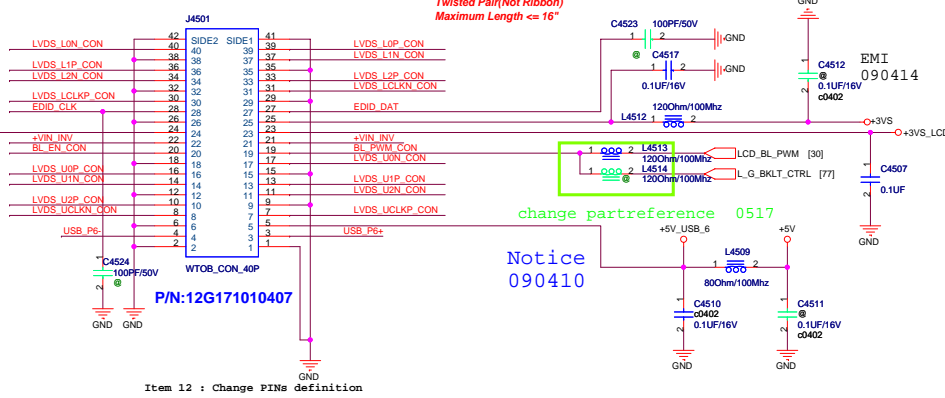
### LCD Backlight Control



notic 090411

LCD Backlight Control change 090331

### LCD LVDS/Inverter/CCD conn.



Cable Requirement:  
Impedence: 100 ohm +/- 10%  
Length Mismatch <= 10 mils  
Twisted Pair(Not Ribbon)  
Maximum Length <= 16"

change partreference 0517

Notice 090410

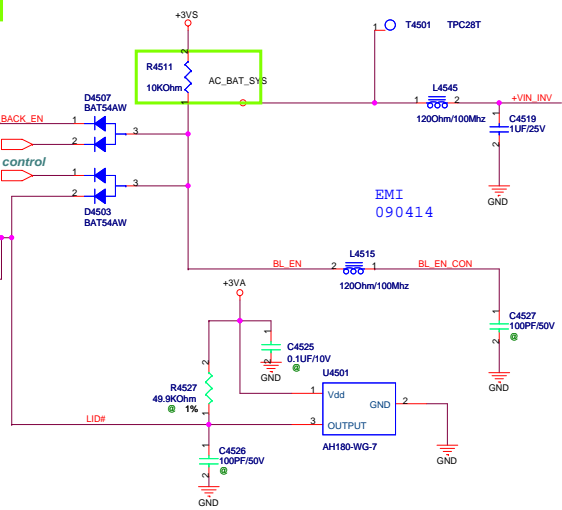
Item 12 : Change PINs definition

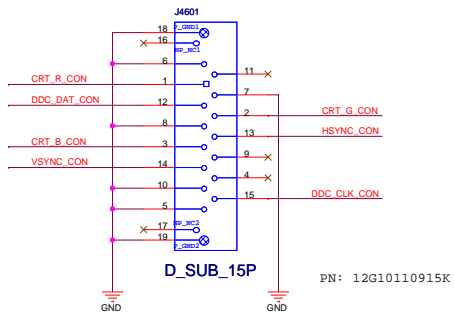
Remove Bead 2005/05/25

change SL 090411

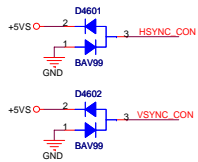
Change R4528 to SL

When AC in,plug cable varify hi Voltage?

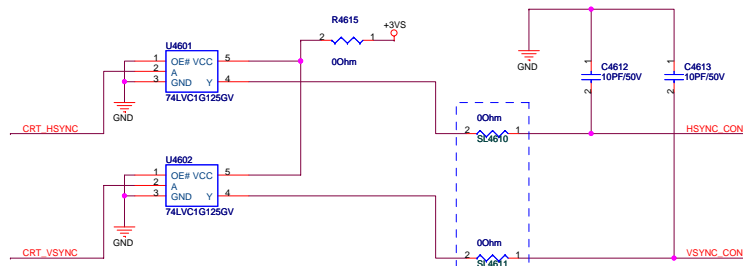
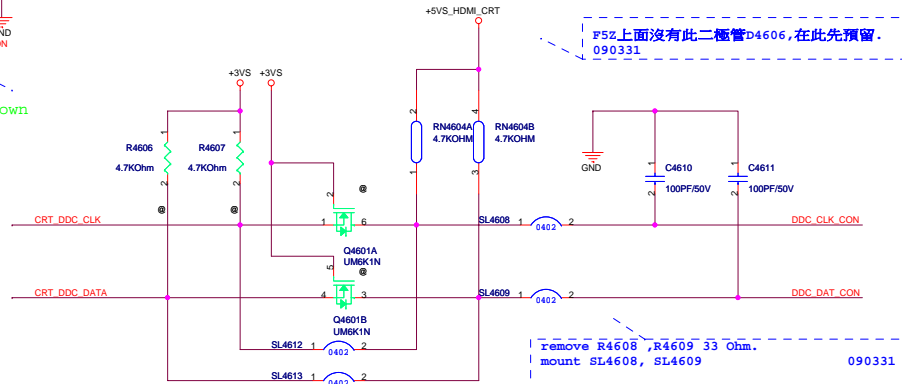
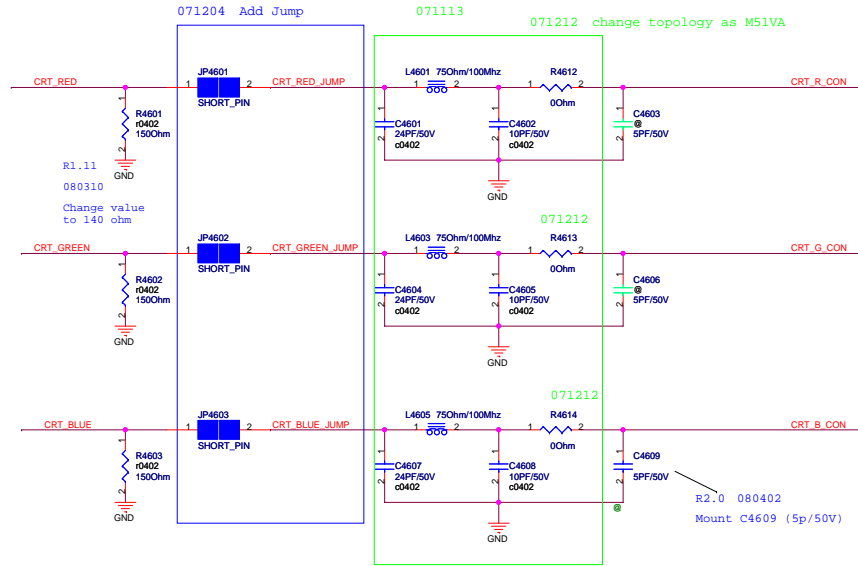
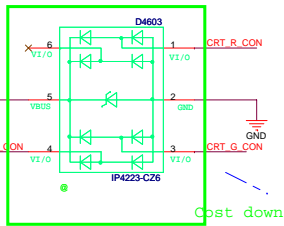




PLACE ESD Diodes near  
VGA port



Notice change P/N  
090410

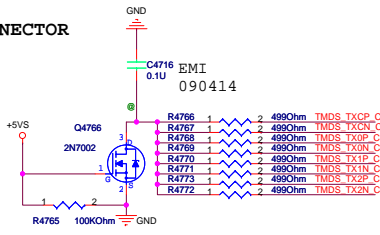


THE COST

- CRT\_RED <math>\rightarrow</math> CRT\_G\_RED [72]
- CRT\_GREEN <math>\rightarrow</math> CRT\_G\_GREEN [72]
- CRT\_BLUE <math>\rightarrow</math> CRT\_G\_BLUE [72]
- CRT\_DDC\_CLK <math>\rightarrow</math> CRT\_G\_DDC\_CLK [72]
- CRT\_DDC\_DATA <math>\rightarrow</math> CRT\_G\_DDC\_DATA [72]
- CRT\_HSYNC <math>\rightarrow</math> CRT\_G\_HSYNC [72,78]
- CRT\_VSYNC <math>\rightarrow</math> CRT\_G\_VSYNC [72,78]

<Variant Name>

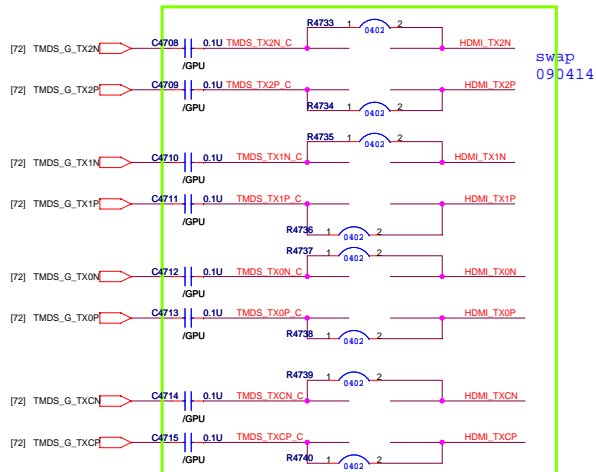
Close to CONNECTOR



不建議換成排阻.  
090406

Close to CONNECTOR

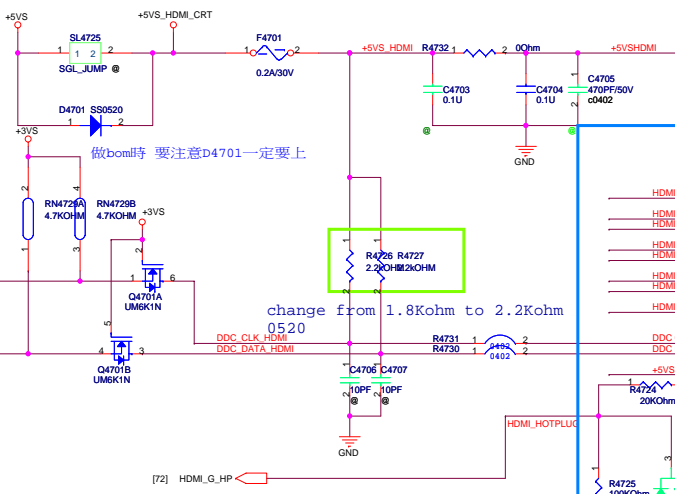
Notice  
090410



swap  
090414

Remove Bead

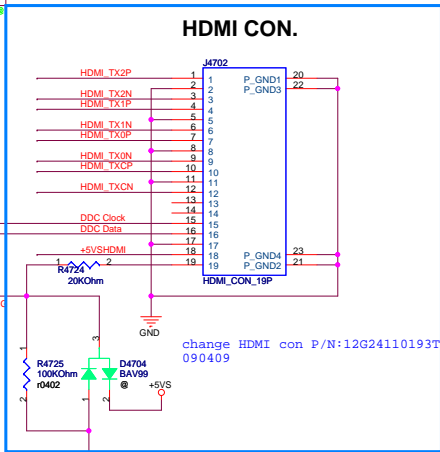
Notice  
090410



做bom時 要注意D4701一定要上

change from 1.8kohm to 2.2kohm  
0520

HDMI CON.



change HDMI con P/N:12G24110193T  
090409

- Note:
1. R1930,R1931,R1932: For EMI.(default=0 ohm)
  2. HDMI\_DDC\_CLK,HDMI\_DDC\_DATA: +3V tolerant

Notice  
090410

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D

C

C


B

B

A

A

<Variant Name>

		<b>Title :</b> *	
ASUSTeK COMPUTER INC		<b>Engineer:</b> <i>Richard Lu</i>	
Size	Project Name		Rev
Custom	<b>F5Z</b>		2.05
Date: <i>Tuesday, May 26, 2009</i>		Sheet	48 of 91

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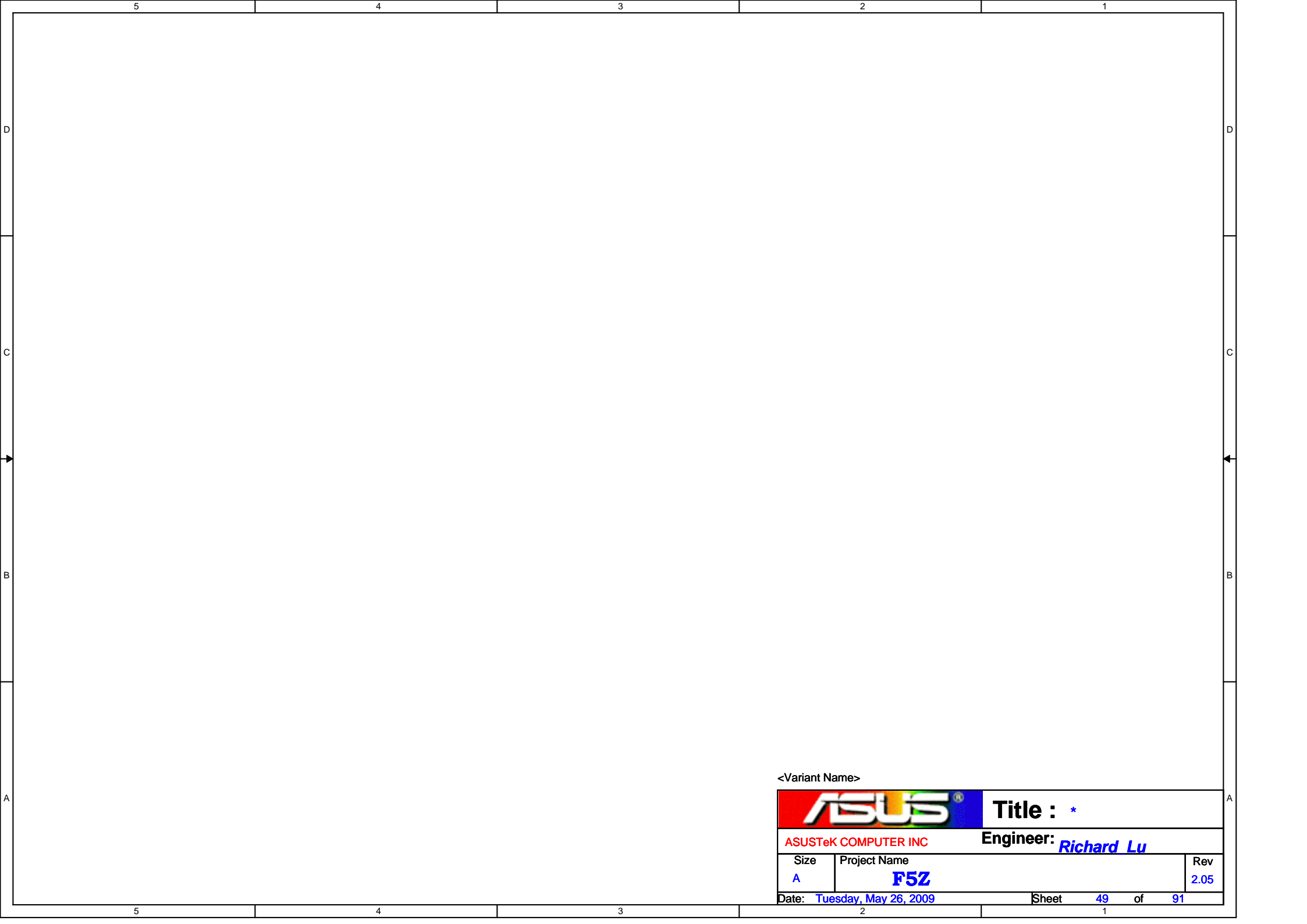
4

3


2

1

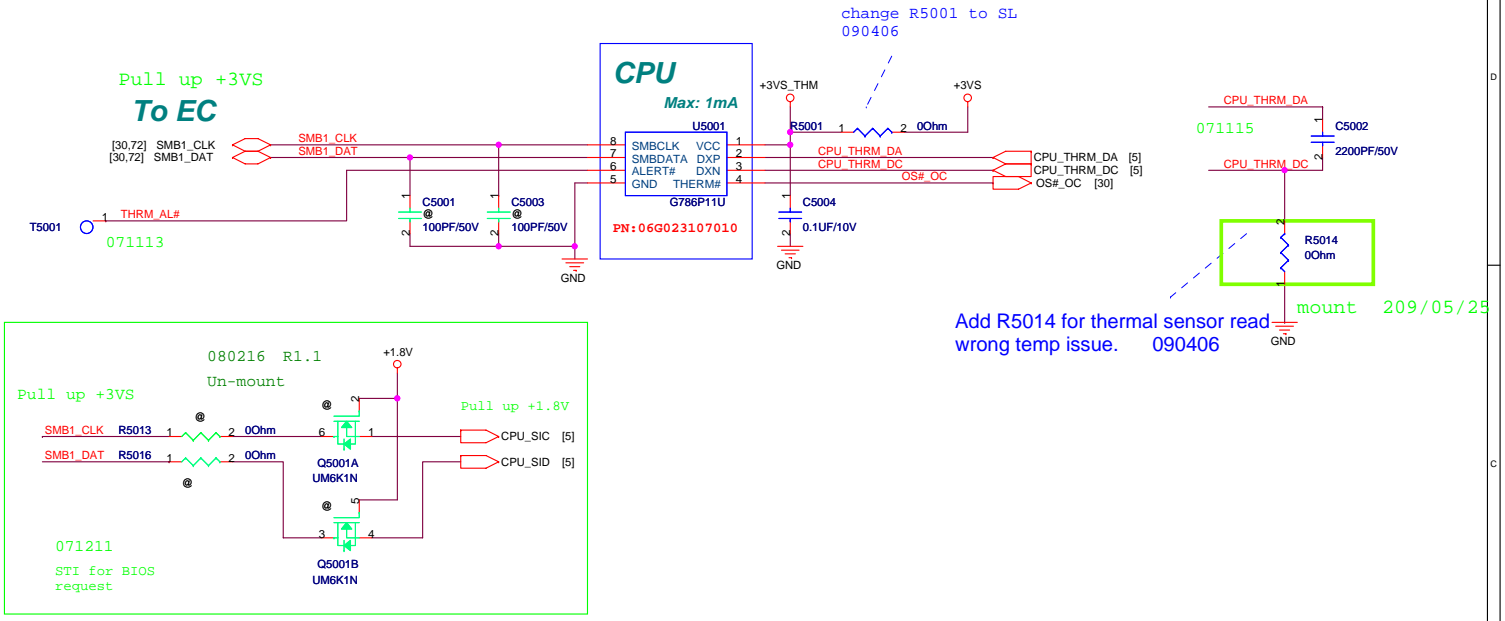




<Variant Name>

		<b>Title :</b> *
ASUSTeK COMPUTER INC		<b>Engineer:</b> <i>Richard Lu</i>
Size	Project Name	Rev
A	<b>F5Z</b>	2.05
Date: <b>Tuesday, May 26, 2009</b>		Sheet <b>49</b> of <b>91</b>

# Thermal Sensor



Route H\_THERMDA and H\_THERMDC on the same layer

-----OTHER SIGNALS  
15 mils

=====GND  
10 mils

=====H\_THERMDA(10 mils)  
10 mils

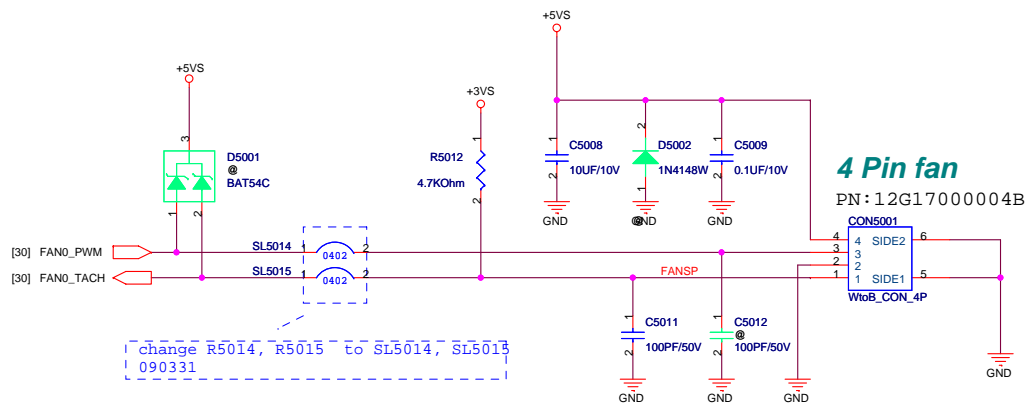
=====H\_THERMDC(10 mils)  
10 mils

=====GND  
15 mils

-----OTHER SIGNALS

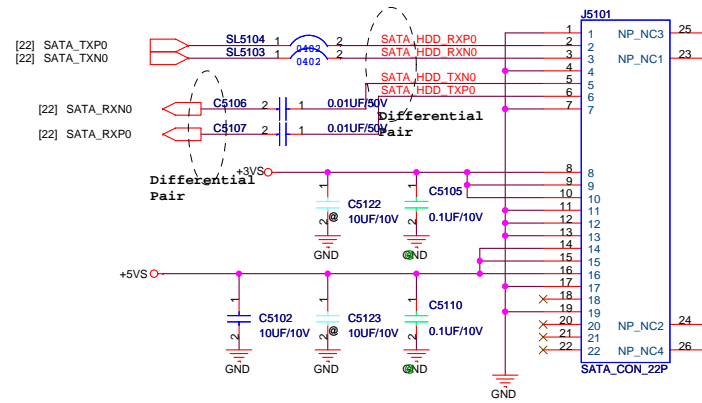
Avoid FSB, Power

# DC FAN Control



# SATA HDD

## SATA HDD CON

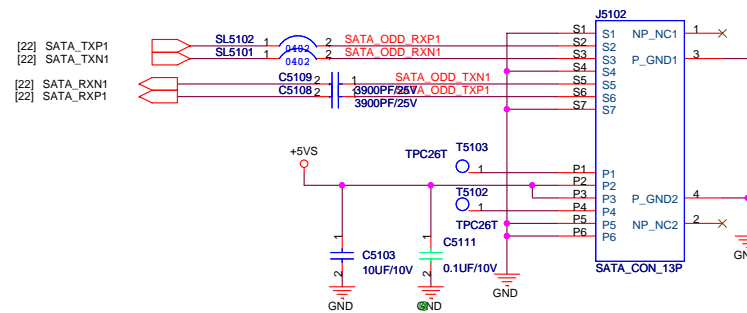


P/N:12G15200022G

MLCC 4700PF/25V (0402)X7R 10%  
11G232147212360 Design IP

MLCC 0.1UF/10V (0402) X7R 10%  
11G232110416360  
比較一下價格

## ODD



P/N:12G15100013J

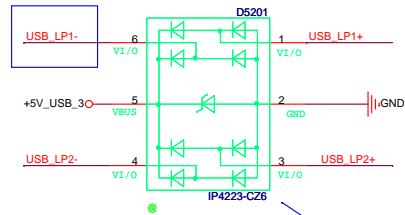
<Variant Name>

071119 change common choke and R P/N

080213 R1.1  
Change D5201, D5204, D5206, D5208 footprint

080125 R1.1  
Change the USB Varistor from EGA10603V05A1 to AZC099-04S

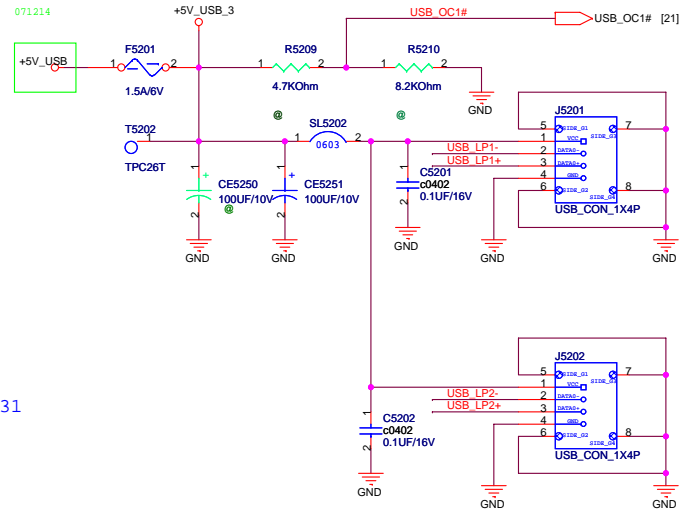
080215 R1.1  
SWAP



07G028075010為建議用料已經更換. 090331

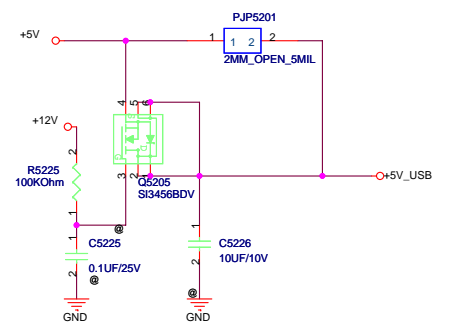
080218 R1.1  
Change PN From 07G014075600 to 07G014075310

Change all MOS with ESD part

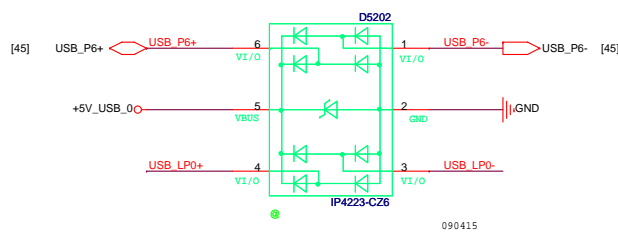


P/N:12G130011045

old:usb\_lx4p\_4hold\_sun\_lf3  
new:nb\_usb\_lx4p\_4hold\_su\_lf2

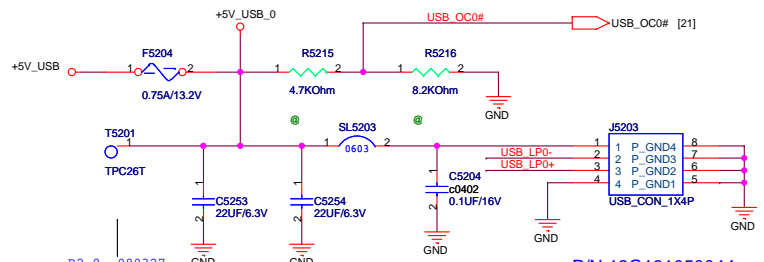


Remove Bead 2005/05/25



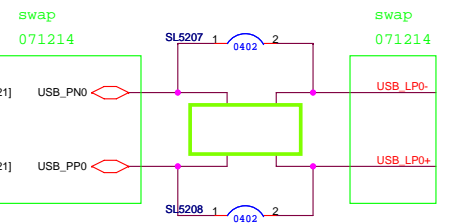
090415

預留USB OC function 090406



R2.0 080327  
Add test point for factory ICT test

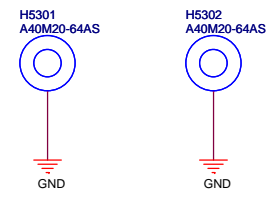
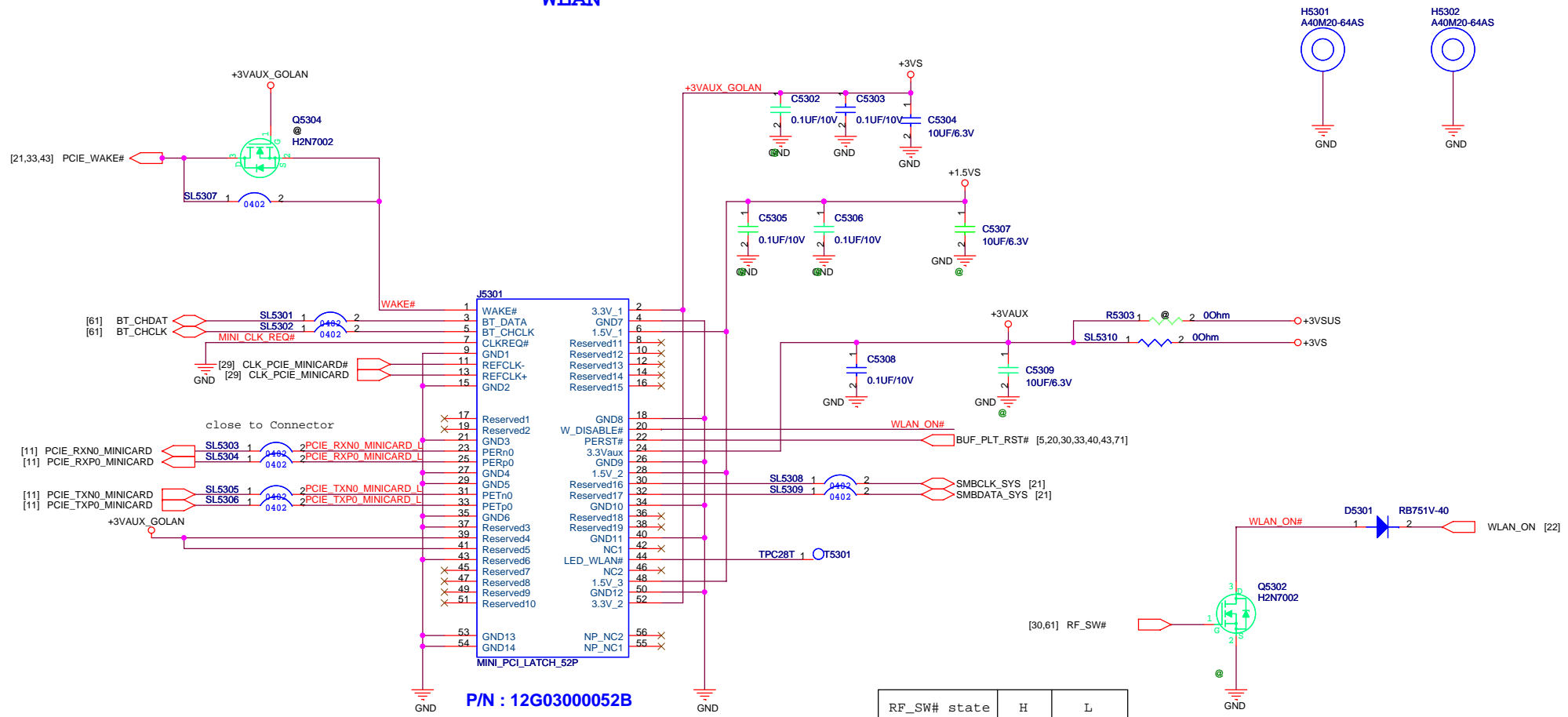
P/N:12G131050044



SWAP 090417

-Variant Name-		Title : USB CONN	
ASUSTek COMPUTER INC		Engineer: Richard Lu	
Size	Project Name	Rev	2.05
Custom	F5Z	Date: Tuesday, May 26, 2009	Sheet 52 of 91

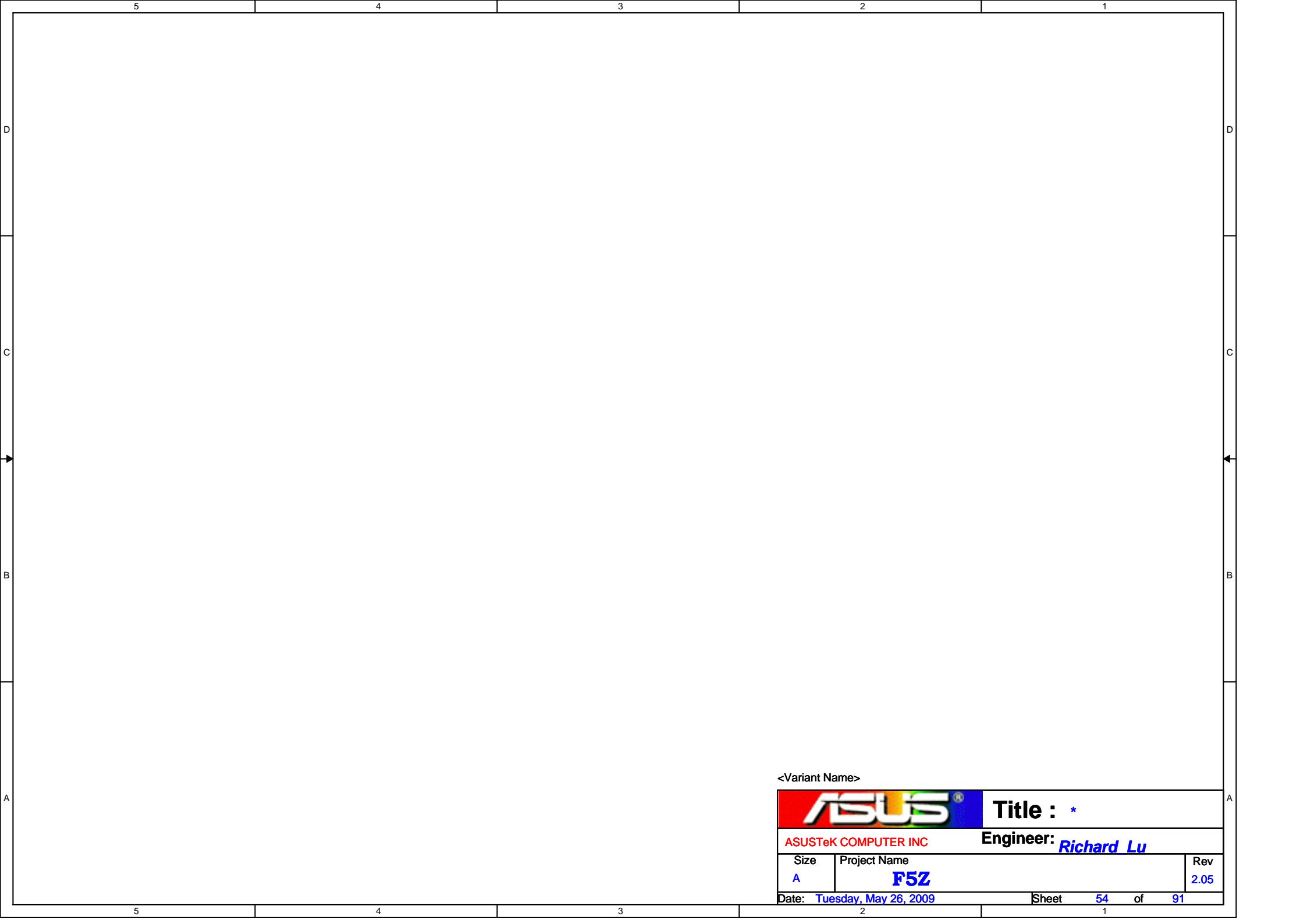
# WLAN




RF_SW# state	H	L
WLAN state	Off	On

<Variant Name>

<b>ASUS</b>		<b>Title : MINICARD</b>
ASUSTek COMPUTER INC		Engineer: <b>Xinghua chen</b>
Size	Project Name	Rev
Custom	<b>F83T</b>	2.0
Date: Friday, May 29, 2009		Sheet 53 of 91



<Variant Name>

		<b>Title :</b> *
ASUSTeK COMPUTER INC		<b>Engineer:</b> <i>Richard Lu</i>
Size	Project Name	Rev
A	<b>F5Z</b>	2.05
Date: <b>Tuesday, May 26, 2009</b>		Sheet <b>54</b> of <b>91</b>

A

B

C

D

E

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<Variant Name>

		<b>Title :</b> *	
ASUSTeK COMPUTER INC		<b>Engineer:</b> <i>Richard Lu</i>	
Size	Project Name	Rev	
A	<b>F5Z</b>	2.05	
Date: <b>Tuesday, May 26, 2009</b>		Sheet	55 of 91

A

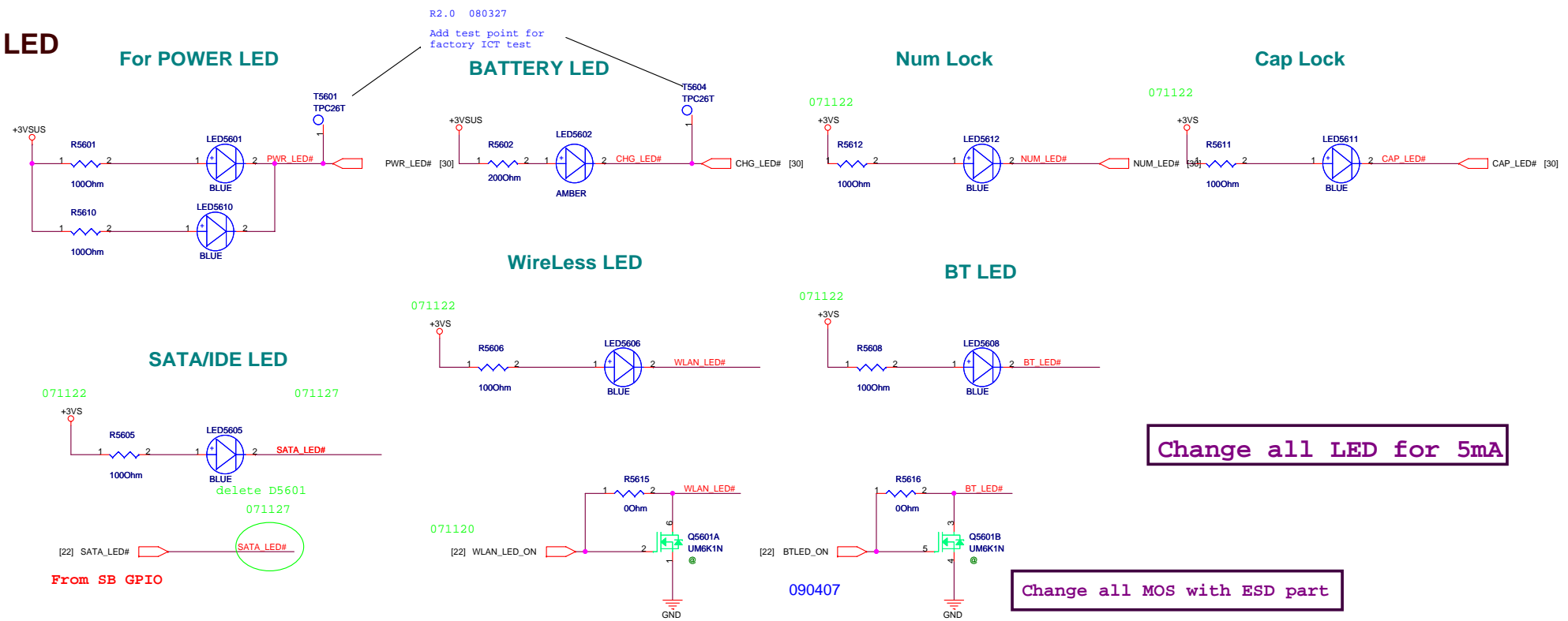
B

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E

# LED



Change all LED for 5mA

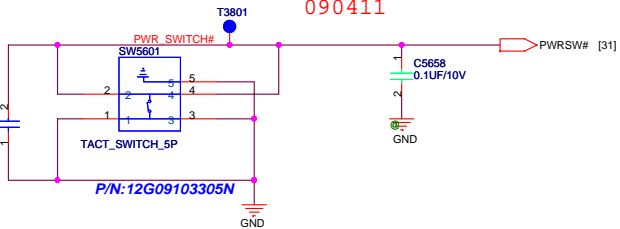
Change all MOS with ESD part

# F5Z SWITCH CIRCUIT

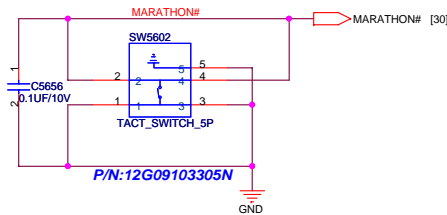
Move SW from P32 to P56

## Power SW.

Remove R5656  
090411



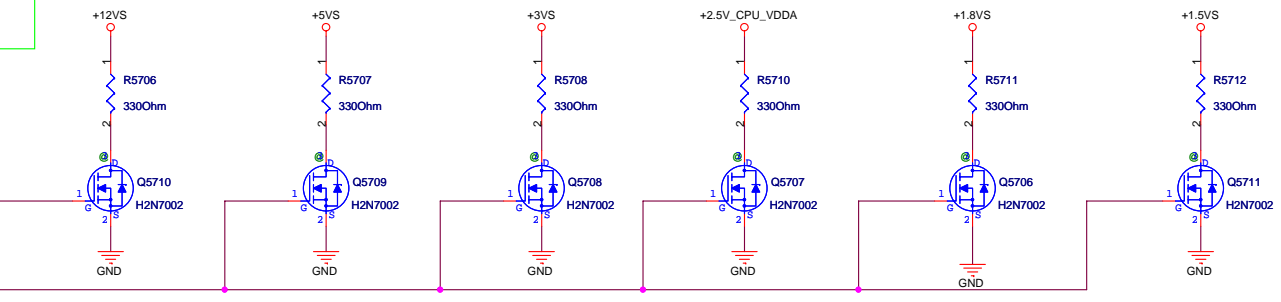
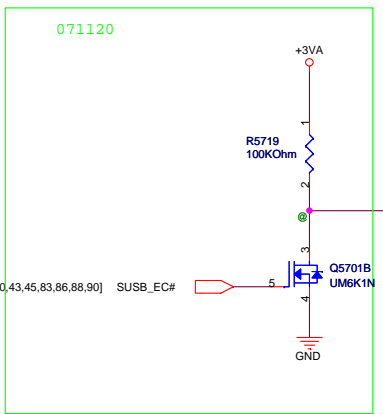
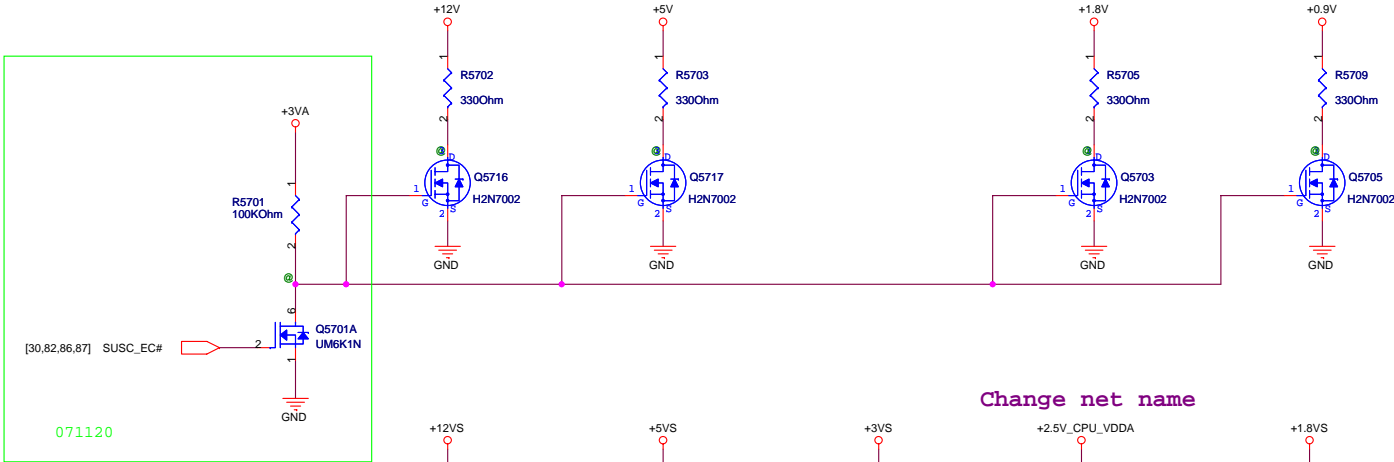
## MARATHON#



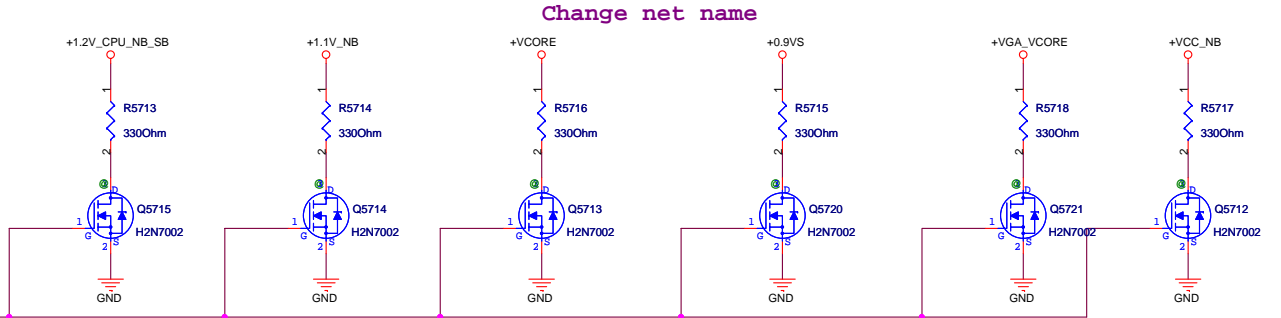
<Variant Name>

<b>ASUS</b>		<b>Title : LED/PWR SWICH</b>	
ASUSTek COMPUTER INC		Engineer: <i>Xinghua chen</i>	
Size	Project Name	Rev	
Custom	<b>F83T</b>	2.0	
Date: Wednesday, May 27, 2009		Sheet	56 of 91





Change all MOS with ESD part



Change net name

Change net name

Change net name

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D

C

C


B

B

A

A

<Variant Name>

		<b>Title :</b> *	
ASUSTeK COMPUTER INC		Engineer: <i>Richard Lu</i>	
Size	Project Name		Rev
Custom	<b>F5Z</b>		2.05
Date: <i>Tuesday, May 26, 2009</i>		Sheet	58 of 91

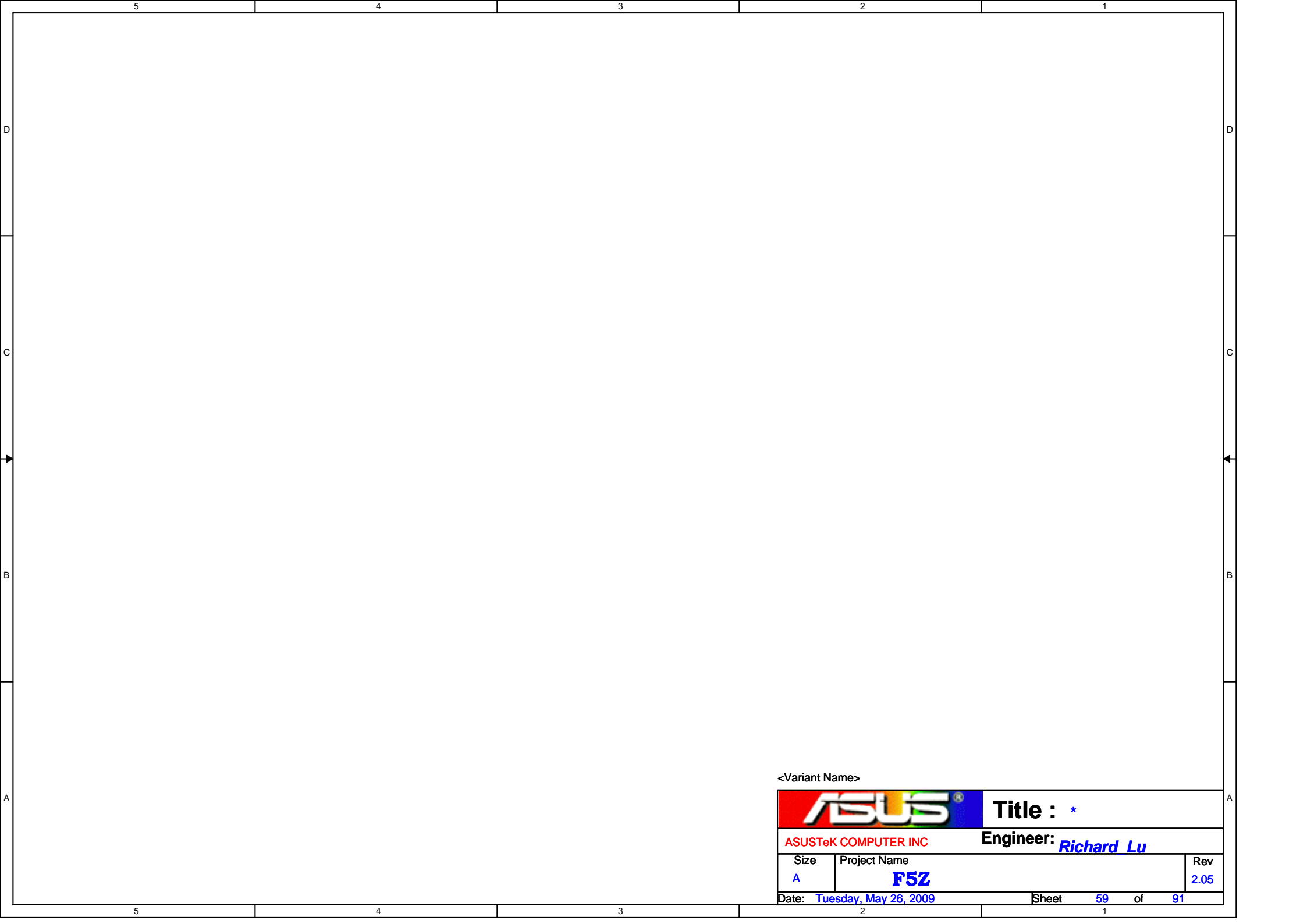
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<Variant Name>

		<b>Title :</b> *	
ASUSTeK COMPUTER INC		<b>Engineer:</b> <i>Richard Lu</i>	
Size	Project Name	Rev	
A	<b>F5Z</b>	2.05	
Date: <b>Tuesday, May 26, 2009</b>		Sheet	<b>59</b> of <b>91</b>

# BATTERY

change PL->L,PT->T,PC->C

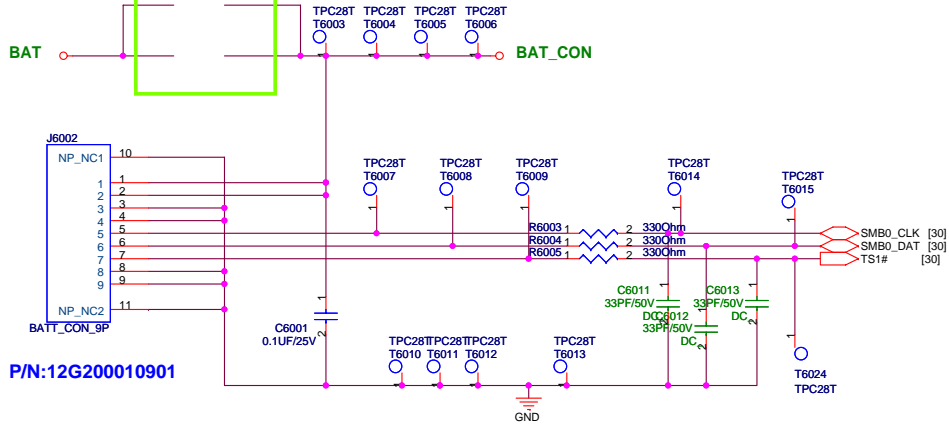
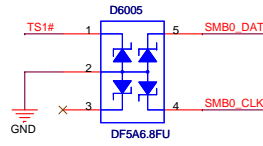
071120

Remove JP

Remove bead 2009/05/25

change footprint

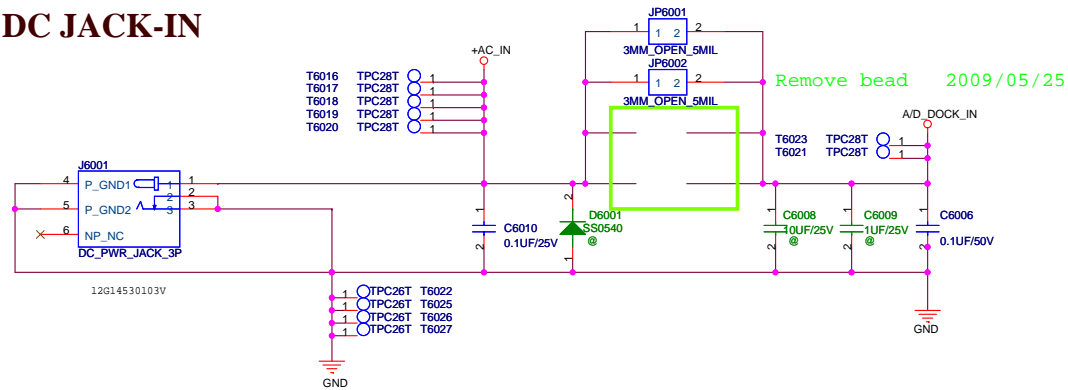
071203



Add for AC Adapter protect

# DC JACK-IN

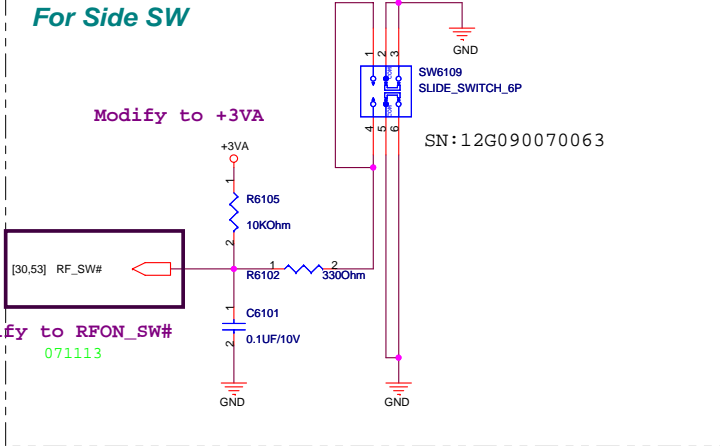
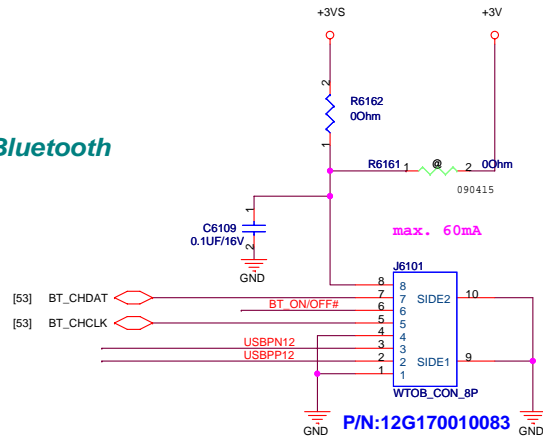
## Adaptor IN



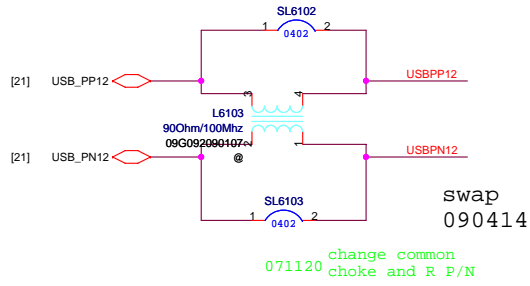
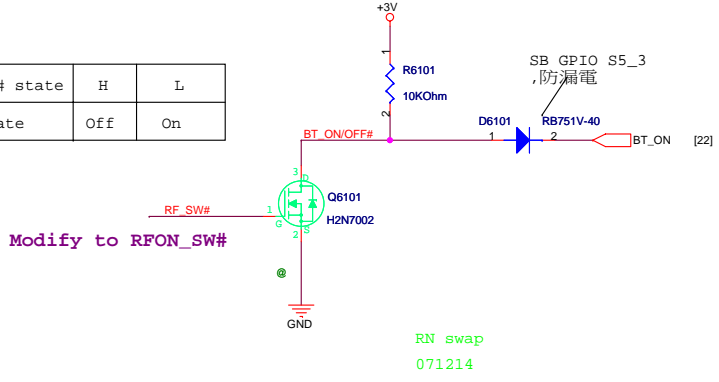
<Variant Name>

<b>ASUS</b>		<b>Title :DC_Jack &amp; BAT Con</b>	
ASUSTeK COMPUTER INC		Engineer: <b>Richard Lu</b>	
Size	Project Name	Rev	
Custom	<b>F5Z</b>	2.05	
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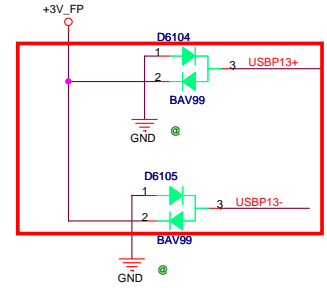
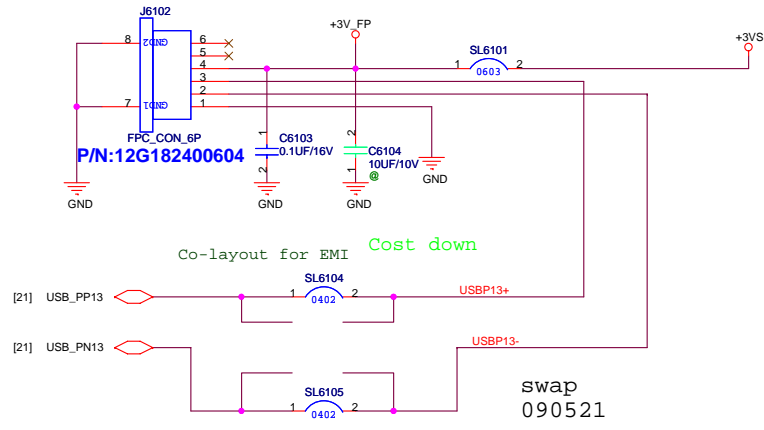
### For Bluetooth



RF_SW# state	H	L
BT state	Off	On



### Fingerprint Conn.



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D

D

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C


B

B

A

A

<Variant Name>

		Title : *	
ASUSTeK COMPUTER INC		Engineer: <i>Richard Lu</i>	
Size	Project Name	Rev	
Custom	<b>F5Z</b>	2.05	
Date: <i>Tuesday, May 26, 2009</i>		Sheet	62 of 91

5

4

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D

D

C

C


B

B

A

A

<Variant Name>

		<b>Title :</b> *	
ASUSTeK COMPUTER INC		<b>Engineer:</b> <i>Richard Lu</i>	
Size	Project Name		Rev
Custom	<b>F5Z</b>		2.05
Date: <i>Tuesday, May 26, 2009</i>		Sheet	63 of 91

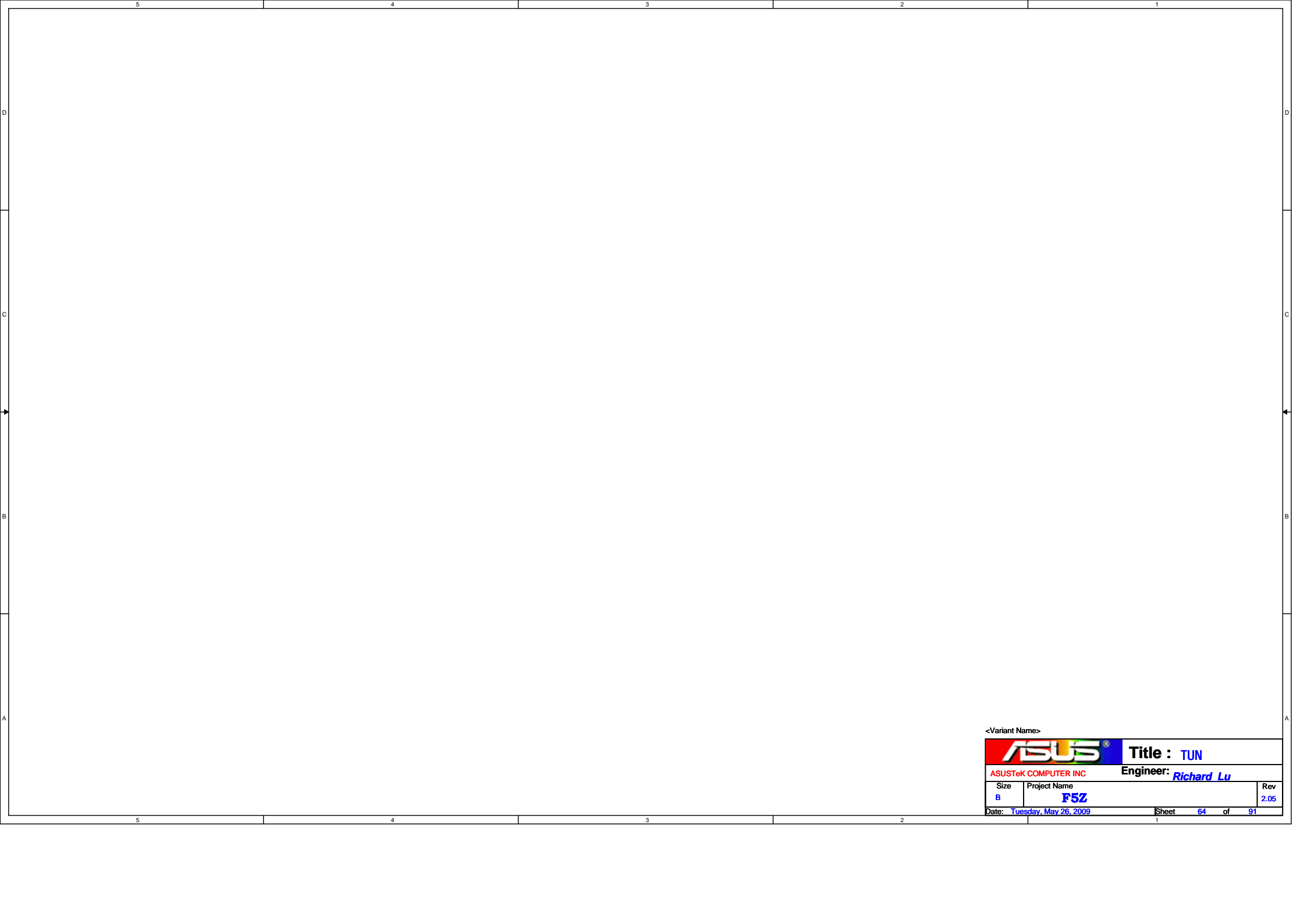
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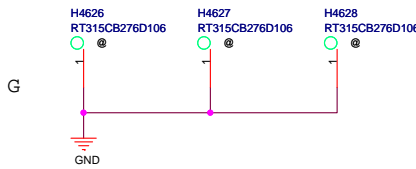
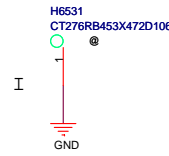
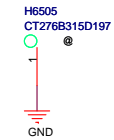
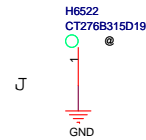
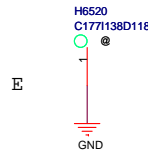
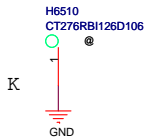
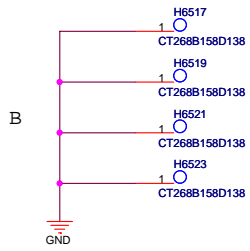


<Variant Name>

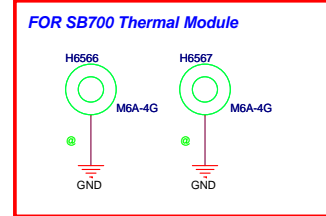
		<b>Title :</b> TUN
ASUSTeK COMPUTER INC		<b>Engineer:</b> Richard Lu
Size	Project Name	Rev
B	F5Z	2.05
Date: Tuesday, May 26, 2009		Sheet 64 of 91



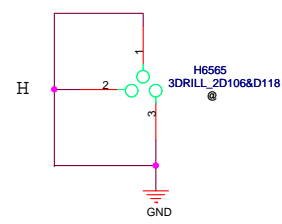
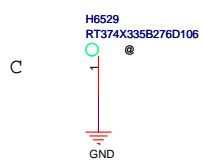
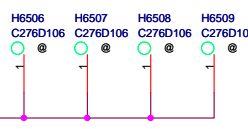
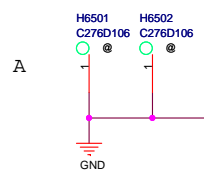
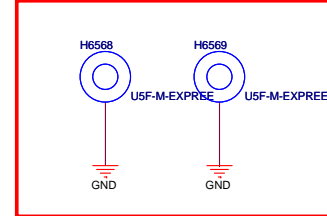
FOR CPU



090406  
Add the Screw hole for thermal Module

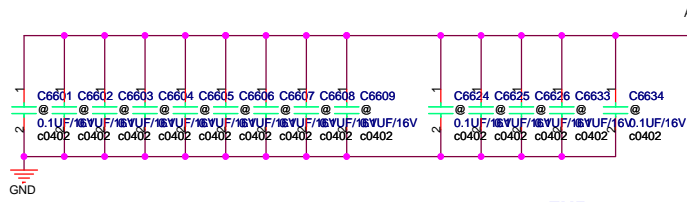


090406  
Add the Nut for GPU thermal Module

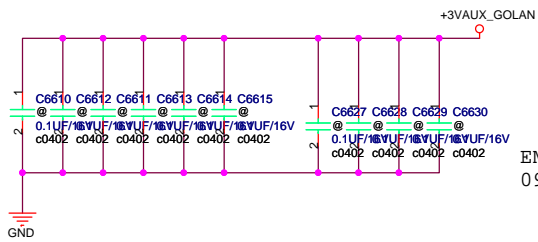
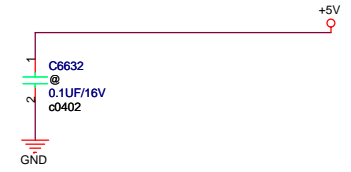


change to P/N:13GN9980M090-1 for high limit

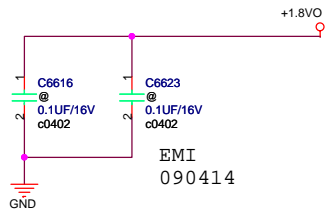
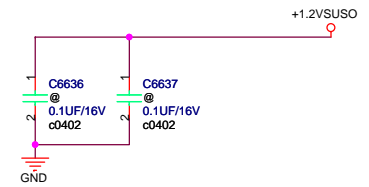
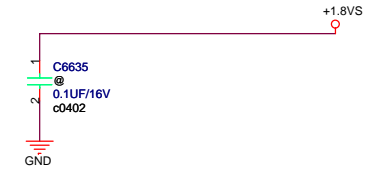
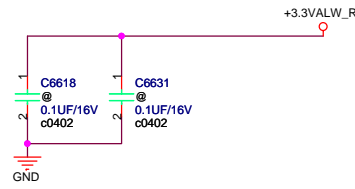
<Variant Name>		<b>ASUS</b> ®		<b>Title : Screw Hole</b>	
ASUSTeK COMPUTER INC		Project Name		Engineer: <OrgAddr1>	
Size	Custom	F5Z			Rev
Date: Friday, May 29, 2009	Sheet	65	of	91	2.05



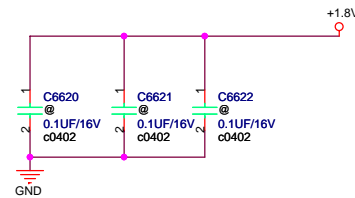
EMI  
090414



EMI  
090414



EMI  
090414



<Variant Name>

		<b>Title : EMI</b>	
ASUSTek COMPUTER INC		Engineer: <b>Richard Lu</b>	
Size	Project Name		Rev
Custom	<b>F5Z</b>		2.05
Date: <b>Tuesday, May 26, 2009</b>		Sheet	66 of 91

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D

D

C

C


B

B

A

A

<Variant Name>

		<b>Title :</b> *
ASUSTeK COMPUTER INC		<b>Engineer:</b> <i>Richard Lu</i>
Size	Project Name	Rev
B	<b>F5Z</b>	2.05
Date: <i>Tuesday, May 26, 2009</i>		Sheet <i>67</i> of <i>91</i>

5

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D

D

C

C


B

B

A

A

<Variant Name>

		<b>Title :</b> *	
ASUSTeK COMPUTER INC		<b>Engineer:</b> <i>Richard Lu</i>	
Size	Project Name		Rev
Custom	<b>F5Z</b>		2.05
Date: <i>Tuesday, May 26, 2009</i>		Sheet	68 of 91

5

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1

1,Vram data swap. 090327

2,修改VGA\_CORE 電壓 , Boot 電壓為1.2V. 090327

3, Page72 add a resistor which connect between XTALIN and XTALOUT when a 27MHz crystal is used. 090329

4, SWAP VRAM data Group4 and Group5 090330

5,Audio AVDD 預留 +3VS 090330

6, Add RN4301, 預留L4301. 090331

7,remove R4610 ,R4611 27 Ohm.(EMI), remove R4608 ,R4609 33 Ohm. mount SL4608, SL4609 ,mount SL4610, SL4611 090331

8,LCD Backlight Control change 090331

9,Remove RJ11 090331

11,SB710 的晶振換成F80系列的32.768KHz的晶振。  
網卡的25MHz的晶振換成料號為07G010Q12500. 090331

12, U4301 pin 18 REFCLKEN NC, remove part 090331

13,Change the ClkGen to RTM880T-797 090331

14, AU6433-GLF mount R4007 090331

15,CLK\_REQ\_LAN is OD ,add R2003 pull high. 090401

17,change power cap PCE8701 & PCE8702 090401

18,change the Screw Hole.Add the Nut for GPU thermal Module 090406

19,Modify the NB & SB power cap 090406

20,Swap the cap pack in page31 090406

21,changeR4726,R4727 from 1.8Kohm to 2.2Kohm 090520

22.Add buffer U4601,U4602 090520

24.Change R4511 to 10Kohm,R7870 to 2.2Kohm 090520

25.Add R2037 for safety 090520

28.Remove L6003,L6004,L6005,L6006 090525

29. Add 10uF cap C7549 090525

30.Remove L4001, L4502, L4506, L4508, L4511, L4503, L4507, L4510, L4504, L4505, L6104, L5201, L5202, L5204, L4704, L4705, L4706, L4707 090525

31.Mount R5014, R7207 090525

32.預留 X7201, C7220, C7219, R7214, R7257 090525

33.Remove NUT for SB 090525

34.Change X2201 P/N:07G010Q12500 090525

35.Change R0403, R0404 from 15ohm to 1Kohm 090525

36. Add C4019 for EMI 090525

37. Change SL4610,SL4610 to 0ohm 090526

		<b>Title : HISTORY</b>	
ASUSTeK COMPUTER INC. NBI		Engineer: <OrgAddr>	
Size	Project Name		Rev
Custom	<b>F5Z</b>		2.06
Date: Friday, May 29, 2009		Sheet	88 of 91

	5	4	3	2	1
D					
C					
B					
A					



**Title :** <Title>

<OrgName>

**Engineer:** <OrgAddr1>

Size  
A

Project Name  
<Doc>

Rev  
<RevCode>

Date: Tuesday, May 26, 2009

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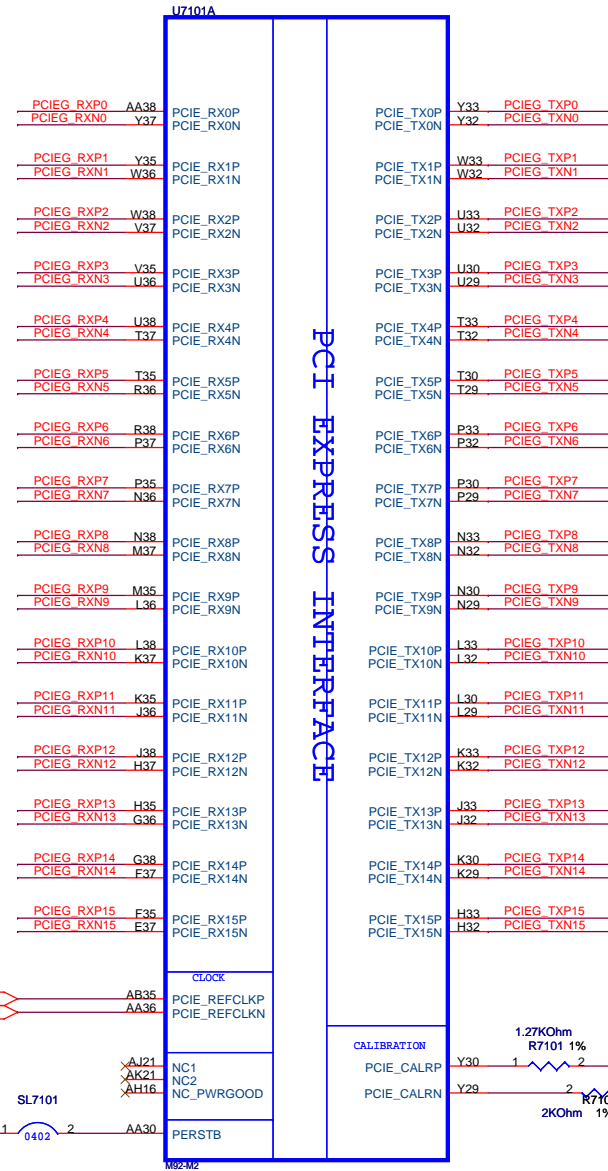
	5	4	3	2	1
D					
C					
B					
A					

notice the net name.RX&TX

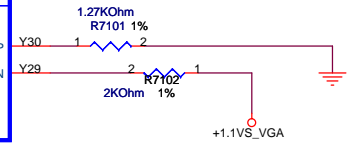
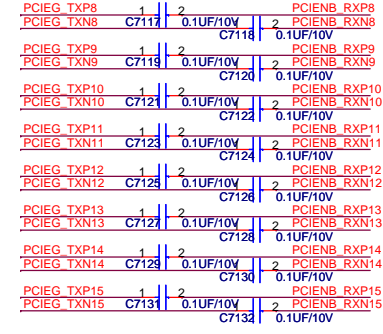
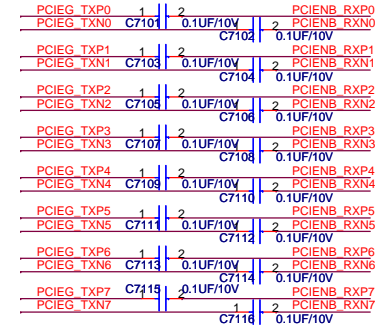


100Mhz 300ppm

[5,20,30,33,40,43,53] BUF\_PLT\_RST#

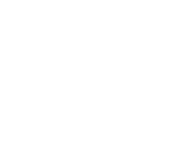
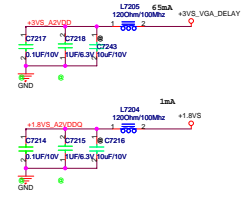
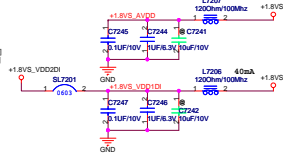
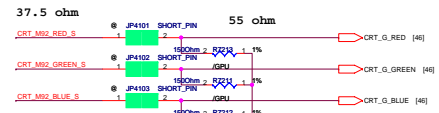
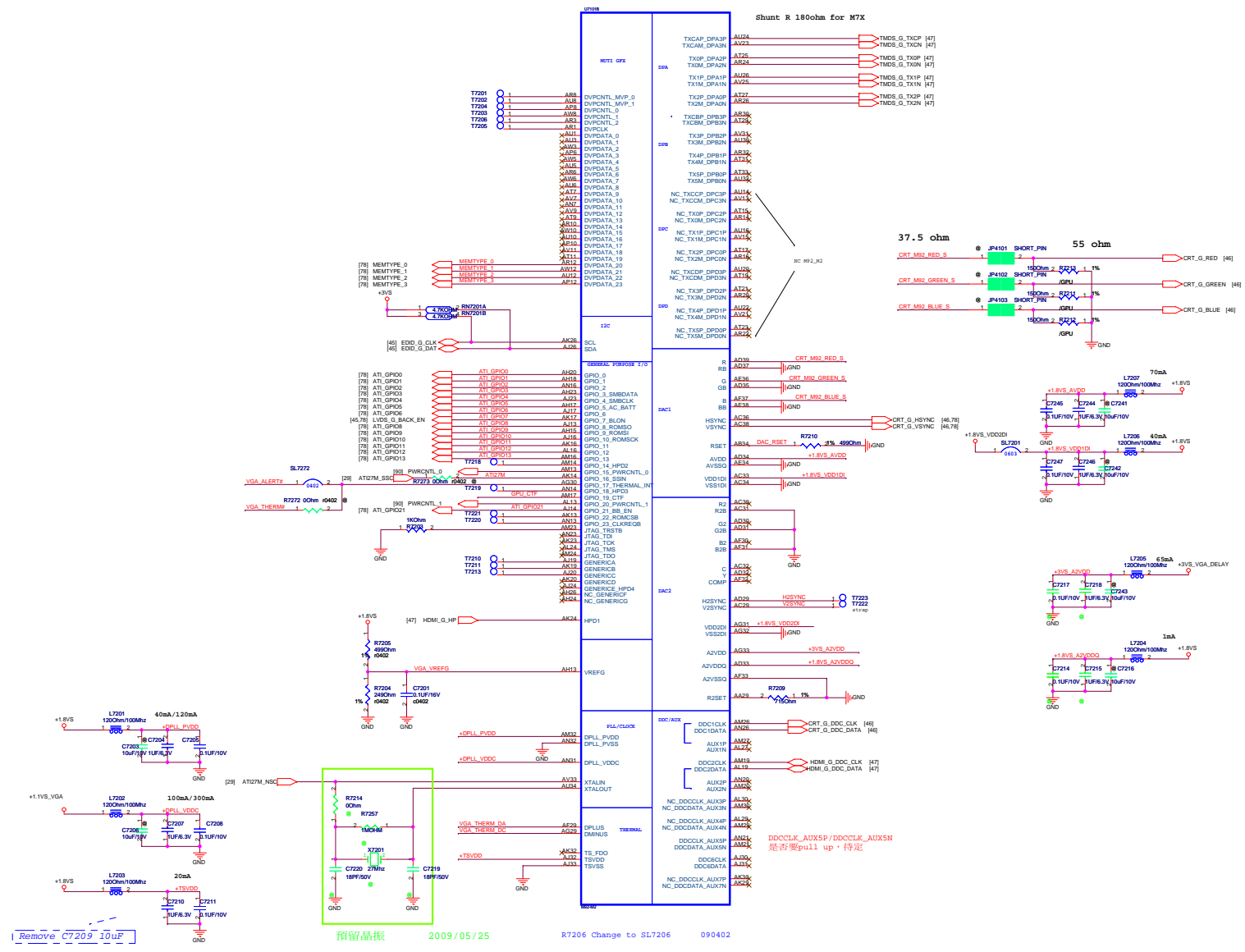


Y5V TO X7R(M92)



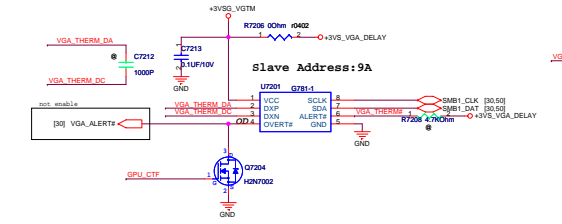
<Variant Name>

**ASUS** Title : M92-M2-PCIE (1)  
ASUSTeK COMPUTER INC Engineer:  
Size Project Name Rev  
Custom F5Z 2.05  
Date: Tuesday, May 26, 2009 Sheet 71 of 91



Remove C7209 10uF

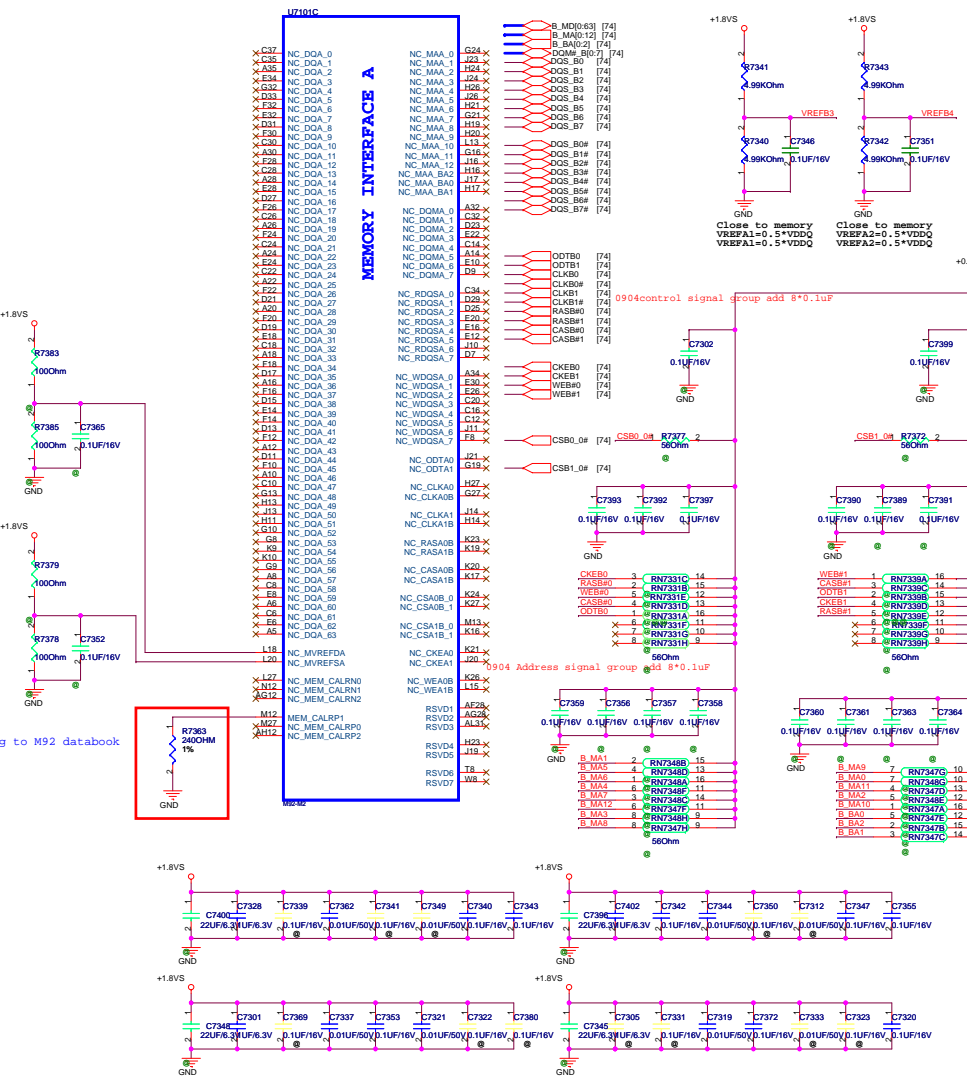
預留晶振 2009/05/25 R7206 Change to SL7206 090402



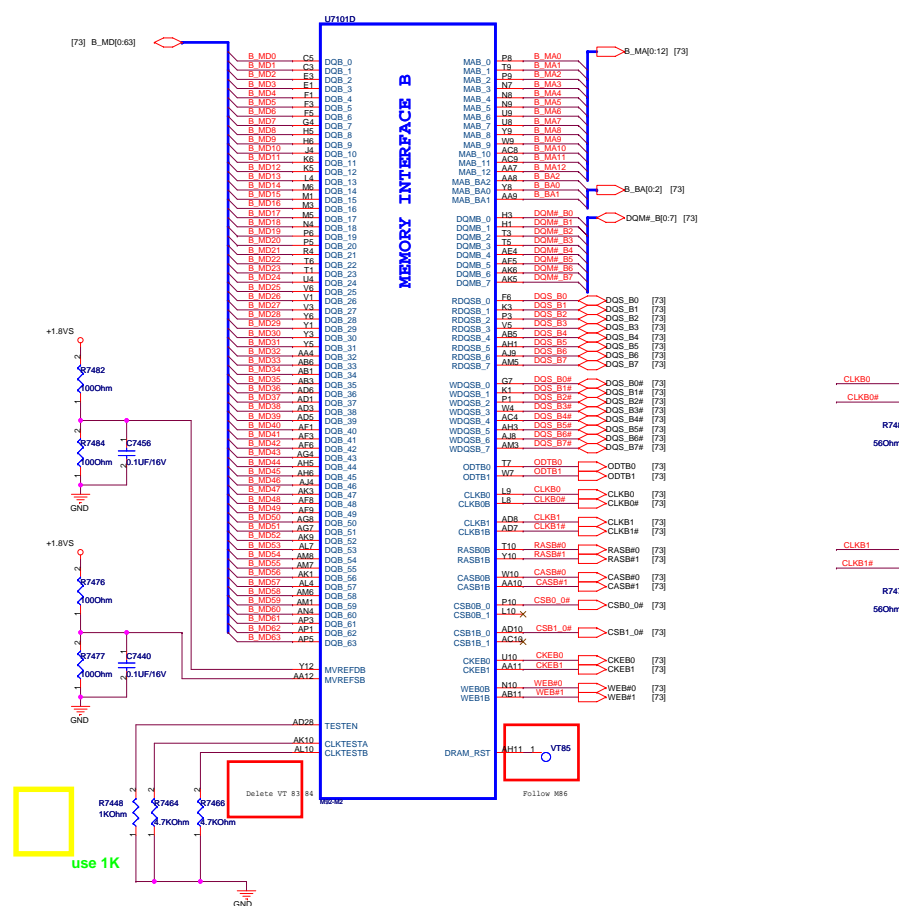
mount R7207 2005/05/25



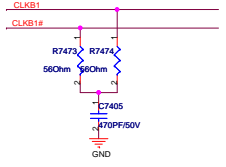
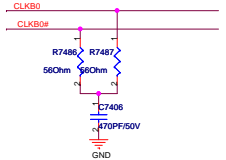
MEMORY INTERFACE A

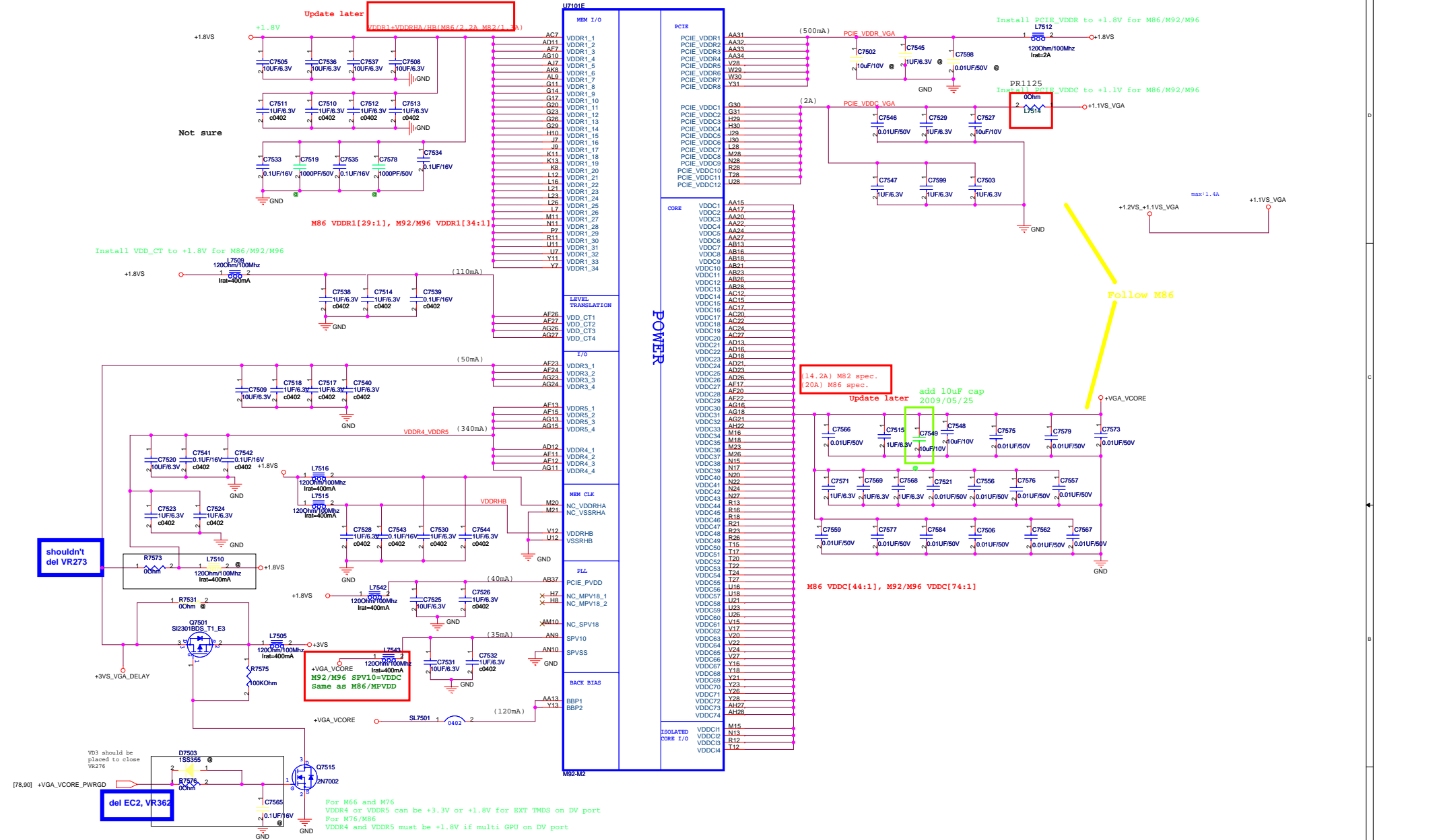


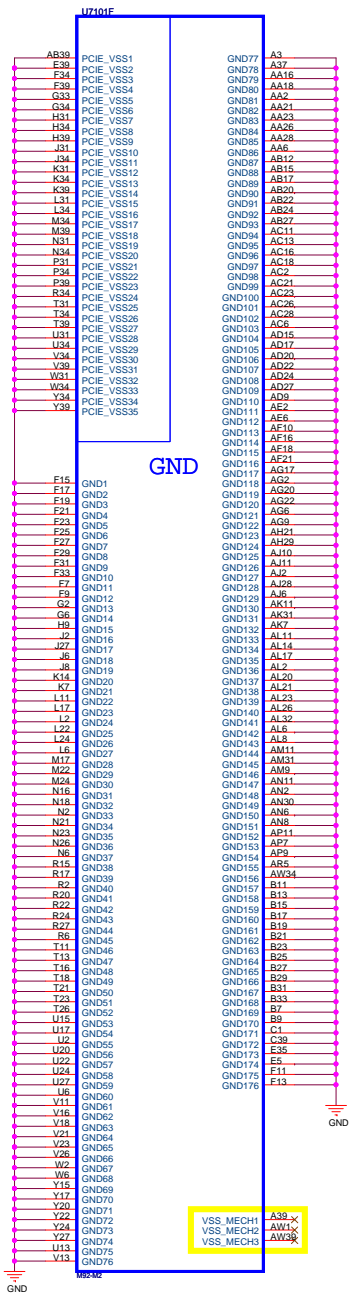
according to M92 databook

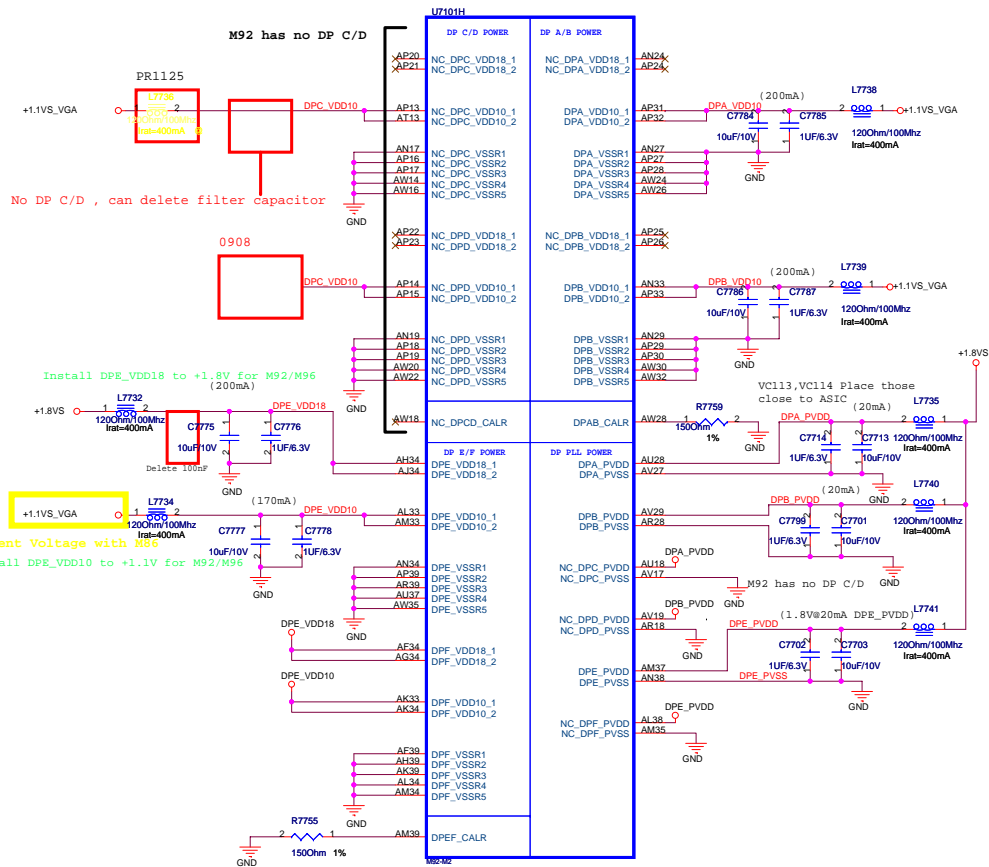
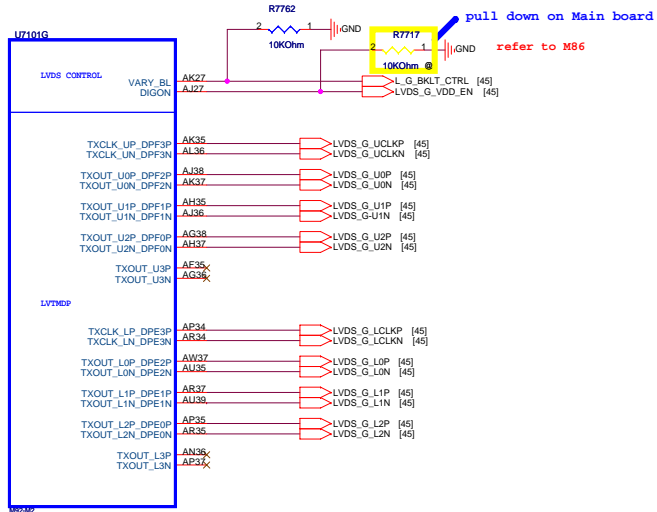


Del 4 Vram  
090323









pull down on Main board refer to M86

M92 has no DP C/D

No DP C/D, can delete filter capacitor

Install DPE\_VDD18 to +1.8V for M92/M96 (200mA)

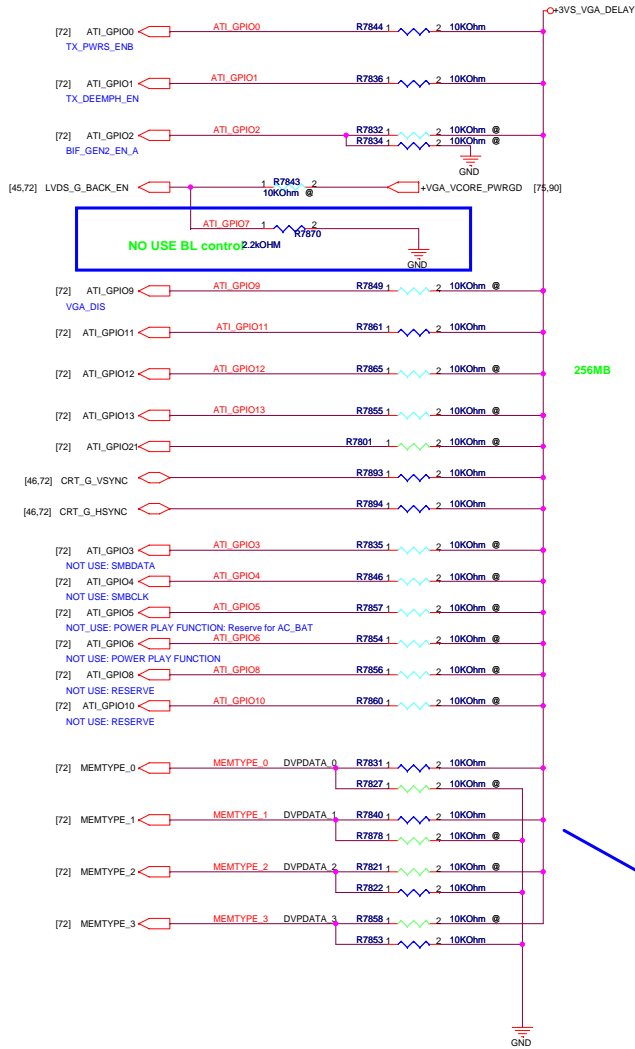
different Voltage with M86

Install DPE\_VDD10 to +1.1V for M92/M96

VC113, VC114 Place those close to ASIC

M92 has no DP C/D

### OPTION STRAPS



### M92 Straps

STRAPS	PIN	DESCRIPTION	ASIC DEFAULT
VIP_DEVICE_STRAP_EN	V2SYNC	0 - Ignore VIP device straps (DVPPDATA_20) 1 - Use VIP device straps (DVPPDATA_20)	0 (internal pull-down)
OK TX_PWR5_ENB	GPIO0	Transmitter Power Savings Enable 0: 50% Tx output swing for mobile mode 1: full Tx output swing <b>This setting can only be used if the PCIe bus design meets the "Low Loss Interconnect" requirements.</b>	0 (internal pull-down)
OK TX_DEEMPH_EN	GPIO1	Transmitter De-emphasis Enable 0: Tx de-emphasis disabled for mobile mode 1: Tx de-emphasis enabled <b>MXM and add-in boards</b>	0 (internal pull-down)
OK BIF_GEN2_EN_A	GPIO2	1 = Advertises the PCI-E device as 5.0 GT/s capable at power-on 0 = Advertises the PCI-E device as 2.5 GT/s capable at power-on	0
OK VGA_DIS	GPIO9	0 - VGA Controller capacity enabled 1 - The device will not be recognized as the system's VGA controller	0 (internal pull-down)
OK ROMIDCFG(2:0)	GPIO(13:11)	If BIOS_ROM_EN=1, then Config(2:0) defines the ROM type. If BIOS_ROM_EN=0, then Config(2:0) defines the primary memoru aperture size. 128MB---x000 32MB---Not Support 2GB---Not Support <b>256MB---x001 512MB---Not Support 4GB---Not Support</b> <b>64MB---x010 1GB---Not Support</b>	0000 (internal pull-down)
OK BIOS_ROM_EN	GPIO22_ROMCSB	Enable external BIOS ROM device 0-Disable external BIOS ROM device 1-Enable external BIOS ROM device	0 (internal pull-down)
OK AUD[1] AUD[0]	PEG_CRT_HSYNC_VGA PEG_CRT_VSYNC_VGA	AUD[1:0]: 00: No audio function; 01: Audio for DisplayPort and HDMI if adapter is detected; 10: Audio for DisplayPort only; <b>11: Audio for both DisplayPort and HDM</b>	0 (internal pull-down)
Reserved	H2SYNC GPIO_21_BB_EN GENERICC	ATI internal use only . THIS PAD HAS AN INTERNAL PULL-DOWN AND MUST BE 0 V AT RESET.	0 (internal pull-down)
AUDIO_EN	VIP_3	Enable HD Audio function in the PCI configuration space 0 - Disable HD Audio 1 - Enable HD Audio	0 (internal pull-down)
64BAR_EN_A	VIP_5	Enable 64-bit BARs Most commonly this strap is left at the default (32-bit BARs)	0 (internal pull-down)
MSI_DIS	VIP_1	Disable Message Signaled Interrupt is both a ROM strap and a pin strap. The pin strap is only applicable if a BIOS ROM is not present	0 (internal pull-down)
VIP_DEVICE	VHAD_0	VIP_DEVICE_STRAP_EN is set 0 =>not used VIP Host interface VIP_DEVICE_STRAP_EN is set 1 =>used VIP Host interface	0 (internal pull-down)
DEBUG ACCESS	GPIO4	Debug_access strap 3.3V ---ON 0V---OFF	0 (internal pull-down)
DEBUG_I2C_ENABLE	GPIO6	ATI internal use only . Other logic must not affect this signal during RESET Recommended to 0	0 (internal pull-down)

0010-DDR2 Qimonda(64MX16) 512MB  
Mount: VR27, VR40, VR22, VR353  
Unmount: VR31, VR41, VR21, VR352

0011-DDR2 Qimonda(64MX16) 1G  
Mount: VR31, VR40, VR22, VR353  
Unmount: VR27, VR41, VR21, VR352

0100-DDR2 Samsung(64MX16) 512MB  
Mount: VR27, VR41, VR21, VR353  
Unmount: VR31, VR40, VR22, VR352

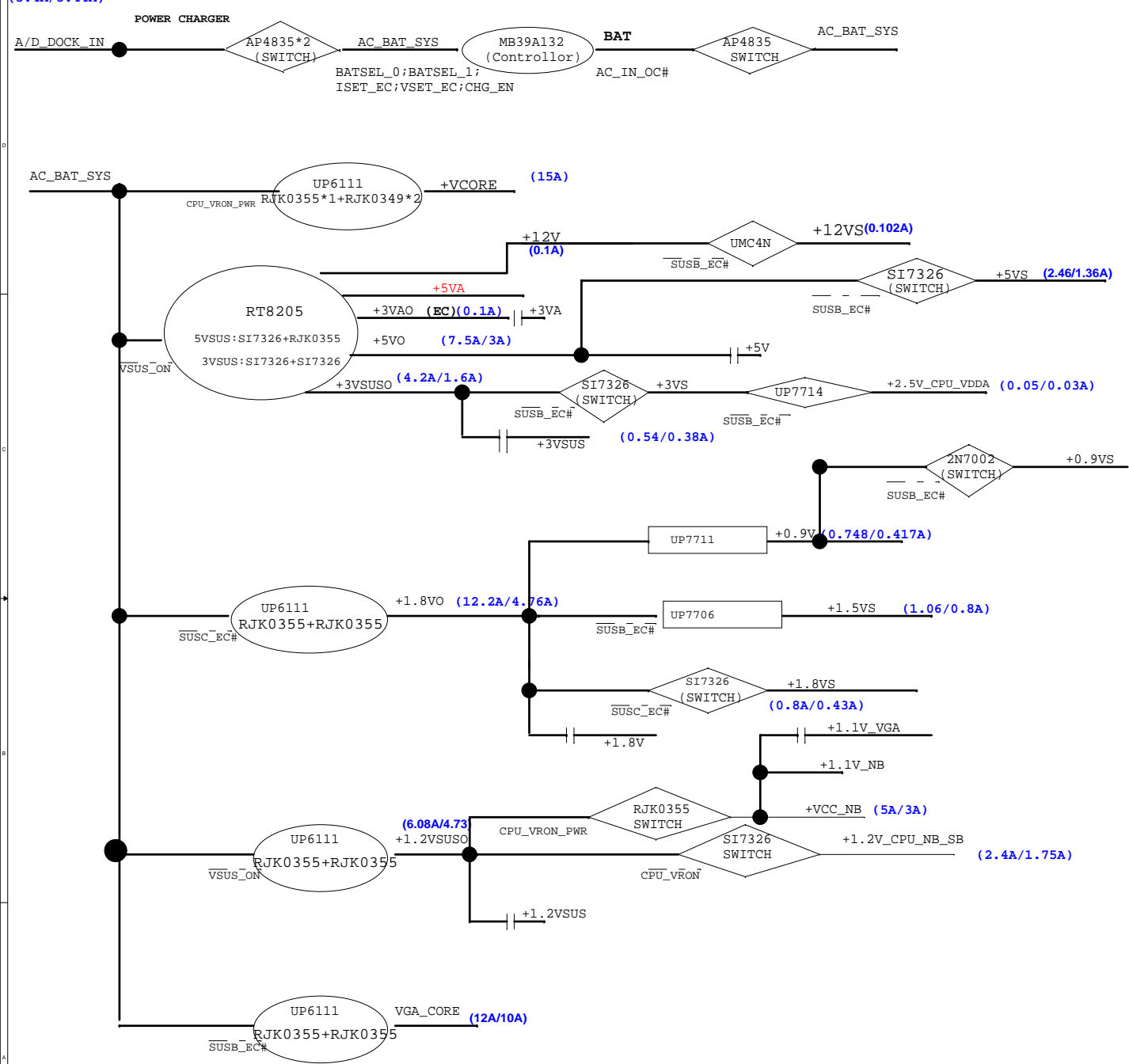
0101-DDR2 Samsung(64MX16) 1G  
Mount: VR31, VR41, VR21, VR353  
Unmount: VR27, VR40, VR22, VR352

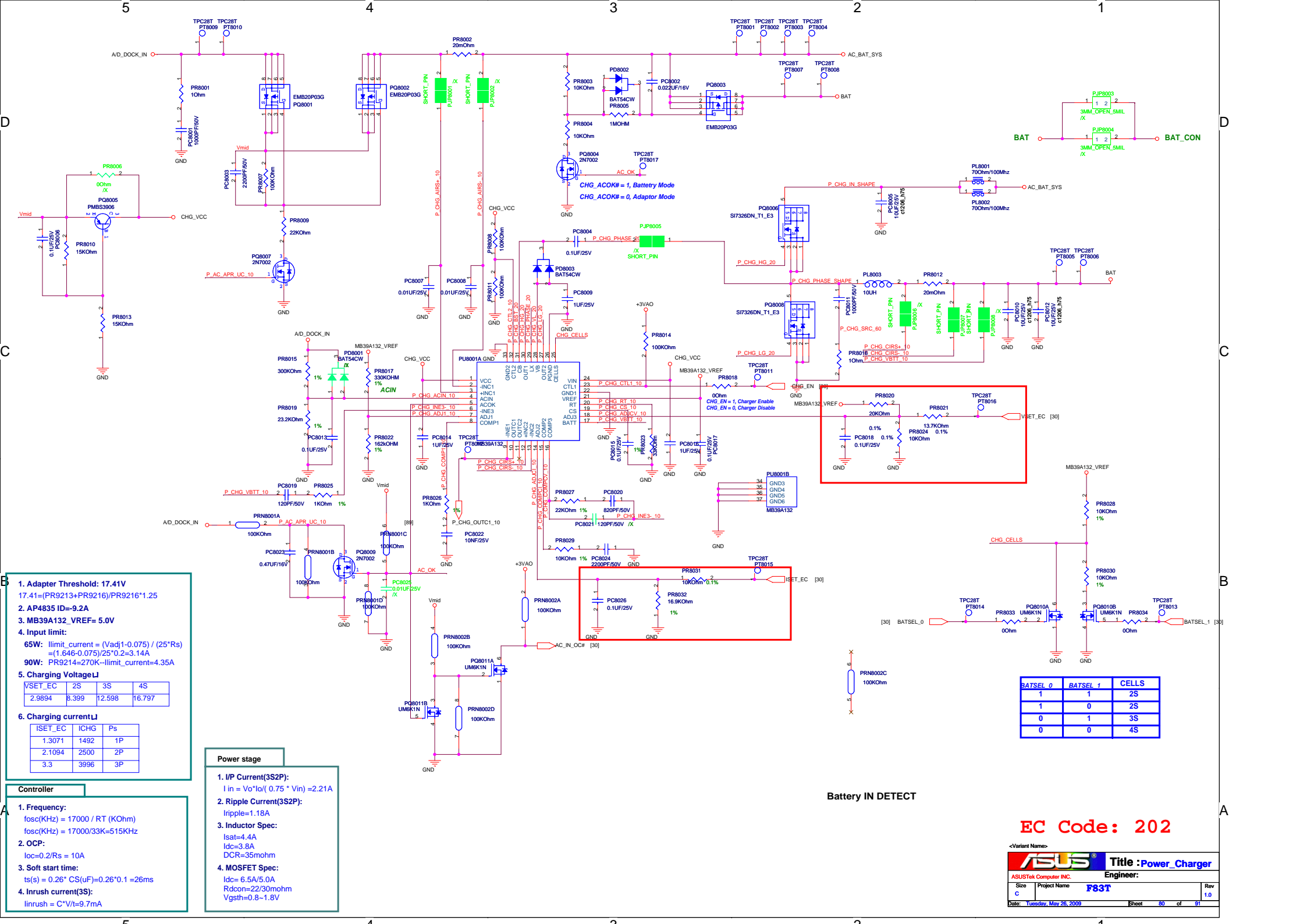
### Memory ID Board Straps

Vendor	DVPPDATA(23,22,21,20)	ID	DDR2 Memory Type	Channel Size
Qimonda	0000	0	32M*16 (256M)	B channel
	0001	1	32M*16 (512M)	B channel dual-link
	0010	2	64M*16 (512M)	B channel
Samsung	0011 M92-M2	3	64M*16 (1G)	B channel dual-link
	0100	4	64M*16 (512MB)	B channel
	0101 M92-M2	5	64M*16 (1G)	B channel dual-link
	0110	6	32M*16 (256MB)	B channel
	0111	7	32M*16 (512MB)	B channel dual-link
Hynix	1000	8	32M*16 (256M)	B channel
	1001	9	32M*16 (512M)	B channel dual-link
	1010	10	64M*16 (512M)	B channel
	1011 M92-M2	11	64M*16 (1G)	B channel dual-link
	1100	12	TBD	
Micron	1101	13		
	1110	14		
	1111	15	64M*16 (1G)	B channel dual-link

M92-M2 only support B channel

<Variant Name>





- Adapter Threshold: 17.41V**  
 $17.41 = (PR9213 + PR9216) / PR9216 * 1.25$
- AP4835 ID=9.2A**
- MB39A132\_VREF= 5.0V**
- Input limit:**  
**65W:**  $I_{limit\_current} = (V_{adj} - 1 - 0.075) / (25 * R_s) = (1.646 - 0.075) / 25 * 0.2 = 3.14A$   
**90W:**  $PR9214 = 270K - I_{limit\_current} = 4.35A$
- Charging VoltageLI**

VSET_EC	2S	3S	4S
2.9894	3.399	12.598	16.797

- Charging currentLI**

ISET_EC	ICHG	Ps
1.3071	1492	1P
2.1094	2500	2P
3.3	3996	3P

- Controller**
- Frequency:**  
 $f_{osc}(KHz) = 17000 / RT (KOhm)$   
 $f_{osc}(KHz) = 17000 / 33K = 515KHz$
  - OCP:**  
 $I_{oc} = 0.2 / R_s = 10A$
  - Soft start time:**  
 $t_s(s) = 0.26 * CS(uF) = 0.26 * 0.1 = 26ms$
  - Inrush current(3S):**  
 $I_{inrush} = C * V / t = 9.7mA$

- Power stage**
- 1. I/P Current(3S2P):**  
 $I_{in} = V_o * I_o / (0.75 * V_{in}) = 2.21A$
  - 2. Ripple Current(3S2P):**  
 $I_{ripple} = 1.18A$
  - 3. Inductor Spec:**  
 $I_{sat} = 4.4A$   
 $I_{dc} = 3.8A$   
 $DCR = 35mohm$
  - 4. MOSFET Spec:**  
 $I_{dc} = 6.5A / 5.0A$   
 $R_{dcon} = 22 / 30mohm$   
 $V_{gsth} = 0.8 - 1.8V$

Battery IN DETECT

EC Code: 202

<Variant Names>

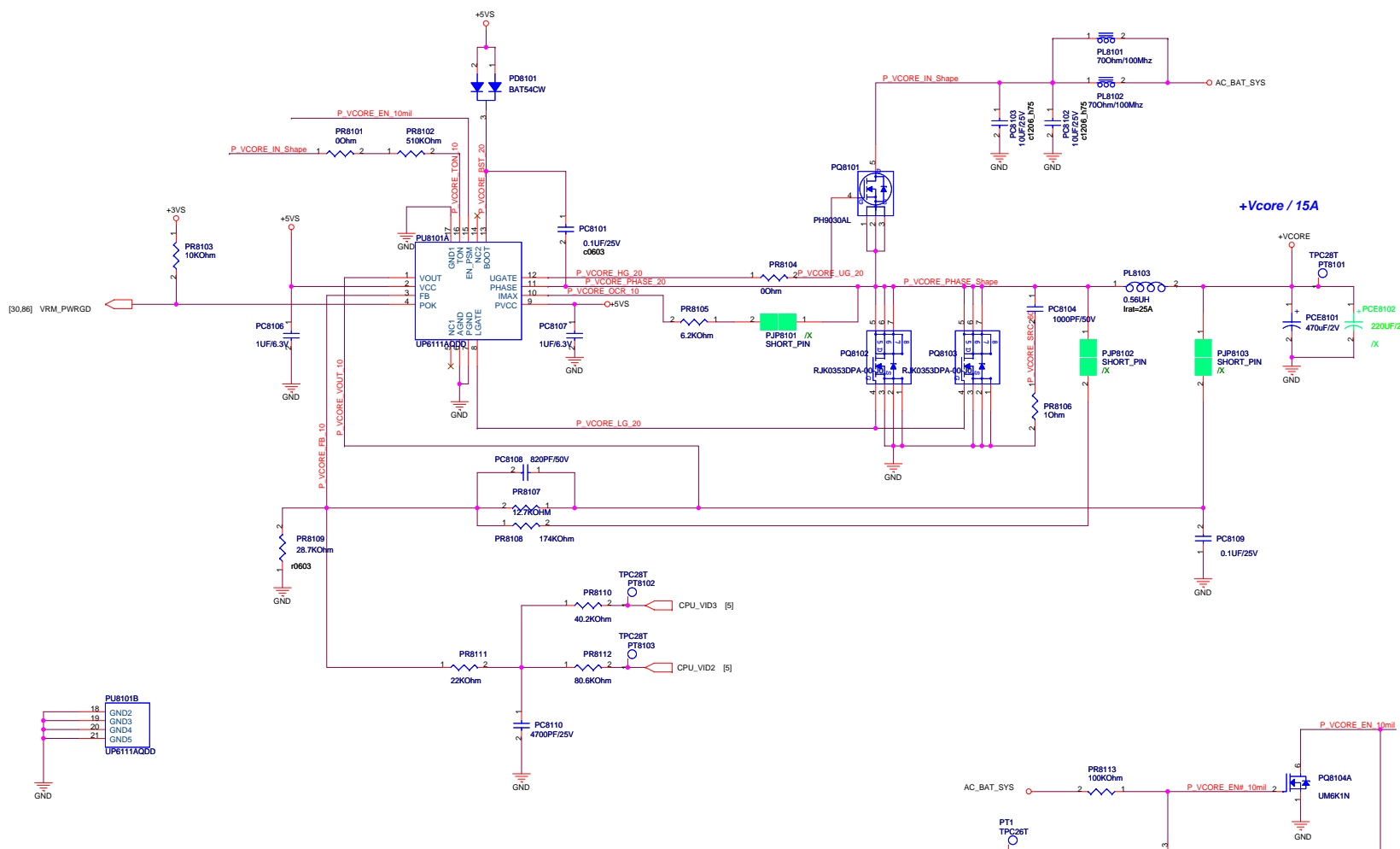
**ASUS** Title : Power\_Charger

ASUSTek Computer INC. Engineer:

Size Project Name **F83T** Rev

C Date: Tuesday, May 26, 2009 Sheet 80 of 91 1.0





[30.86] VRM\_PWRGD

[30.83.86] CPU\_VRON

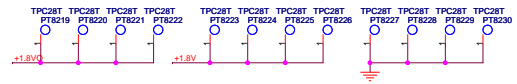
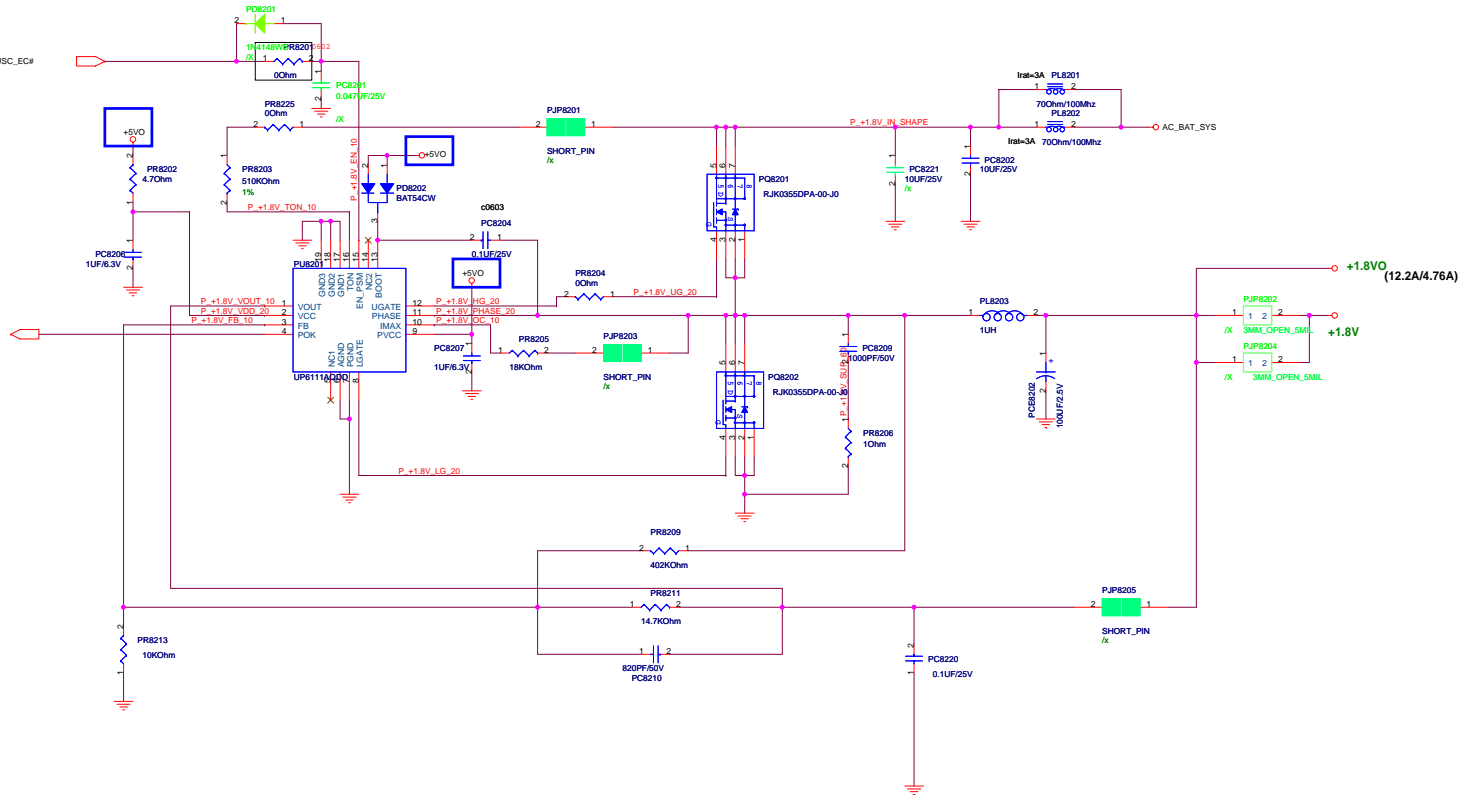
VID3	VID2	Voltage	Status
0	0	1.15V	1.24V
0	1	1.1V	1.096V
1	0	0.95V	0.95V
1	1	0.8V	0.805V

- Controller**
- Voltage & Current:**  
VCORE: 15A
  - Frequency:**  
 $T_{on} = 3.85p \cdot R_{t(on)} / V_{in} - 0.5 = 0.3us$   
Frequency =  $V_{out} / (V_{in} \cdot T_{on}) = 500KHZ$
  - OCP:**  
Set PR8105 = 12K  
 $I_{ocp} = R_{ocp} \cdot 20 / R_{ds(on)} = 12 \cdot 20 / 7.6 = 31.6A$
  - Soft start time:**  
Soft-Star duration is 1.35ms
  - Inrush Current:**  
C total = 470UF  
I inrush = 0.38A

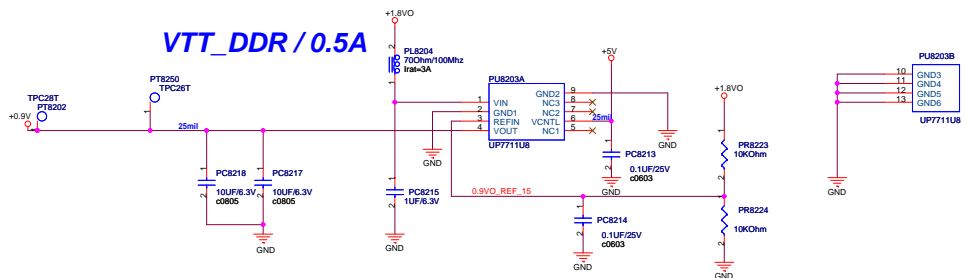
- Power stage**
- I/P Current:**  
 $I_{in} = V_o \cdot I_o / (0.75 \cdot V_{in}) = 1.16A$
  - Ripple Current:**  
ripple = 3.5A
  - Dynamic:**  
I<sub>peak</sub> = 15A  
ESR = 9mohm  
V = 122mV
  - Inductor Spec:**  
I<sub>sat</sub> = 40A  
I<sub>dc</sub> = 25A  
DCR = 1.6mohm
  - MOSFET Spec:**  
L-side MOSFET:  
R<sub>ds(on)</sub> max = 7.6mOhm (V<sub>gs</sub> = 4.5V)  
I<sub>cont</sub> = 35A (T = 25)  
I<sub>peak</sub> = 140A (Pause < 10us)

[30.57,86.87] SUSC\_ECM

[86] +1.8V\_PWRGD



### VTT\_DDR / 0.5A

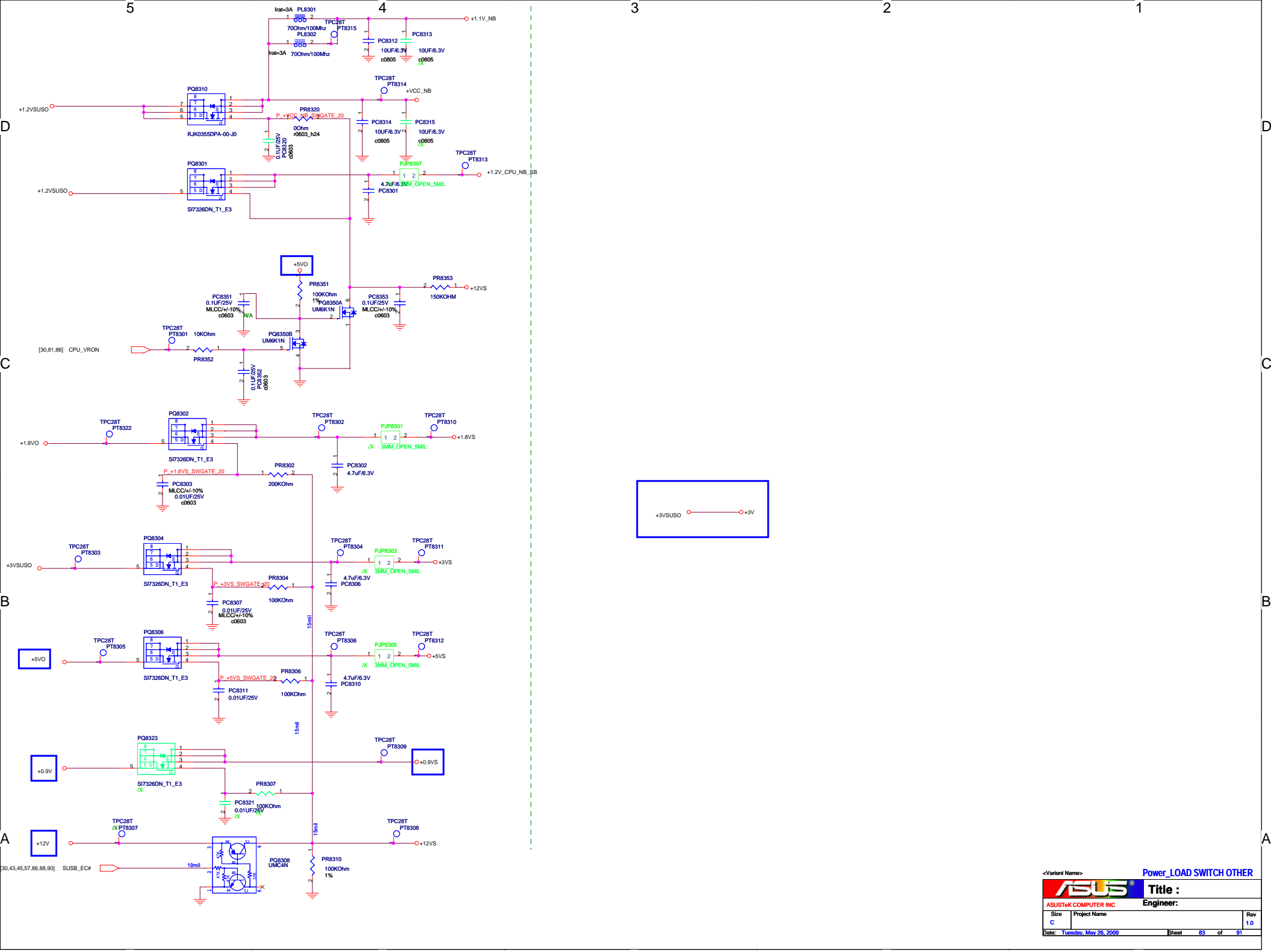


**Controller**

- 1. Voltage & Current:**  
+1.8V:+1.8V&8A
- 2. Frequency:**  
Ton=3.85p\*Rt(on)/Vin-05=0.3us  
Frequency=Vout/(Vin\*Ton)=500KHZ
- 3. OCP:**  
Set PR7343=18kohm  
Iocp=Rocp/20/Rds(on)=20\*18/16.5=21.8A
- 4. Soft start time:**  
Soft-Star duration is 1.35ms
- 5. Inrush Current:**  
C total =100uF  
I inrush=0.133A

**Power stage**

- 1. I/P Current:**  
I in = Vo\*Io/( 0.8 \* Vin )=0.947A
- 2. Ripple Current:**  
Iripple=2.342A
- 3. Ripple Voltage:**  
Ipeak=(vin-vo)\*D/(L\*Fsw)=3.25A  
ESR=18mohm  
V=58.5mV
- 4. Inductor Spec:**  
Isat=22A  
Idc=11A  
DCR=9mohm
- 5. MOSFET Spec:**  
H-side and L-side MOSFET:  
Rds(on)=16.5mOhm (Vgs=4.5V)  
Icont=30A (T=25)  
Ipeak=120A (Pause<10us)



5

4

3

2

1

D

D

C

C

B

B

A

A

<Variant Name>



Title :

ASUSTeK COMPUTER INC

Engineer:

Size	Project Name	Rev
A		1.0

Date: [Tuesday, May 26, 2009](#)

Sheet [84](#) of [91](#)

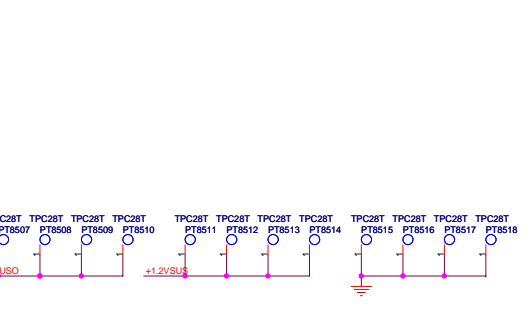
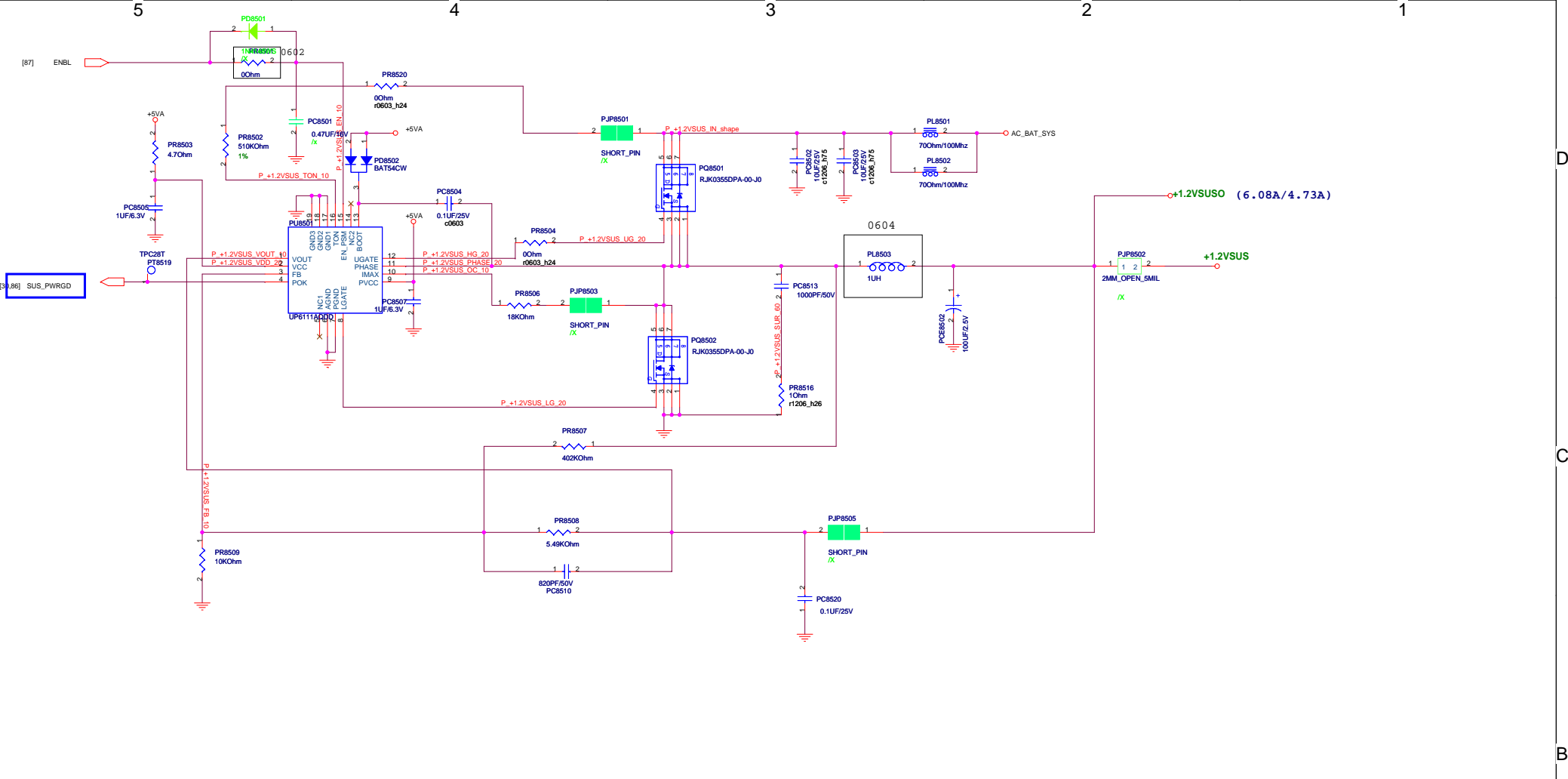
5

4

3

2

1



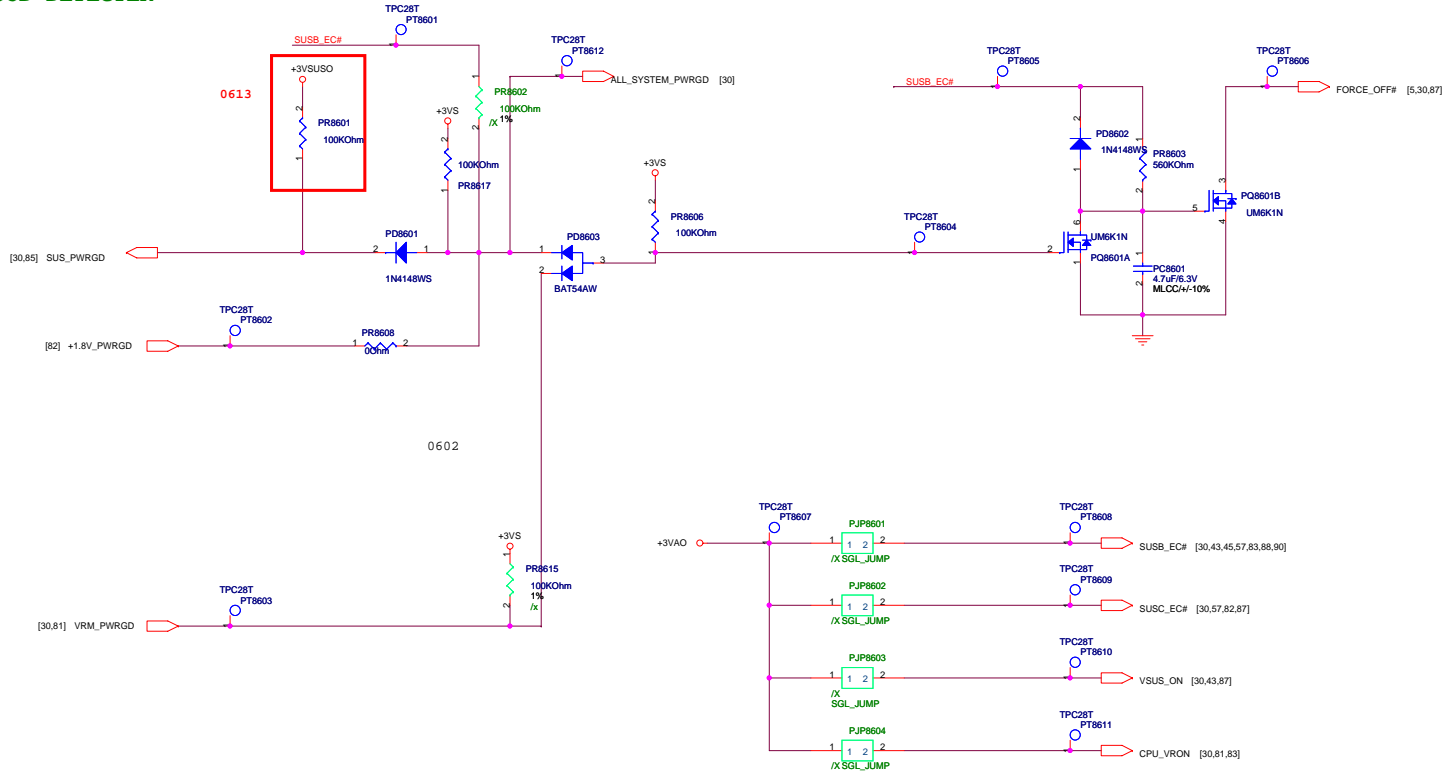
**Controller**

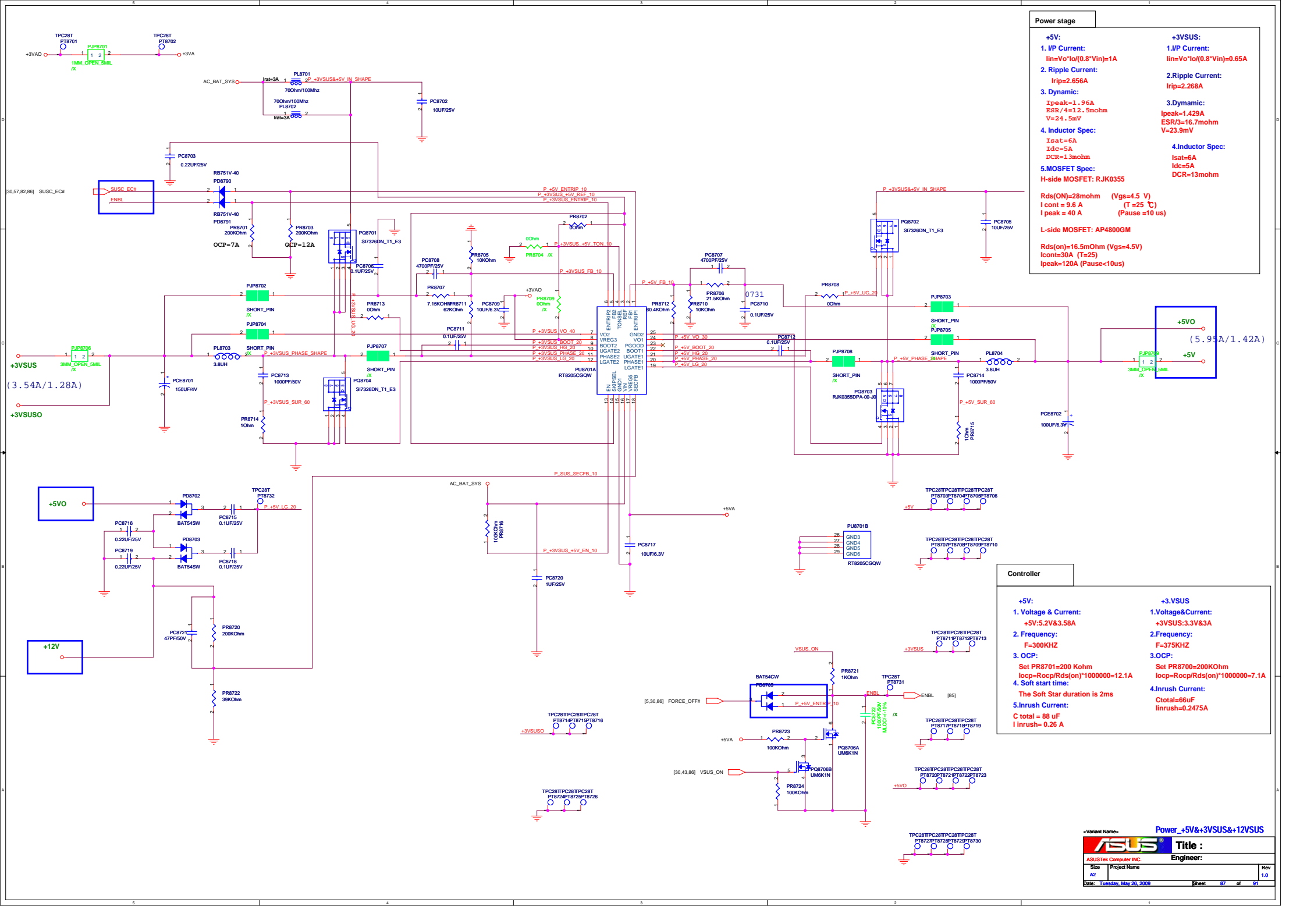
- Voltage & Current:**  
+1.2VSUS: 1.16V & 12A
- Frequency:**  
Ton = 3.85p \* Rt(on) \* Vo / Vin - 05  
Frequency = Vout / (Vin \* Ton) = 500KHZ
- OCp:**  
Set PR7343 = 18Kohm  
Iocp = Rocp \* 20 / Rds(on) = 21.9A
- Soft start time:**  
Soft-Star duration is 1.35ms
- Inrush Current:**  
C total = 100uF  
I inrush = 0.133A

**Power stage**

- IP Current:**  
I in = Vo \* Io / (0.8 \* Vin) = 0.915A
- Ripple Current:**  
I ripple = 2.915A
- Ripple Voltage:**  
I peak = (Vin - Vo) \* D / (L \* Fsw) = 2.24A  
ESR = 18mohm  
V = 40.32mV
- Inductor Spec:**  
Isat = 22A  
Idc = 11A  
DCR = 9mohm
- MOSFET Spec:**  
H-side and L-side MOSFET:  
Rds(on) = 16.5mOhm (Vgs = 4.5V)  
Icont = 30A (T = 25)  
I peak = 120A (Pause < 10us)

**POWER GOOD DETECTOR**





**Power stage**

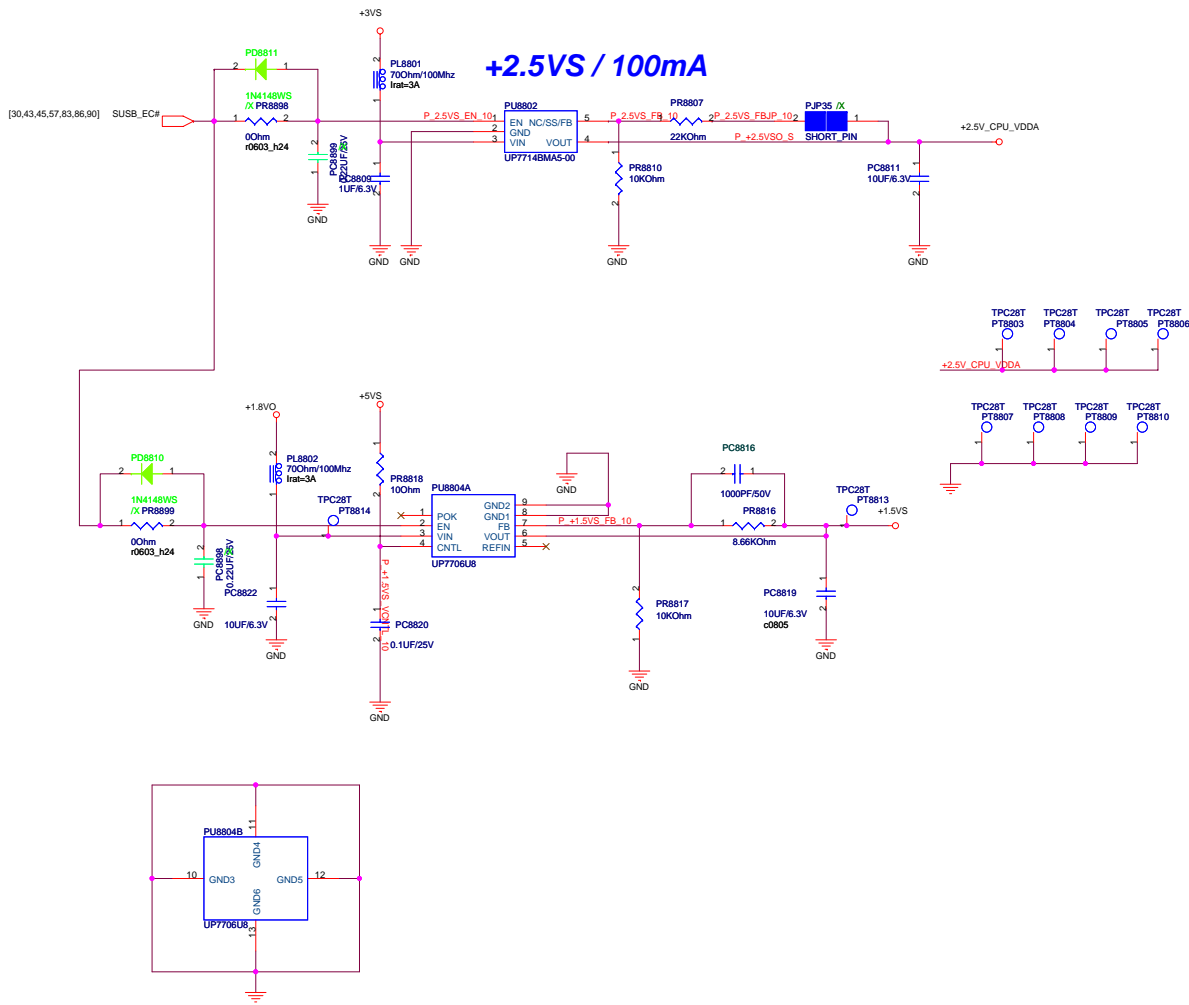
<b>+5V:</b>	<b>+3VSUS:</b>
1. I/P Current: $I_{in} = V_o / I_o (0.8 \cdot V_{in}) = 1A$	1. I/P Current: $I_{in} = V_o / I_o (0.8 \cdot V_{in}) = 0.65A$
2. Ripple Current: $I_{rip} = 2.656A$	2. Ripple Current: $I_{rip} = 2.268A$
3. Dynamic: $I_{peak} = 1.96A$ $ESR / 4 = 1.2 \cdot 5m\Omega$ $V = 24 \cdot 5mV$	3. Dynamic: $I_{peak} = 1.429A$ $ESR / 3 = 16.7m\Omega$ $V = 23.9mV$
4. Inductor Spec: $I_{sat} = 6A$ $I_{dc} = 5A$ $DCR = 13m\Omega$	4. Inductor Spec: $I_{sat} = 6A$ $I_{dc} = 5A$ $DCR = 13m\Omega$
5. MOSFET Spec: H-side MOSFET: RJK0355	

Rds(ON)=28mohm (Vgs=4.5 V)  
I cont = 9.6 A (T=25 °C)  
I peak = 40 A (Pause=10 us)

L-side MOSFET: AP4800GM  
Rds(on)=16.5mOhm (Vgs=4.5V)  
Icont=30A (T=25)  
Ipeak=120A (Pause<10us)

**Controller**

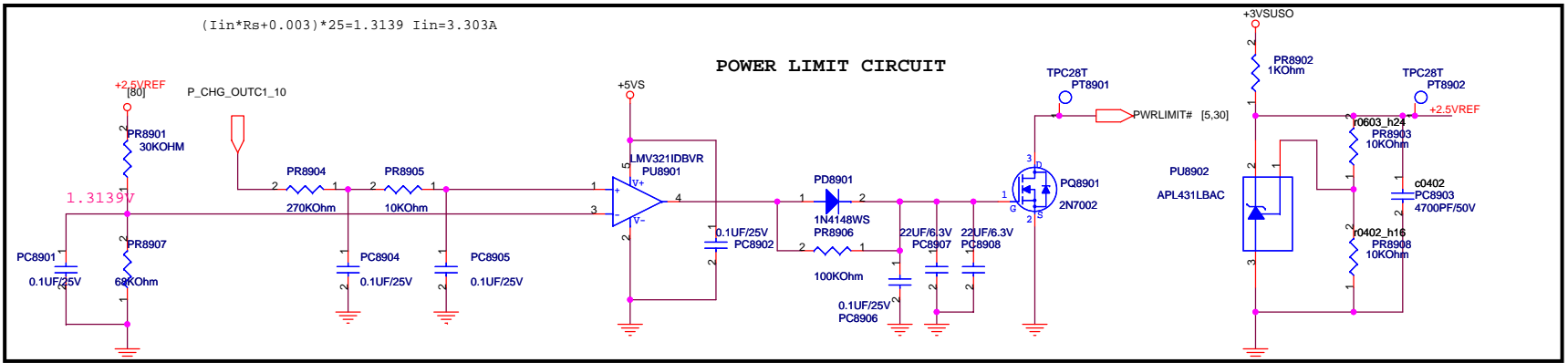
<b>+5V:</b>	<b>+3VSUS</b>
1. Voltage & Current: <b>+5V: 5.2V &amp; 3.58A</b>	1. Voltage & Current: <b>+3VSUS: 3.3V &amp; 3A</b>
2. Frequency: <b>F=300KHZ</b>	2. Frequency: <b>F=375KHZ</b>
3. OCP: Set PR8701=200 Kohm $I_{ocp} = R_{ocp} / R_{ds(on)} = 12.1A$	3. OCP: Set PR8700=200Kohm $I_{ocp} = R_{ocp} / R_{ds(on)} = 7.1A$
4. Soft start time: The Soft Star duration is 2ms	4. Inrush Current: Ctotal=66uF Iinrush=0.2475A
5. Inrush Current: C total = 88 uF I inrush= 0.26 A	

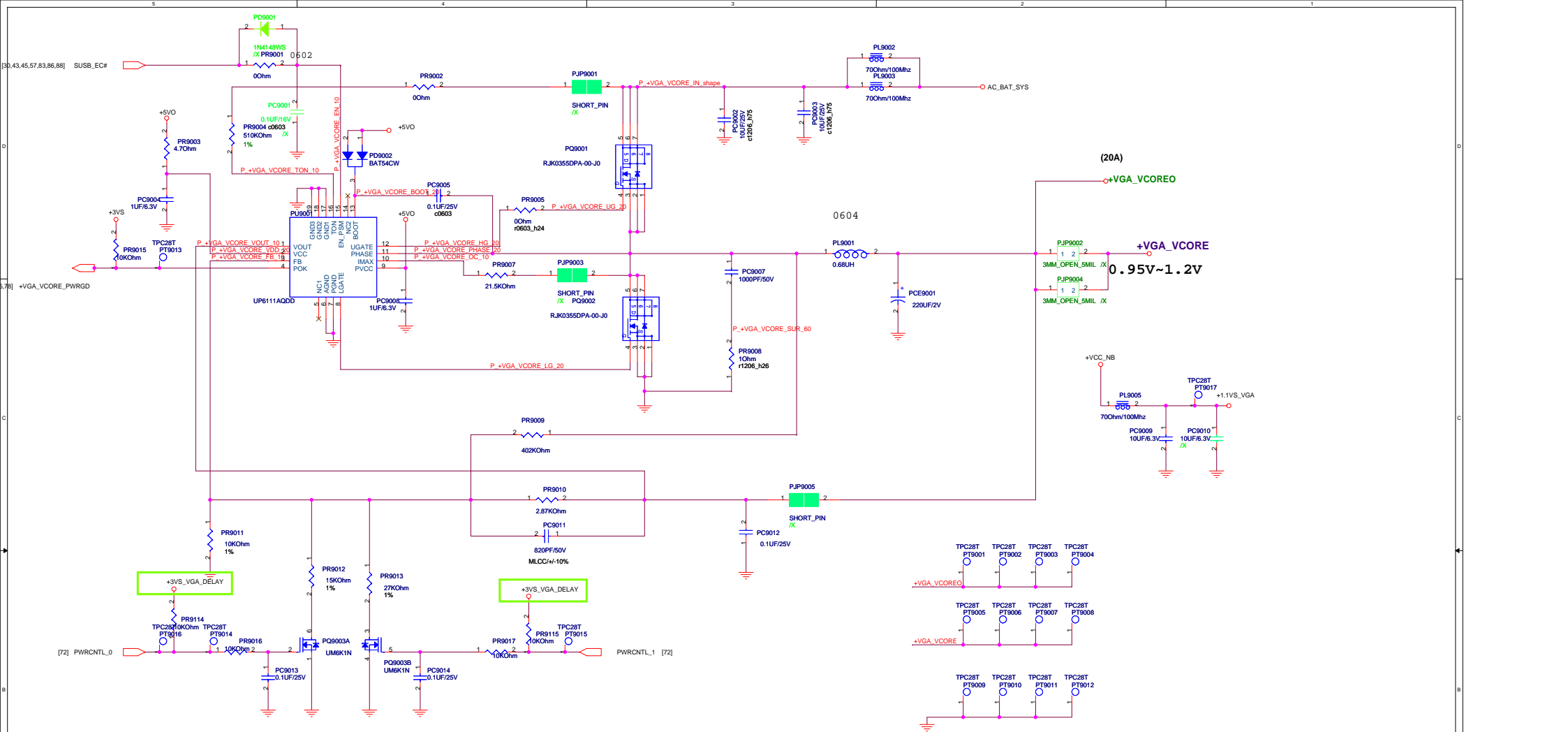


**2.5V @ 0.1A**

1. Dropout Voltage:  
 $\Delta V = 0.21V$  ( $I_o = 0.3A$ )
2. Current Limit:  
 $I_{limit} = 320mA$
3. Continue Current:  
 $I_{cont} = 300mA$
4. Power Dissipation:  
 $R_{thjc} = 250^\circ C/W$   
 $P_d = 0.4W$
5. EN Voltage:  
 $V_{EN rising} = 2V$   
 $V_{EN falling} = 0.8V$
6. Supply Voltage:  
 $V_{cc} = 3V$
7. Inrush current:  
 $T_{ss} = 400\mu s$   
 $C_{total} = 10\mu F$   
 $I_{inrush} = 0.063A$







PWRCNTL_0	PWRCNTL_1	VGA_VCORE	
0	0	0.964	-5%
0	1	1.043	Normal
1	0	1.106	+5%
1	1	1.185	+10%

**Controller**

1. Voltage & Current:  
+1.2VSUS: 16A

2. Frequency:  
Ton=3.85p\*Rt(on)/Vin-05=0.3us  
Frequency=Vout/(Vin\*Ton)=500KHZ

3. OCP:  
Isat=25A  
Set PR8506=21.5kohm  
Iocp=Rocp\*20/Rds(on)=26A

4. Soft start time:  
Soft-Star duration is 1.35ms

5. Inrush Current:  
C total =220uF  
Inrush=0.163A

**Power stage**

1. I/P Current:  
I in = Vo\*Io/(0.75 \* Vin) =0.85A

2. Ripple Current:  
Ripple=3.74A

3. Dynamic:  
Ipeak=6.1A  
ESR/2=4.5mohm  
V=27.5mohm

4. Inductor Spec:  
Isat=25A  
Idc=15.5A  
DCR=5.5mohm

5. MOSFET Spec:  
H-side and L-side MOSFET:  
Rds(on)=16.5mOhm (Vgs=4.5V)  
Icont=30A (T=25)  
Ipeak=120A (Pause<10us)


Date:05/19/09

1.Del PQ8012&PR8035&PC8027 in 80\_Powe\_charge

Date:05/21/09

1.Chagne VCORE H-S MOS PQ8101 to PH9030AL

<Variant Name>

		Title: Power_History	
ASUSTeK COMPUTER INC		Engineer:	
Size	Project Name	Rev	
A		1.0	
Date: Tuesday, May 26, 2009		Sheet	91 of 91